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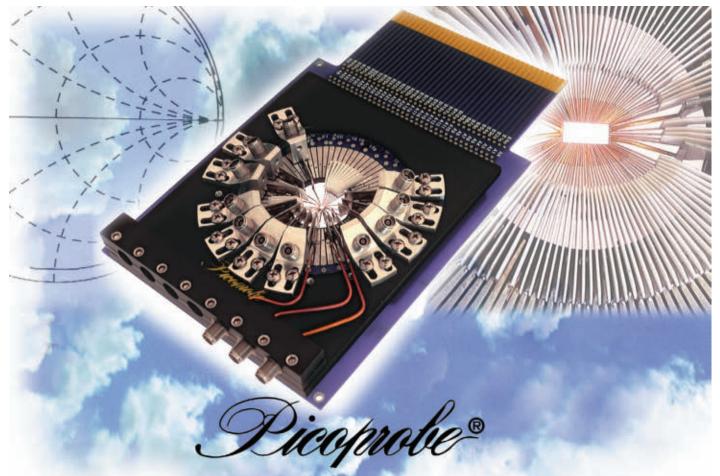
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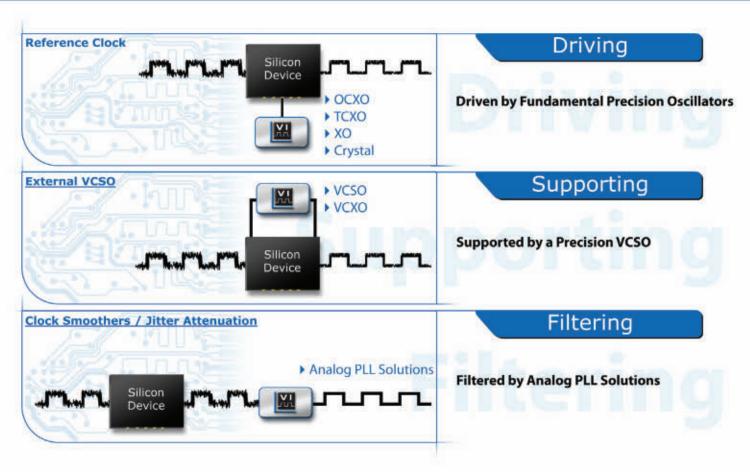


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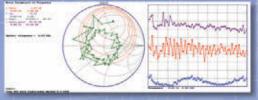
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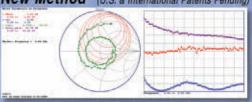
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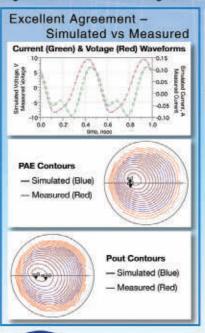
Maury ATSv5.1 Software runs

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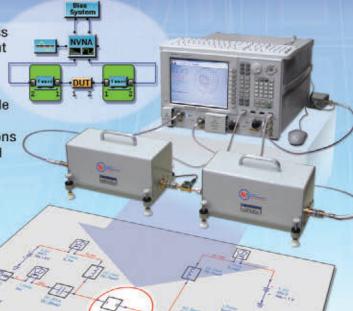
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Presentation of a design methodology for source degenerated cascode dual functionality low noise amplifier and power amplifier for the ZigBee standard (continued online)



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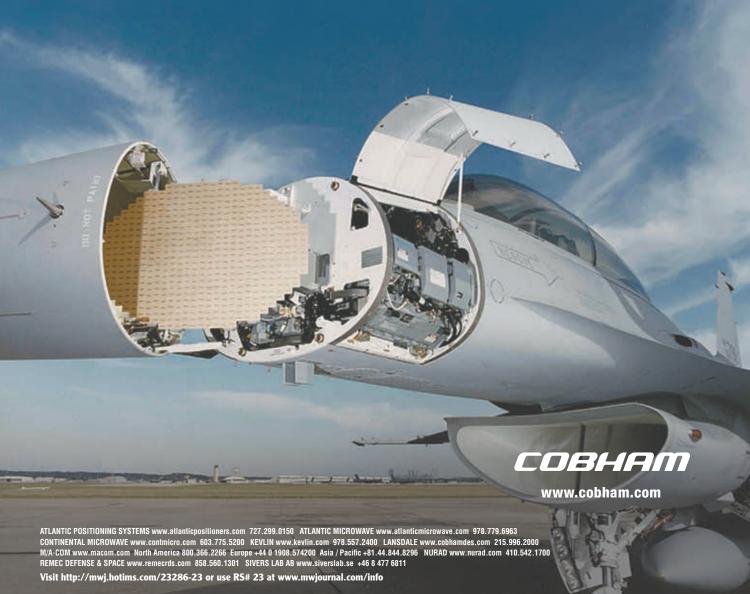






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#### PRODUCT FEATURES

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Introduction to a network analyzer and an extension unit combined to form a solution adaptable to user requirements

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HUBER+SUHNER AG

Development of a rugged omni-directional multiband antenna for GSM 900/1800/1900, UMTS, 2.4 GHz band and GPS/Galileo

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I have just finished reading the RFID article on page 58 of the March issue. I would like to correct the author's description of the Cardullo/Parks device covered by US Patent # 3,713,148. I am the co-inventor and designer of the device and I am also a co-founder of the company that designed the device. The author states the device is a "passive" transponder. My understanding of passive devices is that they use "backscatter" as the retransmission technique. Our device had an RF transmitter stage. This was necessary as we needed much more range than is possible with passive backscatter devices. The device was also RF carrier powered and therefore needed no batteries. Finally, the device had a rewriteable memory. That was a lot of technology for 1970.

We thought we had a device that would revolutionize such chores as collecting tolls, keeping track of railroad cars, etc. Sadly, when we presented the device to the Port Authority of New York and New Jersey they turned us down. One of the reasons they gave was because it "violated driver's rights" to photograph them for failing to pay the toll and therefore they were not interested. The Southern Rail Road had a barcode scanner and they were not interested. San Francisco's BART also turned us down. And so it went. It's hell being first and a small business.

Yours,

William Parks

PS: I enjoyed the article.

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Thilo Bednorz, Product Management & Applications Engineering, Spectrum and Network Analysis, Rohde & Schwarz

#### **EM Analysis within the Design Flow** Dr. Mike Heimlich, AWR

**A-GPS Over the Air Test Method: Business and Technology Implications** 

Spirent Communications

#### **Correcting Imperfections in IQ Modulators Improves RF Signal Fidelity**

Eamon Nash, Analog Devices

#### More on the New Power Brokers

Read the full responses to our questionnaire on the state of LDMOS, GaN, SiC and HV-FETs from contributors RFMD, Freescale, NXP, Cree, Nitronex and HVVi. Go to www.mwjournal.com/ powerbrokers.

## Executive Interview

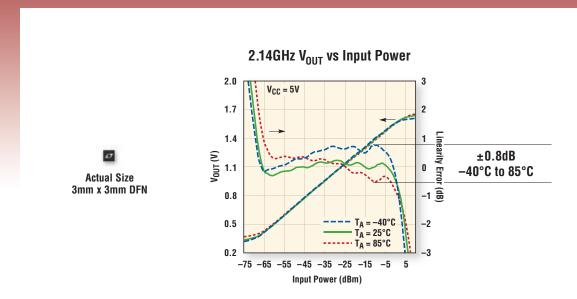
Dr. Bernd Niedermann, Head of Corporate Communications at **HUBER+SUHNER**, explains the company's evolution since its formation following the merger of two independent companies 40 years ago, its commitment to providing connectivity solutions and its strategies for developing new technologies.



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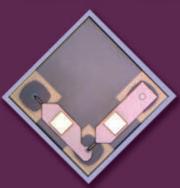
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26  JK Microwave Group	27	28	Birthday Henry Albert Howard "Harry" Boot  English physicist who developed the cavity magne- tron with Sir John Randall. Born 29 July 1917	30	31	I

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#### **EuMW 2009**

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October 6–8, 2009 • Paris, France www.rfhyper.com

#### INTERNATIONAL RADAR CONFERENCE

October 12–16, 2009 • Bordeaux, France www.radar09.org

#### **AOC 2009**

## 46<sup>TH</sup> ANNUAL AOC INTERNATIONAL SYMPOSIUM AND CONVENTION

October 18–22, 2009 • Washington, DC www.crows.org

#### **ISAP 2009**

## International Symposium on Antennas and Propagation

October 20–23, 2009 • Bangkok, Thailand www.isap09.org

#### **NOVEMBER**

#### **AMTA 2009**

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November 1–6, 2009 • Salt Lake City, UT www.amta.org

#### COMCAS 2009

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November 9–11, 2009 • Tel Aviv, Israel www.comcas.org

#### **DECEMBER**

#### **APMC 2009**

#### Asia-Pacific Microwave Conference

December 7–10, 2009 • Singapore www.apmc2009.org

#### **AEMC 2009**

#### IEEE APPLIED ELECTROMAGNETICS CONFERENCE

 $\begin{array}{l} \textit{December 14-16, 2009} \bullet \textit{Kolkata, India} \\ \textit{www.ieee-aemc.org} \end{array}$ 

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#### RADIO WIRELESS WEEK 2010

January 10–14, 2010 • New Orleans, LA www.radiowirelessweek.org

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* MA4P1250-1072T	50	0.75	1.5	15
* MA4P4001F-1091T	100	0.5	2.2	5
* MA4P7101F-1072T	100	0.5	1	15
MA4P7001F-1072T	100	0.8	0.7	15.5
MA4P4301F-1091T	100	1	2	8
MA4P4002F-1091T	200	0.5	2.2	6.5
MA4P7102F-1079T	200	0.5	1	21
MA4PH237-1079T	200	0.6	1.5	25
MA4P7002F-1072T	200	0.8	0.7	15
MA4PH236-1072T	200	3	0.5	25
MA4P7104F-1072T	400	0.5	1	20
MA4P506-1072T	500	0.3	1	10
MA4P505-1072T	500	0.45	0.65	15
MA4P504-1072T	500	0.6	0.5	20
* MA4P4006F-1091T	600	0.5	2.2	6
* MA4P7006F-1072T	600	8.0	0.7	13

<sup>\*</sup> Non-magnetic equivalents available

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# THE NEW POWER BROKERS: HIGH VOLTAGE RF DEVICES

ver since Bell Lab physicists Shockley, Bardeen and Brattain invented the transistor, this little solid state device has been constantly evolving; leveraging the advantages of different semiconductor and process technologies and addressing an increasing number of applications once reserved for tubes. Sixty-plus years later—driven by a number of promising commercial and defenserelated markets—transistors (and MMICs) specifically targeting high power applications in the RF and microwave frequency range continue to be the focus of sizable research and development.

Among the changing landscape of RF/microwave semiconductor developments, devices with material properties that can sustain high electric breakdown are of particular interest. To understand the state of the high power transistor market, we spoke to a number of leading vendors. Our discussion was mostly concerned with devices that could produce in excess of 30 W at UHF/VHF frequencies and above (up to X-band). These are the high-power transistors required for avionics, radar, EW and wireless infrastructure applications. Although these devices are also found in medical equipment, those applications will not be part of our focus in this article. The following is a summary of our correspondence.

# HIGH POWER TRANSISTOR TECHNOLOGIES AND APPLICATIONS

Within the last six months alone, the *Journal* has published over a dozen papers on Laterally Diffused MOS (LDMOS), Gallium Nitride (GaN), Silicon Carbide (SiC) and High-Voltage Vertical FETs (HVVFET). The principle market segments for high-power, high-frequency transistors are wireless infrastructure (3G, 3G+, WiMAX/LTE base stations and backhaul), defense and military applications (radar, jamming, counter-measures, guided weapons, etc.) and broadcast and communication satellites (SatCom). The factors that will decide whether a technology dominates a given application include performance (linearity, efficiency), reliability (ruggedness and thermal considerations), size, cost and legacy.

DAVID VYE Microwave Journal
LEONARD PELLETIER Freescale
Semiconductor
STEVEN THEEUWEN NXP Semiconductors
DAVE AICHELE RFMD
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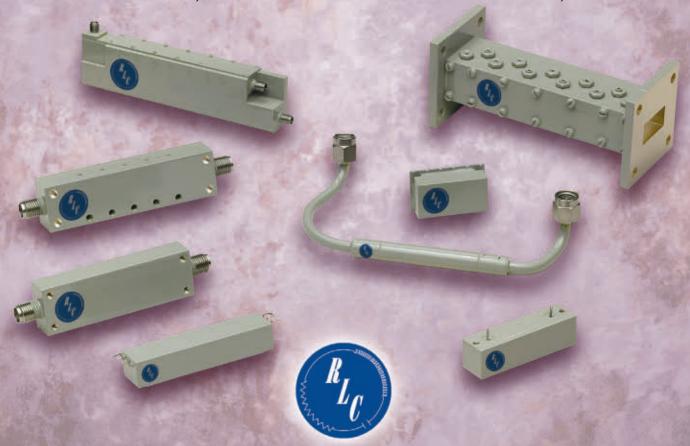
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Figure 1 maps the various highpower semiconductor technologies relative to their operating frequencies and available output power. With an understanding of the power and frequency requirements for a given application, this graph provides a rough guide to the leading technologies today. Implicit in this representation are regions where one technology overlaps another due to its cost advantage. This cost can be related to higher production costs (complexity, less mature processes or lower volume production all drive up costs) as well as replacement costs (a technology missed the critical time-to-market). As process technology advances and new standards (i.e. 4G) provide new opportunities to enter a market, technology dominance in any particular region is subject to change. These factors will be discussed later in this article.

#### RADAR AND AVIONICS

According to ABI Research, the demand for the pulsed RF power devices (greater than 5 W of peak output power and frequencies up to 3.8 GHz) is expected to show solid growth over the next five years, in part due to a worldwide upgrade of air traffic control systems including new avionics transponders and air navigation systems. In response, many semiconductor manufacturers are attempting to enter the avionics, L-band, S-band and sub-1 GHz radar markets. Competitive technologies such as GaN and SiC devices will be vying for market share along with the more established silicon-based technologies. With the entry of many would-be players, competition will be fierce. Companies that have an established track record

1 kW

LDMOS-50V

100 W

LDMOS-28V

GaN

1 W

Si BIPOLAR

RF CMOS

0.1 GHz 2 GHz 5 GHz 10 GHz

▲ Fig. 1 An overview of preferred transistor technologies for 2008 design-ins as a function of power and frequency (courtesy of NXP Semiconductors).

working with government agencies and defense contractors will naturally have an advantage over new entrants.

Long-range radar systems operating from VHF thru S-band are demanding increased performance from the RF power amplifier in order to support the required improvements in system ranging and sensitivity. A key lesson learned from the crisis on 9/11 was the need to extend the pulse width to at least 300 µs for long-range radar as well as the ability to increase the operating dynamic range of the power amplifier.<sup>2</sup>

#### **UHF/VHF RADAR**

Historically, silicon Class C amplifiers were limited by heat dissipation due to the potential for thermal runaway during long pulses (> 300 μs) and high peak powers. Military applications were among the first to use wide band gap (WBG) devices, especially with the SiC MESFETs being developed through broadly financed DARPA and DoD programs in the US.<sup>3</sup> Recently, Microsemi's Microwave RF Power Division developed its WBG SiC technology in support of the new longer pulse radar systems and avionics being developed from VHF thru S-band.

The state of material technology has progressed to the point where Microsemi can build high power devices with reasonable yields and consistent performance. In 2008, the company introduced its first two RF power transistors utilizing silicon carbide technology for high power VHF and UHF band pulsed radar applications. The two Common Gate N-Channel, Class AB, SiC Static Induction Transistors (SIT) are capable of providing

1000 W, pulsed (300 µsec pulse width, 10 percent duty cycle) from 406 to 450 MHz and 1250 W pulsed at 150 to 160 MHz.

In January, the company made good on its promise to extend SiC technology to higher frequencies by introducing a new family of power transistors and modules designed for S-band (3.1 to 3.4)

GHz) pulsed radar. The new products include a 65 and 100 W power transistor and two Power Solution Modules TM rated at 180 and 200 W (100 µsec pulse width and 10 percent duty cycle). The modules demonstrate 40 percent collector efficiency and power flatness of less than 0.5 dB, utilizing the company's advanced chip design and processing enhancements for high power and high gain.

Around the same timeframe (December 2008), HVVi Semiconductors announced its first product to target the UHF-band weather and longrange radar markets using its High Voltage Vertical Field Effect Transistor (HVVFETTM) architecture. The company's 50 V device offered 175 W pulsed, 55 percent drain efficiency, 25 dB of gain for a pulse width of 300 µsec and pulse duty cycle of 10 percent at VDD = 50 V and IDQ = 50 mA. The UHF part also provided a boost to system reliability by withstanding an output load mismatch corresponding to a 20:1 VSWR across all phase angles at rated output power and operating voltage across the entire frequency band.

#### **L-BAND RADAR**

This new device, based on the company's HVVFET, followed the earlier releases (October 2008 at European Microwave Week) of three devices with pulsed output powers of 60, 100 and 250 W operating in the 1025 to 1150 MHz frequency band. These devices targeted airborne Distance Measuring Equipment (DME) applications, a transponder-based radio navigation technology that measures distance by timing the propagation delay of radio signals. The company also targeted ground-based DME (960 to 1215 MHz) with a 50 V device that provides 150 W, 20 dB gain and 43 percent drain efficiency.

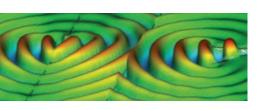
These products expanded the company's portfolio across three L-band, pulsed radar applications: 1025 to 1150 MHz, 1030 to 1090 MHz and 1.2 to 1.4 GHz. The 1030 to 1090 MHz frequency band is used for IFF, TCAS and mode-S applications. For this market, HVVi introduced a pulsed (50 µs pulse width, 5 percent duty cyle) 35 W device (20 dB gain, 52 percent drain efficiency) and 300 W device (18 dB gain, 48 percent drain efficiency).

Meanwhile, Silicon Bipolar devices



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CHANGING THE STANDARDS



continue to be introduced into the market. Companies such as ST Microelectronics, NEC, Motorola and NXP have large Si-BJT product portfolios (to name a few). Last summer, M/A-COM announced a line-up of new high-power bipolar transistors designed for pulsed avionics applications such as ATC, DME and IFF systems, ranging from 960 to 1215 MHz. The Class C, Si-BJT pulse power transistors provide peak powers of 50, 350 and 500 W with gains of approximately 9 dB and 40 to 45 percent collector efficiencies. Integra Technologies also has an extensive portfolio of Si-BJT high power transistors targeting VHF through S-band pulsed radar applications, but they are also offering LD-MOS devices as this technology continues to challenge the supremacy of the Si-BJT in the avionics and radar

At last year's IMS in Atlanta, Freescale Semiconductor introduced the world's first 50 V LDMOS device for L-band radar with a demonstration of a class AB, long-pulse (300 µsec, 12 percent duty cycle) amplifier with peak power of 330 W, 17 dB gain and 60 percent drain efficiency operating between 1200 to 1400 MHz, a band used for ground-based, long-range surveillance radar applications. Freescale pointed to advantages, such as a standard voltage supply, low cooling costs and high reliability of pallet design and expected to demonstrate gain, efficiency and thermal resistance characteristics that would outperform other similar products in the market.

A year later at IMS in Boston, HVVi introduced its 500 W (19 dB gain, 50 percent drain efficiency) device operating with a 50 usec pulse width, and 5 percent duty cycle adding to its portfolio of products with pulsed output powers of 25, 75 and 120 W (200 usec pulse width, 10 percent duty cycle). The 500 W power level was also achieved by NXP Semiconductors this past November with an LDMOS device demonstrating greater than 50 percent drain efficiency and 17 dB of gain operating at 100 µsec pulse width and a 25 percent duty cycle at 1.4 GHz.

Japanese manufacturer Eudyna hit the 500 W mark and then some with an AlGaN/GaN HEMT 1.5 GHz power amplifier reported back in 2006 at the MTT-S IMS that year and an 800

W S-band transistor with linear gain of 14.0 dB, 56.4 percent drain efficiency covering a wide frequency range of 2.9 to 3.3 GHz (operating at 65 V, pulse width of 200 µsec and 10 percent duty cycle) reported just one year later at CS MANTECH. While Eudyna holds a strong position in the market, the company is at a disadvantage to domestic suppliers when it comes to US military opportunities due to (offshore) sourcing concerns. Not surprisingly, Eudyna markets its GaN HEMTs primarily to the WiMAX and LTE infrastructure markets where the majority of GaN manufacturers also have made considerable in-roads.

#### **S-BAND RADAR**

Integra Technologies addresses the S-band radar market with a comprehensive family of Si-bipolar devices (drivers, medium and high power amplifiers) operating from 2.2 up to 3.5 GHz (in bandwidths ranging from 200 to 400 MHz). The high power amplifiers have peak output powers up to 125 W (3.1 to 3.4 GHz) at 300 μs pulse width (PW), 10 percent DC and 140 W (3.1 to 3.5 GHz) at the shorter 100 μsec PW, 10 percent duty cycle. The company offers a LDMOS device operating at the same frequency and pulse conditions, which yields an output power of 154 W (29 W more) and an extra dB of gain (10.4 dB) at a lower drain voltage (32 vs. 36 V). This improvement in performance underlines the competition between technologies, even within the same company.

One domestic manufacturer going after the S-band radar market with GaN technology is RFMD. At last year's MTT-S IMS in Atlanta, the company debuted a 400 W pulsed output power GaN HEMT amplifier operating over the 2.9 to 3.5 GHz band (17 percent bandwidth). Under pulsed RF drive, with 10 percent duty cycle and 100 µsec pulse width, the amplifier delivers an output power in the range of 401 to 446 W over the band, with a drain efficiency of 48 to 55 percent when biased at a drain voltage of 65 V.

The wideband nature of GaN-based amplifiers, with the ability to easily cover 500 MHz to 3 GHz, make them well-suited for use in frequency agile pulsed applications such as military radar, air traffic control radar and communications jamming.

26



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In speaking with the *Journal*, RFMD remarked on GaN's higher efficiency for pulsed, CW saturated and linear applications, which improves thermal requirements and energy usage; showing 5 to 10 percent improvement over LDMOS and Si-Bipolar.

Ray Crampton of Nitronex further added that, "Radar applications require pulsed power in the hundreds of watts up to very high frequencies. This fits well because GaN devices offer improved robustness, higher efficiency, higher power density, higher gain and faster switching speed than competing technologies for today's broadband radar systems. GaN also offers the ability to replace TWTs with more reliable and robust devices." An example of Nitronex recent product offerings is the NPT1007, released last February. This is a 200 W device (based on two 100 W transistors) that targets military communication applications below 1.5 GHz and has notable "design-ins" in the 30 to 512 MHz band as well as bands up to 1 GHz, according to Crampton.

Meanwhile, TriQuint Semiconductor began investigating GaN technology back in 1999, and through subsequent years developed a baseline process that led to a DARPA contract focusing on technology maturity and wideband performance in 2005. This research and development effort resulted in a production-released 0.25 micron gate process supporting products from DC to 18 GHz and achieving power levels in excess of 100 W.

# COMMERCIAL MARKETS – WIRELESS INFRASTRUCTURE

Until four years ago, LDMOS

covered about 90 percent of the high power PA applications above 2 GHz; the remaining market share belonged mostly to GaAs PHEMT technology.

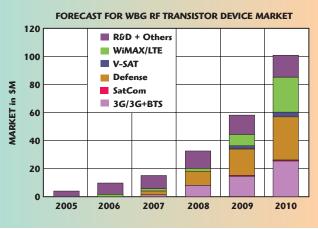
WBG devices made a significant commercial breakthrough in 2006 when Eudyna and NTT jointly announced the first 3G network "test" deployment using

GaN HEMT in Tokyo. New commercial offerings from Cree, RFMD and Nitronex soon followed, targeting both base station (3G, WiMAX) and general purpose applications. According to a 2008 GaN RF market report by Yole Développement, "GaN is currently positioned to challenge silicon dominance in the high power RF amplifier market estimated to be about \$900 M in 2008." ABI Research has the RF power market somewhat below this figure at a predicted \$800 M in 2011. But this challenge is not across the board, as LDMOS maintains an upper hand with pricing and legacy in certain sectors.

In the power market below 4 GHz, RF LDMOS transistors captured almost 70 percent of the total market in 2006. However, that number is predicted to go to 50 percent share of the RF power market in 2011, the ABI report forecasts. GaN may dominate most of the high-power markets at frequencies above 4 GHz, beyond the performance range of Si LDMOS. Eudyna Devices and Toshiba have wisely targeted the microwave (> 4 GHz) markets for much of their participation with GaN.

#### **4G OPPORTUNITIES**

Market analysts point to product announcements by GaN manufacturers as indicators of their increased focus on WiMAX/LTE markets and a shift away from existing 3G/3G+ infrastructure, where LDMOS is the entrenched technology. Unfortunately, the WiMAX market in 2009 has been hit rather hard by the economic downturn. Building-out brand new networks from scratch, as is the



deployment test ▲ Fig. 2 Projected RF markets for WBG transistors indicates most deployment using significant growth coming from 4G (courtesy of Yole Développement).

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case with WiMAX, requires hundreds of millions of dollars of capital. The current credit crunch along with a decrease in demand for broadband due to weakened consumer spending has led to many network build-outs being put on hold or delayed into next year.

Total sales of fixed and mobile WiMAX equipment fell 21 percent to US\$245 M in the third quarter of 2008, from the second quarter's figure, and are expected to slide further in 2009 (a report in early May 2009)

shows component makers revenue down 20 to 30 percent versus the year-ago quarter). Prior to the current slowdown, the GaN RF Market 2008 from Yole Développement had forecasted that the market size for GaN RF transistors could reach a level of about \$100 M by 2010, largely due to strong penetration of WiMAX/LTE systems, as shown in *Figure 2*.

Still LTE rollouts are expected to be coming in the 2010 to 2011 timeframe and any WiMAX delays will shorten its current time to market advantage over LTE. Therefore, WiMAX deployment cannot afford to be postponed for too long. According to ABI Research, the LTE standard is being driven by operators, which is the key differentiator between it and preceding wireless technologies. CDMA and Asian operators who are early adopters will be the first to launch LTE. Existing UMTS operators will probably delay launch to extend the life of their existing HSPA networks and simplify the upgrade to LTE by slowly evolving their current architectures.

When network operators introduced HSPA, packet data traffic quickly exceeded voice traffic. In some cases, a four fold increase in data traffic occurred in just three months. Future WiMAX and LTE build-outs will be needed in order to serve 1.8 billion broadband subscriptions by 2012, according to a five year projection made by Ericsson in 2007. To get there, high power transistors will need to deliver on performance, size, reliability and price.

#### **TECHNOLOGY**

WiMAX faces strong competition from existing wireless services, making it essential that WiMAX infrastructure equipment be as cost-effective as possible. A rough rule of thumb is that for high volume cellular base station applications, LDMOS prices are on the order of \$0.30 per W, GaAs is about \$0.9/W and GaN is about \$1/W. Performance-wise, linearity and efficiency for both WiMAX and LTE are also critical.

# THE IMPORTANCE OF LINEARITY AND EFFICIENCY

Both WiMAX and LTE use OFDM as the core modulation technology in the downlink direction and thus have roughly similar performance for any given RF bandwidth and set of conditions. However, the uplink modulation techniques are somewhat different. While WiMAX uses OFDMA for the uplink, LTE uses single carrier frequency division multiple access (SC-FDMA), which has a significantly reduced Peak to Average Power Ratio (PAPR). WiMAX's OFDMA has a peak-average ratio of about 10 dB, while LTE's SC-FDMA's peak-average ratio is about 5 dB.

The higher PAPR associated with



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BTE	L - Ku	1 kHz	2.2	-73	-80	-96	-96	-97	-123	12.72 GHz	13
MFS	L-K	1 kHz	2	-60	-75	-90	-95	-95	-120	5.3 GHz	13
CFS	L-K	1 Hz	2	-62	-75	-85	-89	-97	-110	14.84 GHz	13
Ku3LS	X - Ku	1 kHz	2.2	-62	-70	-75	-85	-97	-115	12.50 GHz	13
C3LS	С	1 kHz	1.1	-63	-88	-90	-100	-100	-115	5.50 GHz	13
UWB	S-K	1 kHz	Multioctave	-60	-71	-80	-90	-96	-105	12 GHz	13
MOS	VHF - K	1 kHz	Multioctave	-55	-65	-75	-85	-90	-100	20 GHz	13
SLS	L - Ku	125 kHz	1	-70	-80	-86	-88	-105	-115	3.3 GHz	13
SLFS	VHF - Ku	100 kHz	2	-70	-75	-80	-90	-115	-125	5 GHz	13
LFTS	VHF - Ku	100 Hz	1	-78	-88	-98	-98	-110	-130	350 MHz	13
VFS	L - Ku	>25 MHz	1.5	-60	-80	-110	-115	-115	-130	12.5 GHz	13

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WiMAX and OFDMA requires that the amplifier handle the occasional high power levels that can greatly exceed the average signal strength without introducing unacceptable levels of distortion. One way to do this is to use a larger transistor operating far below its compression point, otherwise known as backing-off the amplifier. Unfortunately, amplifier efficiency takes a hit when the device is backed-off. At 2 GHz, the latest LDMOS has

about 18 dB gain and is 65 percent efficient at the P1dB compression point. At a 6 dB back off point, the devices are typically -45 dBc WCDMA ACPR and 30 percent efficient. GaN offers slightly higher efficiency at 6 dB OBO.

#### **SAVING SOME GREEN**

According to Steven Theeuwen of NXP Semiconductors, "All the developments particularly for base stations and broadcast applications are driven by an ever increasing demand for higher efficiency, generally speaking. In turn this means less lost power, which means "greener" amplifiers. Higher efficiency does not only mean better use of RF power, but also reduces the energy necessary to remove the dissipated energy (cooling systems). Hence, improved efficiency helps twice, on amplifier and system level, to reduce overall power consumption. NXP claims leadership in delivering high efficient transistors and high efficiency concepts: developing the world's first fully integrated Doherty amplifier and the highest efficiency, discrete Doherty setup to date." (Ed. note: Based on LDMOS technology.)

At Mobile World Congress (Barcelona, Spain) in February, Freescale introduced its next generation (HV8) of LDMOS high power transistors, specifically targeting the stringent demands of high-data rates called for by WCDMA, WiMAX, LTE and Multicarrier GSM. The company claims that a primary benefit of the HV8 technology is the increase in operating efficiency, reducing the total power consumption of a base station system. This growing concern in "green" technology is driven by a global desire to cut energy costs and reduce the industry's carbon footprint along with the telecom provider's interest in lowering operating expenses.

The new devices introduced in February operate over the 860 to 960 MHz range, providing a power output range of 100 to 300 W and can be used in Class AB or C configurations. A symmetrical Doherty reference design using two transistors designed for multicarrier GSM applications was shown to deliver 58.0 dBm (630 W) peak power, 16.3 dB gain and a drain efficiency of 42.5 percent at an average output power level of 49.4 dBm (87 W) with good broadband linearity. Digital pre-distortion (DPD) evaluations showed the reference design to correct very well with six GSM carriers in signal bandwidths of up to 20 MHz.

According to Leonard Pelletier of Freescale, one of the most substantial system-related issues to consider when working with LDMOS is creating higher linearity through digital pre-distortion or feed forward error correction systems. With improve-





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ments in the correction capability of the architectures, the RF devices can be operated closer to their P1dB compression point, where the DC to RF conversion efficiencies are at their highest level. Improved linearity translates to improved efficiency and lower overall system costs.

Linearity and efficiency are also addressed with similar circuit architectures designed using GaN devices. According to Dave Aichele of RFMD, "The high terminal impedances of high

voltage GaN devices make the amplifiers suitable for higher bandwidth Class AB amplifiers as well as applications that attempt to improve efficiency such as Doherty, linearity such as push-pull, and extreme bandwidth such as distributed techniques. Thanks to the high impedances (and low parasitics) of GaN HEMTs, these higher bandwidth amplifiers can utilize most any standard circuit architecture with enhanced simultaneous bandwidth/efficiency/power performance."



Ray Pengelly from Cree noted that, "There has also been much success designing very high efficiency Class E, F, inverse F, J, etc. PAs (with GaN). Doherty (Class A/B/C) with DPD have addressed a range of telecommunications applications. We today achieve efficiencies > 50 percent at peak power levels as high as 500 W. PAs associated with Envelope Tracking (ET), where the high breakdown aspects of GaN, allow drain voltage operation anywhere from 20 to 65 V again with efficiencies exceeding 50 percent. ET is particularly promising for multi-band telecom applications."

TriQuint recently introduced its PowerBand<sup>TM</sup> family of wideband, high power discrete transistors employing a "revolutionary" (and somewhat secretive) circuit architecture and process technology. The product portfolio is based on different semiconductor technologies, including TriQuint's GaAs PHEMT, LDMOS and GaN materials and processes. The first released LDMOS device operates from 500 MHz to 2 GHz and produces 30 W, P1dB (instantaneous bandwidth), while a GaN-based product that will produce 100 W P1dB CW is expected this year.

Changes to infrastructure architecture will have an impact on how devices will compete. There is a desire by network operators to move the power amplifier from the base of the radio tower closer to the antenna, so that the losses attributed to long cable runs can be eliminated. This will reduce the power required out of the amplifier. The Remote Radio Head (RRH) architecture can increase overall efficiency of the network from 13 to 15 percent up to 30 percent, but requires smaller and lighter amplifiers than those found in the cabinet of a base station. In addition, since the amplifier is on top of a tower, reliability takes on a new importance. The higher operating temperature, higher power density (and therefore smaller device periphery) and better efficiency are strong drivers for using GaN or SiC in the growing RRH market.

#### **SCORECARD LDMOS**

Summary: LDMOS was developed between the late 1980s and early 1990s and became the technology of

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choice for cellular and 3G base station applications, completely replacing the BJT with its higher gain and efficiency, and superior linearity. A typical 28 V LDMOS FET has a power density in the range of 0.7 to 1 W/mm with improvements occurring for each new generation.

Cree has reported GaN-on-SiC power densities of approximately 4 W/mm, meaning that less die size is required for GaN for the same amount of output power compared to LD-

MOS. Higher power density helps offset GaN's higher cost by increasing the number of die per wafer, yet not enough to surpass the price advantage held by LDMOS. Despite more chips per wafer, GaN is processed on smaller (SiC) wafer substrates whereas LDMOS is processed on much larger and cheaper Si wafers.

Benefits: Costs—LDMOS has the lowest cost per watt (\$/W) ratio of any of the high power RF amplifier technologies. LDMOS also has some of

the best Class AB linearity, gain, reliability and thermal resistance of any popular RF power technologies.

Where to use: LDMOS excels in high volume, medium to high power, linear systems with very stringent cost goals and very high reliability requirements

Working with the technology: After years in the field, LDMOS has a solid track record. There are very highly developed and extensively used MMICs in the market place as multi-stage RF drivers and gain blocks. Freescale, for example, has a very extensive internal library of on-chip silicon passive components to design a wide variety of internally matched, temperature compensated, multi-stage RF MMIC devices with power levels ranging from 10 to 100 W. Large signal model (MET) includes thermal behavior.

Downside: LDMOS performance is excellent up to 3.8 GHz, but degrades rapidly beyond 4 GHz.

The Power Brokers: Freescale Semiconductor, RFMD, TriQuint, NXP Semiconductors, Integra Technologies, Infineon Technologies and ST Microelectronics.

#### GaN

Summary: GaNs early development dates back to the late 1990s, with funding largely from defense agencies such as DARPA. By the second half of this decade, GaN began to enter commercial markets with performance that challenged the prevailing technologies. Adoption of GaN has hinged on performance, cost and reliability, all of which has been favorable enough for the technology to make impressive penetration into several key high power markets.

Thermal management is key to achieving acceptable reliability. Because of this, GaN manufacturers use varying techniques to manage thermal rise. Most GaN suppliers use silicon carbide (SiC) as the substrate of choice due to its inherent high thermal conductivity. GaN-on-Si manufacturers use the ability to process very thin wafers with large die areas to achieve the same result. Along with SiC and Si, GaN is also processed on diamond, sapphire and silicon substrates. The diversity of substrates by individual vendors further segments the GaN family of devices.





### **High Performance Amplifiers**

### **General Purpose Gain Block Amplifiers**

- Broadband
- Typical gain up to 20 dB
- Typical bandwidths from 3 GHz up to 12 GHz
- OIP3 up to 36 dBm
- Input and output impedances are 50 Ohms
- Available in SC-88 or SOT-89 packages

71								
Frequency (MHz)	Gain Typ. (dB)	NF (dB)	OIP3 Typ. (dBm)	OP <sub>1 dB</sub>	Vdc (V)	Quiescent Current Typ. (mA)	Package (mm)	Part Number
LF-7	12.5	5.5	29	12.5	3.5	40	SOT-89	SKY65013-70LF
LF-12	12.5	5.8	29	12.5	3.5	40	SC-88	SKY65013-92LF
LF-6	16	4.8	36	18	4.7	70	SOT-89	SKY65014-70LF
LF-9	15	5.4	36	18	4.7	70	SC-88	SKY65014-92LF
LF-6	18	4.2	35	17	4.7	70	SOT-89	SKY65015-70LF
LF-6	18	4.8	35	18	4.7	70	SC-88	SKY65015-92LF
LF-3	20	4.8	27	14	3.5	40	SOT-89	SKY65016-70LF
LF-3	20	5.4	27	14	3.5	40	SC-88	SKY65016-92LF
LF- 6	20	4.5	35	20	5	100	SOT-89	SKY65017-70LF

### **Ultra Linear Power Amplifier Drivers**

• OIP3 up to 42 dBm

• Typical gain up to 20 dB

• Noise figure down to 1.8 dB

Frequency (MHz)	Gain Typ. (dB)	NF (dB)	OIP3 Typ. (dBm)	OP <sub>1 dB</sub>	Vdc (V)	Quiescent Current Typ. (mA)	Package (mm)	Part Number
0.25-2.7	16	5.5	42	25	3.3 or 5	125	3-pin MCM 4 x 4	SKY65004
0.25-2.7	20	3	33	21	3.3	76	3-pin MCM 4 x 4	SKY65008
0.25-2.5	12	4.3	42	27	3.3 or 5	100	4-pin SOT-89	SKY65009-70LF
0.25-2.7	16	5.5	42	25	3.3 or 5	125	4-pin SOT-89	SKY65028-70LF
0.25–6	15	2	40	21.5	3 to 5	140	4-pin SOT-89	SKY65038-70LF
0.39-1.5	14	1.8	37.5	25	5	46	4-pin SOT-89	SKY65045-70LF
1.5–2.5	14	2.1	38	21	5	47	4-pin SOT-89	SKY65080
0.4–2.3	18		39	27	5	260	SOIC-8 Exposed Paddle	SKY65112-84LF
0.4-2.3	20		40	30	5	450	SOIC-8 Exposed Paddle	SKY65113-84LF

### **Application-Specific Amplifiers**

- Advanced Metering Infrastructure (AMI)
- IEEE 802.15.4
- ISM
- TETRA
- WLAN

SKY65111, SKY65116, SKY65131, SKY65132, SKY65137, SKY65152

- High gain
- Internally matched 50 Ohm input and output ports
- Voltage controlled PA enable pin















#### **SiC Pros:**

- Greater than 3x better thermal conductivity of SiC vs Si (4.9 W/cm°K vs. 1.5 W/cm°K), supporting higher junction temperatures, reducing system complexity and weight
- Lower parasitic capacitance
- Epitaxial growth of GaN is better on SiC due to smaller lattice mismatch (3.4 percent on SiC vs. 17 percent on Si)
- Lower TEC mismatch on SiC (+25 percent for SiC vs. +100 percent on Si)

#### Si Pros:

- Silicon can be readily processed in very thin finished form, compensating for the higher thermal conductivity of the substrate relative to SiC
- The low cost and high yield of silicon allows larger die to be used, letting die designers spread heat over a larger area than SiC
- Lower cost than SiC, although this factor is expected to decrease with increasing volume of SiC substrates manufactured over time
- Supply chain advantage from wafer procurement, wafer processing, die attach and packaging can be second sourced by several existing well respected companies to avoid single thread manufacturing steps as well as the ability to scale production to support high volume requirements.

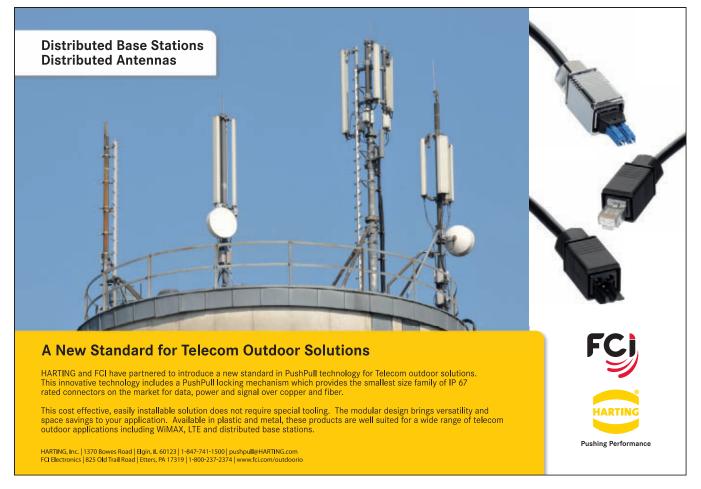
Benefits: GaN has high breakdown voltages (typically 100 to 200 V), higher power densities than LDMOS and higher ft depending on gate length (anywhere from 20 to > 150 GHz). The transistors have low capacitance per

watt resulting in higher output impedances, which leads to easier matching networks and relatively wide band performance.

Where to use: GaN is the high power transistor of choice above 4 GHz and is making in roads at lower frequencies with applications that can afford the higher price compared to LDMOS.

Working with the technology: GaN HEMTs in hybrid, discrete designs are most suited to Class A/B, Doherty, push-pull, feedback and lossy match, etc. For MMICs, a range of amplifier techniques ranging from distributed, through multi-stage and cascode implementations have been proven and many are now in production or preproduction. Today's commercially available GaN-on-SiC HEMTs usually use either copper-moly-copper or coppertungsten flanged packages. In some special cases more elaborate heat-sinking is required using advanced materials, such as those containing diamond, but they are less mature and tend to be expensive. In some critical applications where liquid cooling may not be available, that option may be acceptable. The transistors can also be "spread out" to reduce heat density, but this can have an impact on the frequency of operation of the devices as well as the number of parts that can be produced on each wafer. Models are available for popular RF/microwave design software depending on the device manufacturer.

Downside: Currently more expensive than LDMOS, relative lack of field data and minimal reliability data based on life history of the technology.



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The Power Brokers: RFMD, Nitronex, TriQuint, Eudyna, Cree, Toshiba, NEC, Fujitsu and Matsushita MEI/Panasonic.

#### SiC

Summary: The larger thermal conductivity of SiC and GaN enables lower temperature rise due to self heating. The five to six times' higher breakdown field of SiC and GaN is what gives those materials the advantage over Si and GaAs for RF power devices. SiC is a wide bandgap material (3.26 eV), but suffers from poor electron transport properties, which hinders its use in very high frequency amplifiers. SiC has also been limited by expensive, small and low-quality substrate wafers.

In addition, the new SiC devices from Microsemi are fabricated with 100 percent gold metallization and gold wires in hermetically sealed packages (measuring a compact 0.9 × 0.4 in, which is 50 percent smaller than the highest power devices in BJT or LDMOS). This gives the technology the highest reliability in weather radar and long-range tracking radar applications (i.e. providing military-grade long-term reliability), according to the company. The product capability at 10:1 load mismatch tolerance performance also improves system yields. Cree boosts using the same epoxy sealed (gross leak proof) ceramic/metal packages used for GaN HEMTs. The semiconductors are fully passivated providing MTTFs greater than 1 million hours at transistor junction temperatures of 225°C.

Benefits: Microsemi says that typical silicon-based RF

power transistor solutions offered throughout the industry, such as BJT (bipolar junction transistor) or LDMOS (laterally diffused metal oxide semiconductor) devices must use complex push-pull circuit designs to achieve similar power levels. In contrast, the SiC RF power transistors have a single-ended design with simplified impedance matching.

Where to use: Radar and avionics where higher power levels (up to the kilowatt range) at UHF and VHF frequencies are required. Development is pushing the frequency range higher.

Downside: Smaller number of suppliers and limited frequency.

The Power Brokers: Microsemi and Cree Inc.

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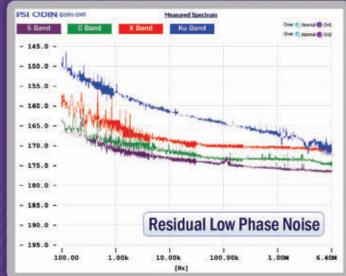
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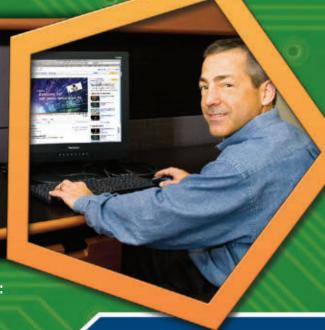
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### **TriQuint Optical Drivers**

	Frequency	Power	Gain	Noise	Voltage / Current	Package	Part
Description	(GHz)	(Vpp or dBm)	(dB)	Figure (dB)	(V / mA)	Style	Number
10.7 Gb/s Diff. TIA	DC - 10	-	8K dB $\Omega$ SE	6pA√Hz	3.3 / 80	Die	TGA4815
10.7 Gb/s Diff. TIA	DC - 10	11-7	1.6K dB $\Omega$ SE	6pA √Hz	3.3 / 60	Die	TGA4816
10.7 Gb/s Diff. TIA	DC - 10	-	3.2K dB $\Omega$ SE	11pA√Hz	3.3 / 70	Die	TGA4817
9.9 - 12.5 Gb/s 3V - 7V Driver	DC - 13	3 - 7 Vpp	20	-	3.3 - 5 / 100	SM-A5-28	TGA4955-SM**
9.9 - 12.5 Gb/s 3V - 7V Driver	DC - 13	3 - 7 Vpp	32	-	3.3 - 5 / 115	SM-A8-28	TGA4956-SM*
40 Gb/s LN / MZ Mod. Driver	DC - 35	5 - 8 Vpp	30		8 / 300	SL-A7-21	TGA4942-SL**
28 Gb/s 8Vpp SE Driver	DC - 30	3 - 9Vpp	32	-	6 - 7 / 270	SL-A7-21	TGA4943-SL*
9.9 - 12.5 Gb/s Mod. Driver	DC - 16	3V - 10V	35	2.5	5.5 - 8 / 210	SL-A2-18	TGA4953-SL
9.9 - 12.5 Gb/s Mod. Driver	DC - 16	3V - 10V	35	2.5	5.5 - 8 / 210	SL-A4-18	TGA4954-SL
12.5 Gb/s NRZ Driver	DC - 18	11V	16		8 / 285	Die	TGA4807
12.5 Gb/s NRZ Driver	DC - 18	24 dBm	16	3.5	5 - 8 / 70 - 175	Die	TGA1328-SCC
12.5 Gb/s NRZ Driver	DC - 18	8V	16	3.5	8 / 175	SL-A1-12	TGA8652-SL
12.5 Gb/s RZ Driver	DC - 25	7V	15	-	9 / 100	Die	TGA4802
43 Gb/s NRZ Driver	DC - 35	7V	15	-	6.5 / 170	Die	TGA4801
Wideband Driver (40 Gb/s)	DC - 35	4V	12	-	5 / 135	Die	TGA4832
40 Gb/s TIA, SE	DC - 40		<b>250</b> dB $\Omega$	15pA √ Hz	5 / 30	Die	TGA4812
LNA / Gain Block	DC - 40	11.5 dBm	13	3.2	5 / 50	Die	TGA4830
LNA / Gain Block	DC - 60	13 dBm	15	3	6 / 50	Die	TGA4811
43 Gb/s Driver	DC - 78	3V	8	5	6 / 82	Die	TGA4803
10.7 - 12.5 Gb/s Linear Mod. Driver	0.03 - 8	25 dBm	20	- 1	8 / 310	SM-A8-28	TGA4823-2-SM
CATV TIA / Gain Block, SB	0.04 - 1	27 dBm	20	1.5	8 / 350	SM-O8-20	TGA2803-SM

NOTES: \* = New, \*\* = Coming Soon, SB = Self Biased, SE = Single-Ended





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	ND_LOW N			_		
Model No.	Freq (GHz)	Gain (dB) MI	Noise Figure (dB)	Power-out @ P1-dl		VSWR
CA01-2110 CA12-2110	0.5-1.0 1.0-2.0	28 30	1.0 MAX, 0.7 TYP 1.0 MAX, 0.7 TYP	+10 MIN +10 MIN	+20 dBm +20 dBm	2.0:1 2.0:1
CA24-2111	2.0-4.0	29	1.0 MAX, 0.7 TTT	+10 MIN	+20 dBm	2.0:1
CA48-2111	4.0-8.0	29	1.1 MAX, 0.95 TYP 1.3 MAX, 1.0 TYP	+10 MIN	+20 dBm	2.0:1
CA812-3111	8.0-12.0	27	1.6 MAX, 1.4 TYP	+10 MIN	+20 dBm	2.0:1
CA1218-4111	12.0-18.0	25	1.9 MAX, 1.7 TYP	+10 MIN	+20 dBm	2.0:1
CA1826-2110	18.0-26.5	32	3.0 MAX, 2.5 TYP	+10 MIN	+20 dBm	2.0:1
			ID MEDIÚM POV		FIERS	0.0.1
CA01-2111 CA01-2113	0.4 - 0.5 0.8 - 1.0	28 28	0.6 MAX, 0.4 TYP	+10 MIN +10 MIN	+20 dBm +20 dBm	2.0:1 2.0:1
CA12-3117	1.2 - 1.6	25	0.6 MAX, 0.4 TYP 0.6 MAX, 0.4 TYP	+10 MIN	+20 dBm	2.0:1
CA23-3111	2.2 - 2.4	25 30 29 28	0.6 MAX, 0.45 TYP	+10 MIN	+20 dBm	2.0:1
CA23-3116	2.7 - 2.9	29	0.7 MAX, 0.5 TYP	+10 MIN	+20 dBm	2.0:1
CA34-2110	3.7 - 4.2	28	$1.0 \text{ MAX} \cdot 0.5 \text{ TYP}$	+10 MIN	+20 dBm	2.0:1
CA56-3110	5.4 - 5.9	40	1.0 MAX, 0.5 TYP	+10 MIN	+20 dBm	2.0:1
CA78-4110	7.25 - 7.75	40 32 25	1.2 MAX, 1.0 TYP	+10 MIN	+20 dBm	2.0:1
CA910-3110 CA1315-3110	9.0 - 10.6	Z5	1.4 MAX, 1.2 TYP	+10 MIN	+20 dBm +20 dBm	2.0:1
CA12-3114	13.75 - 15.4 1.35 - 1.85	30	1.6 MAX, 1.4 TYP	+10 MIN +33 MIN	+20 dBm	2.0:1
CA34-6116	3.1 - 3.5	25 30 40	4.0 MAX, 3.0 TYP 4.5 MAX, 3.5 TYP	+35 MIN	+43 dBm	2.0:1
CA56-5114	5.9 - 6.4	30	5.0 MAX. 4.0 TYP	+30 MIN	+40 dBm	2.0:1
	8.0 - 12.0	30	4.5 MAX, 3.5 TYP 5.0 MAX, 4.0 TYP	+30 MIN	+40 dBm	2.0:1
CA812-6116	8.0 - 12.0	30	5.0 MAX, 4.0 TYP	+33 MIN	+41 dBm	2.0:1
CA1213-7110	12.2 - 13.25	30 30 28 30	6.0 MAX, 5.5 TYP	+33 MIN	+42 dBm	2.0:1
CA1415-7110 CA1722-4110	14.0 - 15.0 17.0 - 22.0	30 25	5.0 MAX, 4.0 TYP 3.5 MAX, 2.8 TYP	+30 MIN +21 MIN	+40 dBm +31 dBm	2.0:1 2.0:1
IIITRA-RRC		MILITI-O	CTAVE BAND AN	APLIFIERS	+31 ubili	2.0.1
Model No.	Freq (GHz)	Gain (dB) MI	Noise Figure (dB)	Power -out @ P1-dl	3rd Order ICP	VSWR
CA0102-3111	0 1-2 0	28	1.6 Max, 1.2 TYP	+10 MIN	+20 dBm	2.0:1
CA0106-3111	0.1-6.0	28 26 32 36 26 22	1.9 Max, 1.5 TYP	+10 MIN	+20 dBm	2.0:1
CA0108-3110 CA0108-4112	0.1-8.0	26	2.2 Max, 1.8 TYP	+10 MIN	+20 dBm	2.0:1
CA0100-4112	0.1-8.0 0.5-2.0	32 36	3.0 MAX, 1.8 TYP 4.5 MAX, 2.5 TYP	+22 MIN +30 MIN	+32 dBm +40 dBm	2.0:1 2.0:1
CA26-3110	2.0-6.0	26	2 N MAX 1 5 TYP	+ I () \\\\\\\\	+20 dBm	2.0:1
CA26-4114	2.0-6.0	22	2.0 MAX, 1.5 TYP 5.0 MAX, 3.5 TYP 5.0 MAX, 3.5 TYP 5.0 MAX, 3.5 TYP	+30 MIN	+40 dBm	2.0:1
CA618-4112	6.0-18.0	25	5.0 MAX, 3.5 TYP	+23 MIN	+33 dBm	2.0:1
CA618-6114	6.0-18.0	35 30	5.0 MAX, 3.5 TYP	+30 MIN		2.0:1
CA218-4116 CA218-4110	2.0-18.0 2.0-18.0	30	5.0 MAX, 3.5 TYP 3.5 MAX, 2.8 TYP 5.0 MAX, 3.5 TYP	+10 MIN +20 MIN	+20 dBm +30 dBm	2.0:1 2.0:1
CA218-4110	2.0-18.0	29	5.0 MAX, 3.5 TYP	+24 MIN	+34 dBm	2.0:1
	MPLIFIERS					2.0.1
Model No.	Freq (GHz) I	nput Dynamic	Range Output Power F	Range Psat Pov	ver Flatness dB	VSWR
CLA24-4001	2.0 - 4.0	-28 to +10 (	IBm +/ to + [ ]	dBm -	⊦/- 1.5 MAX	2.0:1
CLA26-8001	2.0 - 6.0	-50 to +20 (	1BM + 14 to + 10	8 dBm -	-/- I.5 MAX	2.0:1
CLA712-5001 CLA618-1201	7.0 - 12.4 6.0 - 18.0	-2110 + 100	IBm +7 to +11 IBm +14 to +13 IBm +14 to +13 IBm +14 to +13	7 ubili -	-/- 1.5 MAX	2.0:1 2.0:1
		ATED GAIN	ATTENUATION	/ ubili	F/ 1.3 MAX	2.0.1
Model No.	Freq (GHz)	Gain (dB) MIN	Noise Figure (dB) Pow	er-out@P1-dB Gair	Attenuation Range	VSWR
CA001-2511A	0.025-0.150	21	5.0 MAX, 3.5 TYP - 2.5 MAX, 1.5 TYP -	+12 MIN +18 MIN	30 dB MIN	2.0:1
CA05-3110A	0.5-5.5 5.85-6.425	23	2.5 MAX, 1.5 IYP -	+18 MIN	20 dB MIN	2.0:1
CA56-3110A CA612-4110A	6.0-12.0	28 24	2.5 MAX, 1.5 TYP - 2.5 MAX, 1.5 TYP - 2.2 MAX, 1.6 TYP -	+16 //\li\ +12 MIN	22 dB MIN 15 dB MIN	1.8:1 1.9:1
CA1315-4110A		25	2.2 MAX, 1.6 TYP -	+16 MIN	20 dB MIN	1.8:1
CA1518-4110A	15.0-18.0	30	3.0 MAX, 2.0 TYP -	+18 MIN	20 dB MIN	1.85:1
	NCY AMPLIFI					
Model No.		Gain (dB) MIN		ower-out@P1-dB	3rd Order ICP	VSWR
CA001-2110	0.01-0.10	18	4.0 MAX, 2.2 TYP	+10 MIN	+20 dBm	2.0:1
CA001-2211 CA001-2215	0.04-0.15 0.04-0.15	24 23	3.5 MAX, 2.2 TYP	+13 MIN +23 MIN	+23 dBm +33 dBm	2.0:1 2.0:1
CA001-2213	0.01-1.0	28	4.0 MAX, 2.2 TYP 4.0 MAX, 2.8 TYP	+17 MIN	+27 dBm	2.0:1
CA002-3114	0.01-2.0	27	4.0 MAX, 2.8 TYP	+20 MIN	+30 dBm	2.0:1
CA003-3116	0.01-3.0	18	4.0 MAX, 2.8 TYP	+25 MIN	+35 dBm	2.0:1
CA004-3112	0.01-4.0	32	4.0 MAX, 2.8 TYP	+15 MIN	+25 dBm	2.0:1
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### Defense News



Harris Corp.

Awarded \$600 M
to Modernize US

Strategic Satellite

Communications

arris Corp., an international communications and information technology company, has been awarded a 10-year, \$600 M contract for the US Army's Modernization of Enterprise Terminals (MET) program. The next-generation military satellite communications terminals developed for the MET program will provide

the worldwide backbone for high-priority military communications and missile defense systems. As prime contractor, Harris will develop, test and certify four unique terminal configurations during a 30-month, First Article Test phase. In addition, Harris will provide production hardware under the five-year base contract, with five additional option years, and will support field activities such as site preparation, installation, test, operations and maintenance. The program will be managed by Team DCATS—Project Manager, Defense Communications and Army Transmission Systems.

Harris will replace up to 80 AN/GSC-52, AN/GSC-39, AN/FSC-78 and other aging strategic satellite communications terminals around the world with new, simultaneous X- and Ka-band terminals capable of interfacing with the new Wideband Global Satellite constellation as well as with legacy satellite systems. The new terminals will support Internet Protocol and Dedicated Circuit Connectivity within the Global Information Grid, providing critical reach-back capability for the warfighter.

"MET leverages our long and successful track record of success on the AN/GSC-52 terminal modernization program to provide PMDCATS with an advanced, strategic terminal architecture that achieves a high level of equipment and integration commonality, thereby lowering acquisition and logistics costs," said Wes Covell, President of Defense Programs for Harris Government Communications Systems. "Harris is proud to provide the next generation of strategic, multiband terminals for the Department of Defense, and we look forward to expanding our successful relationship with PMDCATS through the MET program."

Harris teammates on the MET program include General Dynamics SATCOM Technologies, a leader in X- and Ka-band satellite communications products; O'Neil & Associates, a supplier of world-class logistics and interactive, electronic technical manuals; and Janus Research Group, an innovator in training simulation. The hardware will include various fixed ground terminal configurations; a hardened, transportable terminal and a small terminal suitable for rooftop mounting. General Dynamics SATCOM Technologies will develop the X-band antenna feed as well as a dual/simultaneous X- and Ka-band antenna feed capable of meeting the stringent requirements for low intermodulation products. They will also develop 12.2-meter antennas for fixed ground terminals, 7.2-meter antennas for transportable terminals and 4.8-meter antennas for small terminals. The first terminal is scheduled for fielding in early

Lockheed Martin
Rolls Out THAAD
Launchers, Fire
Control and
Communications

Lockheed Martin officially rolled out the new Terminal High Altitude Area Defense (THAAD) Weapon System launcher and Fire Control and Communications unit in a ceremony at the company's THAAD Launcher Integration Complex in Camden, AR. The ceremony, attended by US Senator Mark

Pryor and US Congressman Mark Ross, commemorated the delivery of the first THAAD ground segment vehicles to come off the production line in Camden.

The new hardware will be delivered to soldiers at Fort Bliss, TX, who will have a fully operational THAAD battery (equipment and personnel) by the end of 2009. "What the hardworking employees of Lockheed Martin's Camden Operations have accomplished in such a short time is a testament to their dedication to our troops," said US Senator Mark Pryor. "It gives me great pride to know that one of the world's most advanced and proven air defense systems are produced, in part, here in the great state of Arkansas."

"The THAAD system will play a pivotal role in our nation's missile defense, and today's rollout is an encouraging sign of the tremendous progress we are making in this vital technology," said US Congressman Mike Ross. "The Camden area employees of Lockheed Martin have a long history of success and today is no exception. I thank them for their hard work in providing our military with the technology it needs to protect and defend our troops and our homeland."

"This is truly a great day for air defenders," said Tom Mc-Grath, Vice President of the THAAD program at Lockheed Martin. "We are proud to deliver this proven air defense capability to our forces. We are seeing the incredible power of THAAD to protect our warfighters and population centers with each successful test flight, and now we are seeing the reality of production hardware rolling off the line."

Lockheed Martin is the prime contractor and systems integrator for the THAAD Weapon System. The company's new 200,000 square-foot Launcher Integration Complex at Camden Operations currently has an employee population of approximately 600. "This is an outstanding example of government/industry partnership to achieve great things for the warfighter," said Glenn David Woods, Camden Operations Plant Manager for Lockheed Martin Missiles and Fire Control. "Our commitment is to produce the world's most advanced and effective air defense capability for our soldiers and allies."

Northrop Grumman
Space & ISR Systems
Joins Raytheon-led
Team IBCS

Another industry partner has joined the Raytheon Co.-led team for the US Army's Integrated Battle Command System (IBCS) program. Northrop Grumman Corp.'s Space & ISR Systems Division facility in

### DEFENSE NEWS



Boulder, CO, joins the other partners of Team IBCS including Raytheon, General Dynamics, Teledyne Brown Engineering, Davidson Technologies, IBM and Carlson Technologies, as well as academia partners. The new team member brings expertise in evaluating warfighter benefits of space-based data to the IBCS architecture. The Northrop Grumman Space & ISR Systems Division performs work at Buckley and Schriever Air Force Bases elsewhere in Colorado.

IBCS is a US Army and joint development program with a modular, open architecture, system-of-systems construct allowing air and missile defense warfighters to use any sensor and any shooter within an integrated fire control network. Raytheon won the first stage of a competitive, multi-phase Army award for IBCS in late September 2008.

Team IBCS was formed using OpenAIR<sup>TM</sup>, Raytheon's open business model that uses the best of large and small businesses and academia to provide the best value solution. "The addition of Northrop Grumman Space & ISR Systems to the team reinforces our commitment to providing warfighters with advanced capabilities early as well as exemplifying the tenets of our open air objective and best-of-breed approach," said Dan Kirby, the win leader for Team IBCS.

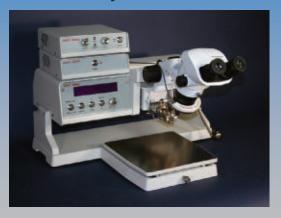
"Raytheon's Team IBCS is a specifically tailored team devoted to partnering with our Army customer to provide our warfighters the next 'unfair advantage' on current and future battlefields against all aerial threats," added John Urias, Vice President of the Raytheon Battlespace Integration Directorate.

Air and Missile Defense systems included in the IBCS program architecture are weapon and sensor systems already developed and produced by Raytheon, including the Patriot air and missile defense system; JLENS (Joint Land-Attack Cruise Missile Defense Elevated Netted Sensor System); SLAMRAAM (Surface-Launched Advanced Medium-Range Air-to-Missile); the Sentinel Radar; and the THAAD (Terminal High-Altitude Air Defense) radar.

A preliminary design review for the Integrated Battle Command System was scheduled for May 2009, and a single award for phase two of the program is expected in late August 2009. Integrated Defense Systems is Raytheon's leader in Global Capabilities Integration providing affordable, integrated solutions to a broad international and domestic customer base, including the United States Missile Defense Agency, the United States Armed Forces and the Department of Homeland Security.

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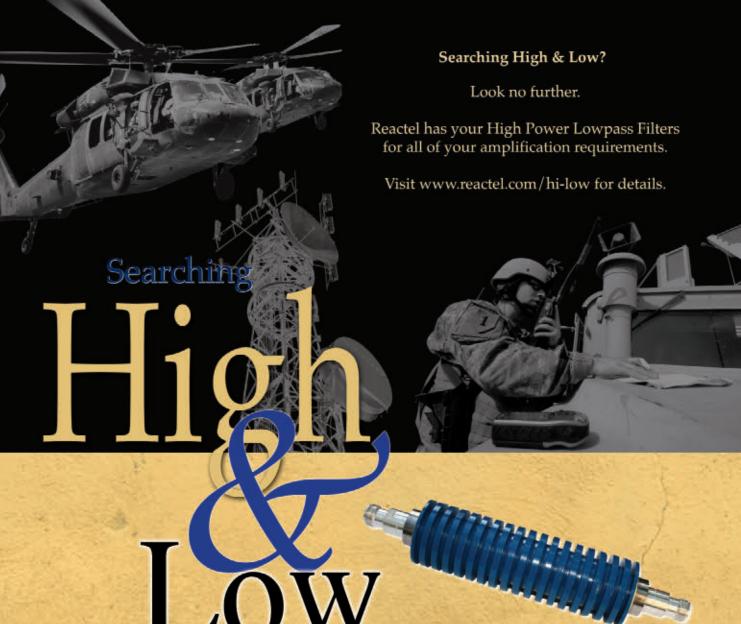
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Passband	Rejection Points
20 - 30 MHz, minimum	≥ 40 dB @ 40 MHz & ≥ 50 dB @ 60 - 400 MHz
20 - 45 MHz, minimum	≥ 40 dB @ 60 MHz & ≥ 50 dB @ 90 - 600 MHz
20 - 75 MHz, minimum	≥ 40 dB @ 90 MHz & ≥ 50 dB @ 135 - 600 MHz
20 - 115 MHz, minimum	≥ 40 dB @ 150 MHz & ≥ 50 dB @ 250 - 600 MHz
20 - 150 MHz, minimum	≥ 40 dB @ 200 MHz & ≥ 50 dB @ 300 - 600 MHz
20 - 220 MHz, minimum	≥ 40 dB @ 300 MHz & ≥ 50 dB @ 450 - 900 MHz
20 - 335 MHz, minimum	≥ 40 dB @ 440 MHz & ≥ 50 dB @ 660 - 1400 MHz
20 - 500 MHz, minimum	≥ 35 dB @ 670 MHz & ≥ 50 dB @ 1005 - 2000 MHz
20 - 700 MHz, minimum	≥ 40 dB @ 980 MHz & ≥ 50 dB @ 1470 - 2000 MHz
20 - 1010 MHz, minimum	≥ 35 dB @ 1400 MHz & ≥ 50 dB @ 2100 - 3000 MHz
20 - 1400 MHz, minimum	≥ 40 dB @ 2000 MHz & ≥ 50 dB @ 3000 - 4200 MHz
20 - 2000 MHz, minimum	≥ 40 dB @ 2800 MHz & ≥ 50 dB @ 4200 - 5000 MHz
20 - 3000 MHz, minimum	≥ 40 dB @ 3940 MHz & ≥ 50 dB @ 5910 - 6000 MHz

#### Common Specifications

- IL: ≤ 0.3 dB @ PB
- VSWR: < 1.25:1 @ Passband</li>
- Power: 2000 W CW
- · Connectors: SC or Type N
- \* These units are customizable to your exact specifications.



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### International Report

Richard Mumford, International Editor

### EADS DS and Larsen & Toubro Join Forces in India

ADS Defence & Security (DS) and Indian engineering giant Larsen & Toubro (L&T), Mumbai, are to join forces in the fields of defence technology. Subject to approval by the Indian Government the plan is for the formation of a joint venture company for defence electronics in India, based in Talegaon near Pune.

The proposed joint venture has the potential to become the leading Indian Electronics House for defence and security. The new company will aim at design, development, manufacturing and related services in the fields of electronic warfare, radar, military avionics and mobile systems for military applications.

The Indian defence and security market is growing fast and EADS intends to grow with it. Via this joint venture EADS plans to move beyond just providing high technology sales to India by creating an Indian industrial base with the development of a long-term partnership, including the transfer of technology wherever necessary.

The joint venture company will develop and manufacture indigenous solutions for military requirements of Indian customers as well as the world market. Thus, the Indian JV company will provide the armed forces with locally produced high tech equipment and assured life-time support.

A.M. Naik, chairman and managing director of L&T, said, "For over two decades, L&T has been a major supplier of critical systems to India's defence forces. These include a wide range of products like weapon launchers, naval systems, radar systems, etc. We welcome the formation of this joint venture that will create opportunities for development of state-of-the-art defence electronic products and systems for the Indian defence forces and for the rest of the world."

Dr. Stefan Zoller, CEO of EADS Defence & Security, added, "EADS DS is a high tech company driving the development of integrated system solutions for armed forces and civil security worldwide. We are proud of joining forces with one of India's biggest technology companies. Our joint venture is proof of our commitment to India."

### TSB Funds Ultra Fast Broadband Initiative

A new initiative by the Technology Strategy Board (TSB), which addresses the development of Ultra Fast Broadband, looks set to be accelerated following the start of over a dozen innovative research and development feasibility projects. The result could be a major change in the way that businesses operate across the world

TSB, the organisation that drives technological innovation in the UK, is investing £1 M to help companies carry out initial research that will ultimately lead to the introduction of Internet access technology with speeds of between 1 and 10 Gb/s—100 to  $1{,}000$  times faster than current broadband speeds.

The feasibility projects—each costing between £30,000 and £100,000—will, in turn, help establish European collaborations that will participate in larger EU-funded research and development initiatives. The ultimate aim, the development of pan-European Ultra Fast Broadband, could see European companies gaining a massive competitive advantage on a global scale.

Commenting on the decision to fund the projects, Mike Biddle, lead technologist at the Technology Strategy Board, said, "The challenge is to identify ways to address the technical issues facing the introduction of Ultra Fast Broadband within the next decade and to build European collaborations to exploit the technology, while generating wealth for the UK. Our intention in providing this funding is to help British companies establish future European collaborations that will participate in larger EU funding initiatives."

### NEC Mobile WiMAX Base Station Selected for Japan

Inc., a nationwide Japanese telecommunications carrier capitalizing on mobile WiMAX technologies, has selected NEC Corp. to supply mobile WiMAX base stations. The company has chosen to adopt NEC's recently developed Paso-Wings BS202 mobile WiMAX base station, which

is the first to be equipped with Uplink-Beam Forming (UL-BF) technologies. These technologies improve communications speed and increase the base station coverage area by reducing radio frequency interference between base stations and data transmission terminals.

The system's adoption follows NEC's work to acquire the WiMAX Forum's Wave 2 (2.5 GHz, 3.5 GHz) authentication and its actions to secure international standardization. A wide variety of functions and an external interface based on international standards enable the PasoWings BS202 system to be integrated with a broad range of vendors' equipment, which contributes to the smooth construction of WiMAX networks in short periods of time.

The base stations are compact and the adoption of a high efficiency amplifier enables the integration of outdoor units (ODU), which send and receive transmissions, with indoor units (IDU), which convert signals and control access. Also, reducing the space required to accommodate base stations, the time needed to construct them, and the resources necessary for maintenance reduces costs. NEC regards its selection to provide the PasoWings BS202 to UQ Communications as evidence of the high regard held for its products and services on a worldwide level.





### ITP-IET Join Forces to Raise Standards

The Institute of Telecommunications Professionals (ITP) has formed a collaborative partnership with the Institution of Engineering and Technology (IET) to create a joint service exclusively for its members aimed at raising professional standards across the ICT sector. This joint ITP-IET member registration programme

means that ITP members can apply for professional registration, using the IET, which is licensed by the Engineering Council UK to award professional qualifications. ITP members of this programme will be entitled to use qualification designatory letters CEng, IEng, EngTech or ICTTech after their name once they are awarded ECUK registration.

Michelle Richmond, IET Membership and Professional Development Director, said, "In the current economic climate it is more important than ever to set oneself apart from the competition. Professional registration does just this and shows commitment and dedication, as well as demonstrating to employers a range of skills. We are delighted to have formed this partnership, which is part of the IET's collaborative approach to raising professional standards and competence across the industry worldwide."

### Motorola and Apprion Complete OEM Agreement

Apprion has signed an OEM agreement with Motorola Inc. that enables the two companies to jointly develop and market integrated wireless application networks for industrial enterprises. By integrating Apprion's industrial-focused wireless appliances and applications with Motorola's comprehensive line of in-

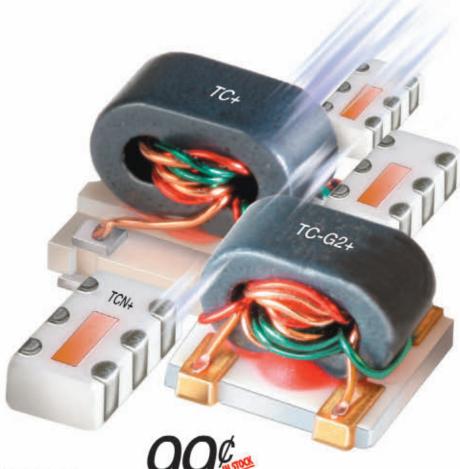
door and outdoor wireless networking solutions, industrial enterprises will now be able to leverage best-of-class wireless networks, enabling them to support dozens of applications that utilize numerous wireless radios and protocols.

Through the OEM agreement, the two companies will initially incorporate wireless broadband systems and wireless LAN solutions from Motorola into the Apprion ION System. The second phase of enhancements will result in the full integration of Motorola products and technologies as modular components of Apprion's IONosphere and IONizer solutions.

The combination of technologies from the two companies will enable a wide range of applications. Examples include mobile safety applications, unified voice communications, perimeter security, predictive maintenance, and remote monitoring and optimization of critical assets.



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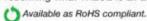
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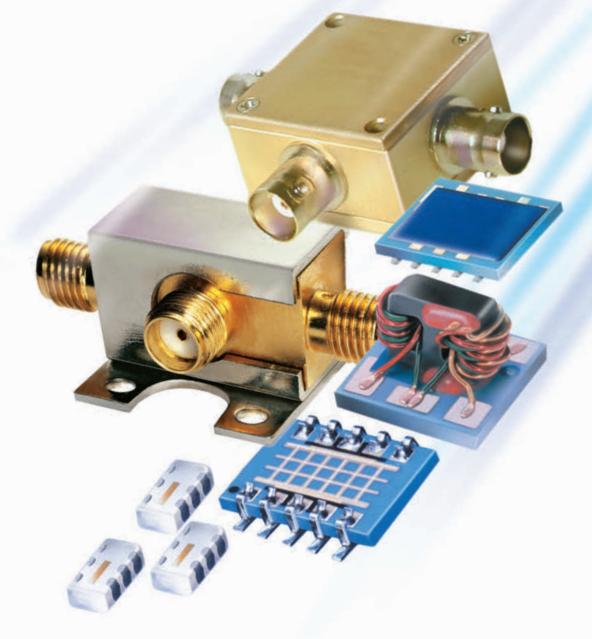






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### Commercial Market

# Recession or Not, Wireless Backhaul Expansion Continues Strongly

Worldwide revenues from backhaul leasing are expected to double over the next 30 months, according to a new study from ABI Research. The growth curve even accelerates after 2012, resulting in a five-fold revenue increase between 2009 and 2014. Why this powerful perfor-

mance? According to ABI Research senior analyst Nadine Manjaro, the main driver is the effort by mobile operators to prepare for an upgrade to LTE. "Operators might not deploy LTE immediately," she says, "but they know that before they do, they'll have to upgrade their backhaul capacity."

Backhaul is the bottleneck that can prevent a satisfactory 3G user experience. "AT&T Mobility has found that one iPhone user typically generates as much data traffic as 30 basic feature phone users," notes Manjaro. Wireless network traffic will dramatically increase as iPhone-like devices become the norm and laptop PC card usage increases. Another indicator is the growing capital expenditure on microwave backhaul, which will exceed \$8.5 B in 2009.

The market opportunities generated by this growth in backhaul are spread around the backhaul equipment vendors and fixed line operators. Some backhaul infrastructure vendors like Ericsson, Alcatel-Lucent and Nokia Siemens Network will benefit from operators' strong interest in Carrier Ethernet solutions. Major microwave equipment vendors like DragonWave and Harris Stratex will also benefit from increased microwave adoption. And fixed-line operators such as BT, Embarq, AT&T and Verizon Communications will develop new revenue streams by providing leased backhaul services.

Even the business models for backhaul are in flux. "We have observed a movement towards backhaul as a managed service," says Manjaro. "This enables mobile operators to focus on their core business, while guaranteeing a backhaul capacity matched to their changing traffic demands. BT provides that service to four of the top five European operators. In the US, Embarq is moving in the same direction, and I think more cable companies will follow suit. Wireline operators, who typically were losing business to wireless operators, can now get a piece of that wireless pie."

ABI Research's new study, "Mobile Backhaul—Global Market Analysis and Forecast," provides a comprehensive analysis of the global mobile backhaul market, including forecasts by region and technology. It is part of the firm's Mobile Networks Research Service

ABI Research provides in depth analysis and quantitative forecasting of emerging trends in global connectivity.

Wireless
Communications
Sector to Benefit
from \$6.8 B
Stimulus Funding

The American Recovery and Reinvestment Act (ARRA, also known simply as the Stimulus Bill) will provide funding for a massive \$6.8 B worth of wireless communications upgrades and new deployments over 2009-2010. The Act offers a significant one-off opportunity for wireless equipment vendors, an opportunity that

is examined in depth by a new study from ABÎ Research.

"The ARRA represents a windfall for wireless service providers as well as for satellite service providers," comments vice president Stan Schatt. "It will have an enormous impact on Wi-Fi and wireless broadband vendors. It will also immediately benefit a number of specific vertical industries including healthcare, education, homeland security, the environment, and the nation's electricity infrastructure."

In healthcare, the scope for adding wireless to the technology mix encompasses Wi-Fi-enabled mobile devices and sensors, communications systems linking health networks, telepresence, wireless LAN equipment, and Wi-Fi-enabled video surveillance systems.

In education, already a leading adopter of Wi-Fi solutions, equipment vendors are developing templated solutions in such areas as WLANs for "learning anywhere," voice-over-Wi-Fi, and WLAN equipment and software to track students' progress for "No Child Left Behind" record keeping.

The Department of Homeland Security and US Customs and Border Protection are potential goldmines for wireless vendors because of the many agencies within them that will use ARRA funds for tactical communications equipment, infrastructure equipment, and security equipment. Even critical infrastructure construction projects such as bridges and tunnels often require wireless video surveillance systems.

### Mobile Consumers Prepared to Support Green Initiatives

The results of a recent consumer survey conducted in North America by ABI Research suggest that nearly half of those mobile consumers surveyed are somewhat likely or very likely to be influenced by suppliers' green credentials when purchasing services or devices.

Respondents were asked whether they'd be more likely to purchase mobile services or mobile handsets from an operator that makes use of 'green' initiatives, which were described as:

"...gives money to organizations seeking to help the environment, actively employs programs that reduce its carbon footprint, buys network equipment from 'green' equipment vendors."

Paying more than just lip service, 41% (for services) and 45% (for devices) of the 1,000+ respondents indicated that



### Commercial Market

they'd be significantly or somewhat more likely to do so. Younger consumers showed a greater willingness to pursue "eco-groovy" mobile activities than older ones.

The service providers first to connect with environmentally conscious businesses and consumer subscribers will have an edge in this growing trend. Additional education remains necessary to communicate issues surrounding battery disposal and the accumulation of e-waste.

"If consumers are simply unaware of the environmental issues surrounding mobile devices and services," Orr adds, "then the industry should increase its efforts to get the message across. Some other verticals—the inkjet print industry, for example—are more proactive in motivating consumers to help. And other ABI Research studies have found little motivation among handset vendors, except the two or three largest, to offer 'green' mobile device product lines."

**Mobile Computing** and Consumer **Electronics Devices** to Drive GPS Growth

Although cellular hand-sets will continue to dominate shipments of devices with integrated GPS, the next growth spurt will come from mobile consumer electronics (CE) and mobile computing applications, reports In-Stat. Mobile computing and CE

devices will comprise over 100 million units in 2013.

"With growing attach rates and market maturity, GPS chipset providers must carefully evaluate which technologies to integrate into single chip solutions," says Jim McGregor, In-Stat's chief technology strategist.

Recent research by In-Stat found the following:

- Although the number of devices shipping with integrated GPS is increasing, the attach rates and the devices shipments have been hampered by the faltering economy.
- By 2012, there will be more CE devices with integrated GPS shipping than there are stand alone personal navigation devices.
- Mobile computing holds a lot of promise for GPS with 26 million GPS enabled units shipping in 2013, but there are barriers. In the netbook segment, for example, cost, integrating yet another antenna, only one mini-card slot will inhibit adoption.
- CPUs must be integrated (ARM, x86, Mips, etc.) to manage the host processor load.
- Infrastructure radios (802.11, WiMAX, LTE, etc.) are likely candidates for integration.
- The research, "GPS—'Locating' Its Way into Mobile Devices," covers the worldwide market for GPS chipsets and end products. It includes:
- Total Available Market and GPS attach rate forecasts for mobile CE and mobile computing through 2013.
- GPS chipset unit and revenue forecasts through 2013.
- GPS supplier breakdowns.
- Analysis of device OEM needs by market segment.



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### INDUSTRY NEWS

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- Harris Corp., an international communications and information technology company, has signed a definitive agreement to acquire the Tyco Electronics Wireless **Systems** business (formerly known as M/A-COM), an established provider of mission-critical wireless communications systems for law enforcement, fire and rescue, and public service organizations. Tyco Electronics Wireless Systems, a business segment of Tyco Electronics Ltd., was formed in 1999 and grew through the acquisition of ComNet Ericsson in 2001 to create Tyco Electronics Wireless Systems (Wireless Systems). Wireless Systems will be combined with the Harris RF Communications business segment, creating a dynamic new organization that will provide end-to-end wireless network solutions to the growing \$9 B global land mobile radio systems market. Under the definitive agreement, Harris will purchase the Wireless Systems assets of Tyco Electronics for \$675 M in cash, subject to post-closing adjustments.
- Microsemi Corp., a manufacturer of high performance analog mixed signal integrated circuits and high reliability semiconductors, and Endwave Corp., a provider of high frequency RF solutions for mobile communications markets, announced that Microsemi has acquired Endwave's defense electronics and security (D&S) business. Microsemi intends to combine Endwave's high frequency product portfolio with its own, creating one of the leading high reliability RF product offerings in the market today and covering the technology spectrum up to 100 GHz. Under the terms of the agreement, Microsemi is acquiring the D&S assets for a total equity value of \$28 M in cash plus the assumption of specified liabilities. Microsemi expects the acquisition to be accretive immediately.
- Codan Ltd. has announced a strategic expansion of its satellite communications business, acquiring Pennsylvania-based Locus Microwave Inc. Locus is a specialist microwave technology company based in State College, PA, primarily focused on the design, manufacture and supply of microwave radio products for satellite communications. Under Codan's ownership, Locus will remain a US-based business with its design, manufacturing and sales led by the company's founders and current executive team comprising Jim Dixon, Gary McGovern and Dana Wilt. The acquisition will enable Codan to establish closer contact with the North American Satellite market with the addition of Locus's product development and manufacturing base in State College.
- Superconductor Technologies Inc. (STI), a provider of advanced wireless solutions, innovative adaptive filtering and world class cryogenic products for commercial and government applications, will be participating with a major wireless original equipment manufacturer (OEM)

### AROUND THE CIRCUIT

in a long-term evolution (LTE) field trial with a tier-one US wireless operator for its new 700 MHz network. The trial is scheduled to be completed in the fourth quarter of 2009.

- Centellax Inc., a manufacturer of high performance, low cost test equipment, announced the opening of its first international sales office in Shenzhen, China, as well as the expansion of its international sales team to meet the growing demand from their customers. Centellax made the decision to open an office in China because of an increase of business opportunities in the region.
- Asylum Research's wholly owned UK subsidiary has moved and expanded its offices. **Asylum Research UK** opened for business nearly three years ago and its successful growth has led to the need for more office space to accommodate staff and demonstration equipment, including the new Cypher<sup>TM</sup> AFM. The new office is located in Bicester, Oxfordshire.
- Aeroflex announced support for new NXDN radios being developed for the land mobile radio market. As a member of the NXDN<sup>TM</sup> Forum, Aeroflex is leading the way with new test features that aid in the research and development of this exciting new radio technology.
- Texas Instruments Inc. (TI) announced the company's strong endorsement of the ZigBee Alliance's recent announcement to integrate Internet Protocol (IP) and open standards. The plan to incorporate global IT standards from the Internet Engineering Task Force (IETF) will allow continued growth of smart grid applications beyond the smart meter with the proven ZigBee Smart Energy public application profile.
- Agilent Technologies Inc. introduced a new option—arbitrary load impedance X-parameters—for its PNA-X Nonlinear Vector Network Analyzer. The option, when used in conjunction with Maury Microwave tuners and software, enables the capability to accurately measure and simulate nonlinear component behavior at all load impedances. The result is the highest level of insight into nonlinear DUT behavior, making the NVNA capability especially useful for scientists researching new RF technologies and engineers involved in designing today's high performance active devices.
- AWR, an innovation leader in high frequency electronic design automation (EDA), announced that users of AWR's Microwave Office design software now have access to XML library data for a broad array of microwave amplifiers from TriQuint Semiconductor Inc.'s San Jose design center (formerly WJ Communications). The devices include packaged gain-blocks, field effect transistors (FET) and heterojunction bipolar transistor (HBT) amplifiers. The library provides measurement-based models and footprints used for printed circuit board (PCB) and module layouts. It is available to users

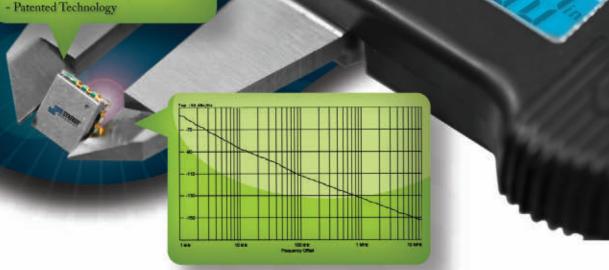


Model	Model Frequency Range ( MHz )		DC Bias VDC @ I [Typ.]	Phase Noise @ 10 kHz (dBc/Hz) [Typ]	Size (Inch)	
DCO Series					M	
DCO1198-8	1198.4 - 1198.7	0.5 - 7.5	+8 @ 30 mA	-116	wiew/	
DC0170340-5	1700 - 3400	0.5 - 24	+5 @ 24 mA	-90	Wideband Models	
DCO200400-5 DCO200400-3	2000 - 4000	0.5 - 18	+5 @ 35 mA +3 @ 35 mA	-90 -89	Models 0.3 x o	
DCO300600-5 DCO300600-3	3000 - 6000	0.5 - 18	+5 @ 35 mA +3 @ 35 mA	-80 -78	0.3 x 0.3 x 0.1	
DCO400800-5 DCO400800-3	4000 - 8000	0.5 - 18	+5 @ 35 mA +3 @ 35 mA	-78 -76	0.3 x 0.3 x 0.1	
DCO432493-5 DCO432493-3	4325 - 4950	0.5 - 11	+5 @ 17 mA +3 @ 17 mA	-88 -86	0.3 x 0.3 x 0.1	
DCO473542-5 DCO473542-3	4730 - 5420	0.5 - 22	+5 @ 20 mA +3 @ 20 mA	-88 -86	0.3 × 0.3 × 0.1	
DCO490517-5 DCO490517-3	4900 - 5175	0.5 - 5	+5 @ 22 mA +3 @ 22 mA	-88 -86	0.3 x 0.3 x 0.1	
DCO495550-5 DCO495550-3	4950 - 5500	0.5 - 12	+5 @ 22 mA +3 @ 22 mA	-87 -85	0.3 x 0.3 x 0.1	
DCO608634-5 DCO608634-3	6080 - 6340	0.5 - 5	+5 @ 22 mA +3 @ 22 mA	-86 -84	0.3 x 0.3 x 0.1	
DCO615712-5 DCO615712-3	6150 - 7120	0.5 - 18	+5 @ 22 mA +3 @ 22 mA	-85 -83	0.3 x 0.3 x 0.1	
DXO Series			to an wear of the first of the first	25570		
DXO810900-5 DXO810900-3	8100 - 8800	0.5 - 16	+5 @ 22 mA +3 @ 22 mA	-82 -80	0.3 x 0.3 x 0.1	
DXO900965-5 DXO900965-3	9000 - 9650	0.5 - 16	+5 @ 22 mA +3 @ 22 mA	-80 -78	0.3 x 0.3 x 0.1	

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### AROUND THE CIRCUIT

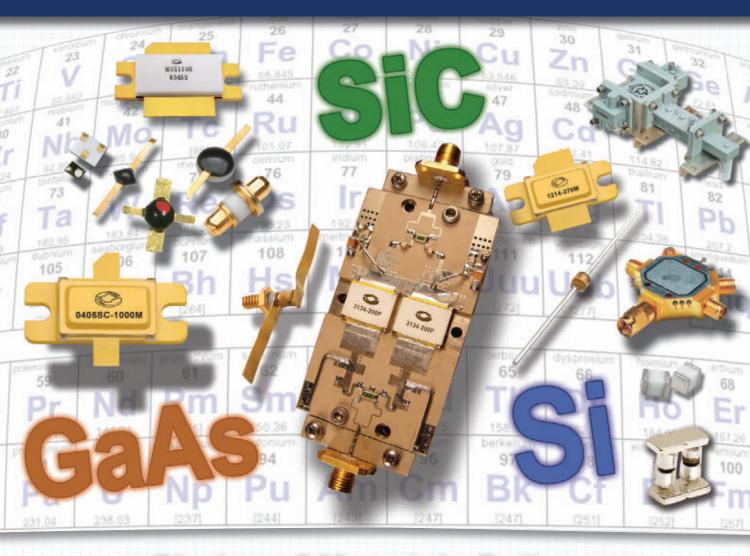
of AWR's Microwave Office software through the XML library link accessible from the software.

- Metelics Inc., Sunnyvale, CA, was named the Discrete Semiconductor Commodity Supplier of the Year 2009 by Rockwell Collins. The award was presented during the company's Annual Supplier Conference. The Supplier of the Year award is an acknowledgment of significant contributions made during the year by suppliers and is based upon quality, delivery, total cost of ownership, lead time and customer service.
- Teledyne Storm Products' Microwave Group recently obtained AS9100(B) certification. As an AS9100 registered company, Teledyne Storm—Microwave's quality management system meets not only ISO 9001 standards, but also the additional standards formulated by the International Aerospace Quality Group (IAQG) to specifically address specialized requirements of the aviation, space and defense industries. Teledyne Storm Products—Microwave provides high performance interconnect solutions to domestic and international defense/aerospace, telecommunications, and test & measurement markets.
- Electronic Assembly Manufacturing Inc. (EAM), an RF/microwave coaxial cable assembly supplier, has recently announced the receipt of its ISO 9001:2000 certification. The certificate of registration assures adherence to the BS EN ISO 9001:2000 standard as it applies to the manufacture of standard and custom cable assemblies, and related products for military, medical and commercial applications. The certification was granted through IMS International, which has been improving and enhancing the technical excellence of its clients since 1989.
- In an effort to reduce the company's carbon footprint, use less energy and water, and significantly increase efficiencies, Jazz Semiconductor Inc., a Tower Group company, and leading Orange County chipmaker, is conducting an ongoing efficiency overhaul. To be more energy efficient in the operation of its globally competitive 24/7 fabrication facility, the company has already instituted new technology and practices that have resulted in a savings of more than 7.5 million kilowatt hours per year, resulting in the avoidance of 5,386 tons of greenhouse gas (GHG) emissions—the equivalent of taking 986 cars off the road.
- The 17<sup>th</sup> Annual SMT Vision Award has announced **LPKF Laser & Electronics** as the winner for innovation and excellence in products and service, within the Assembly Tools category. The ProtoLaser U is a UV laser for depaneling of flex, rigid and rigid-flex material.
- **L-com**, a leader in the manufacture of wired and wireless connectivity solutions, announced that it is the recipient of the prestigious 2008 Boeing Performance Excellence Award (BPEA).

#### CONTRACTS

- XIO Strategies Inc., a supply chain management and communications consulting firm, announced that it has been awarded a subcontract by Northrop Grumman to provide active RFID consulting services to the US Department of Defense under their RFID III contract, a multiple award, indefinite delivery/indefinite quantity contract with a \$429 M ceiling available for task orders.
- Cobham plc has received a contract modification from the US Navy to produce 51 ALQ-99 Low Band Transmitters (LBT) and provide spare parts for US\$72 M. This contract, initially valued at US\$37 M, was previously announced by the company in October 2008.
- Micronetics Inc. announced that its New Jersey-based subsidiary, Microwave Concepts (Micro-Con), has received advanced funding of approximately \$5 M from a major defense OEM for highly integrated microwave subassemblies. These subassemblies are used as part of a complex jamming system. In addition to this advanced funding, full funding of production quantities is expected within 90 days. The anticipated period of performance on this program is approximately 24 months.
- Radio Waves Inc. has announced that a North American wireless communications carrier has selected its high quality microwave antenna systems. Both Radio Waves SP standard performance and HP high performance products as well as Radio Waves newest UHP ultra high performance models will be utilized by the carrier. These microwave antennas will support the carrier's geographical expansion and network capacity enhancement. Radio Waves was selected for this expansion due to its ability to deliver high quality antennas made in the US at its Billerica, MA global headquarters more rapidly than other manufacturers.
- Lommunications & Power Industries Inc. (CPI) has been awarded approximately \$3.1 M by Sierra Nevada Corp. to supply integrated microwave assemblies and transmitters for use in the US Navy's AN/APN-245 Automatic Carrier Landing System (ACLS) Beacon. CPI, a subsidiary of CPI International Inc. (CPII), is a provider of microwave, radio frequency, power and control solutions for critical defense, communications, medical, scientific and other applications.
- Comtech Telecommunications Corp. announced that its New York-based subsidiary, Comtech PST Corp., received a \$2 M contract for broadband, solid-state, high power RF microwave amplifier system spares from an international original equipment manufacturer (OEM). These spares are being provided in support of previously fielded communications jamming high power amplifier systems for the electronic warfare market.
- RF Micro Devices Inc. (RFMD), a leader in the design and manufacture of high performance semiconductor components, announced that the company has been selected by a smartphone manufacturer to supply its RF2815 GPS LNA module for use in a soon to be released CDMA smartphone. This new smartphone is

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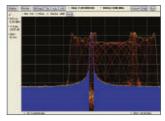
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expected to launch in the second half of calendar 2009 in North America. The feature-rich, dual-band CDMA device will be manufactured by the leading Taiwan-based smartphone manufacturer and will feature a leading open source mobile operating system.

### FINANCIAL NEWS

■ WiSpry Inc., a leader in programmable RF semiconductor products for the wireless industry, announced its first closing for a Series C financing of \$10 M dollars. The round was led by a new investor in the company, Paladin Capital Group, which is also gaining a seat on WiSpry's board of directors, as well as existing investors L-Capital Partners and Blue Print Ventures. A new strategic investor, MuRata Manufacturing Co. Ltd., and additional existing investors American River Ventures, In-Q-Tel, Tech Coast Angels and Shepherd Ventures also participated. A second close of the Series C, anticipated to be at least \$5 M, is expected to be completed this summer.

### **PERSONNEL**

■ Park Electrochemical Corp. announced the appointment of **Marty Kendrick** as Vice President of Operations. In this new position, Kendrick will be responsible for the Park's operations in Asia, Europe and North America with the exception of the company's advanced composite materials operation located in Waterbury, CT. Most recently, Kendrick was Vice President of North American Operations of Park with responsibility for Park's Neltec Inc., Nelco Products Inc., Park Aircraft Technologies Corp. and Park Aerospace Structures Corp. subsidiaries. The company also announced the appointment of **Tom Pursch** as the President of the company's aircraft composite parts subsidiary in Lynnwood, WA and the company's aircraft composite materials and technologies subsidiary. Since joining the company in October of 2008, Pursch was President of Park's Nelco Products Inc. electronics materials subsidiary located in Fullerton, CA.

■ Peregrine Semiconductor Corp., a supplier of high performance RF CMOS and mixed-signal



communications ICs, announced that it has appointed **Jay Biskupski** to the role of chief financial offer, responsible for the company's financial and site services organizations. Prior to joining Peregrine, Biskupski served as chief financial officer of publicly traded Xantrex Technology Inc.

■ Emerson & Cuming Microwave Products Inc. announced the appointment of **Devin Sullivan** as RFID Program Manager. This addition comes as a prelude to the launch of MetalTag<sup>TM</sup> Impact, a ruggedized addition to the MetalTag product line. In response to the growing RFID industry, and the need for Read-On-Metal and Liquid solutions, the company is expanding its presence

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by adding a dedicated individual to focus on the need for its Read-On-Metal, RFID transponder product line. Sullivan will be responsible for sales of products into the RFID sales channel. His responsibilities will include identifying trade partners, setting market pricing and making recommendations for product promotion, and related marketing support.

■ MI Technologies announced the appointment of Jan Kendall as Director, Product Marketing, and Bill





Bill Hawkins

Hawkins, Strategic Manager. Account In the new position of Director, Product Marketing, Kendall is responsible for ensuring the company's product management customer

efforts align with overall strategies and market trends by providing focused product marketing and marketing communications management. Hawkins comes to MI Technologies with more than 17 years sales experience. Prior to joining the company, Hawkins served as a Field Sales Engineer for Agilent Technologies where he coordinated all facets of sales of multimillion-dollar testing solutions to the semiconductor industry.

### REP APPOINTMENTS

- **Reactel Inc.**, a manufacturer of RF and microwave filters, multiplexers, switched filter banks and sub-assemblies to the commercial, military, industrial and medical industries, announced the appointment of WES-K as the company's representative in Southern California. For more information about WES-K, visit www.wes-k.com or telephone Randy Salmont at (661) 714-5414.
- International Manufacturing Services Inc. (IMS), a manufacturer and supplier of high quality thick film resistors, terminations, attenuators, thermal management products, planar dividers and planar filters to the electronics industry, announced the appointment of Joe Ruvolo of **K&R Engineering** as its Northern New Jersey sales representative. Ruvolo has more than twenty years' experience in the electronics industry working in purchasing and sales. He worked for ITT for seven years before joining K&R Engineering of Succasunna, NJ. He has been with K&R Engineering since 1995, covering Northern New Jersey. Contact Joe Ruvolo, K&R Engineering, 275 Route 10 East, Suite 220-285, Succasunna, NJ 07876; e-mail: joe@kreng.com; ph: (973) 584-5235.
- Precision Connector Inc., a manufacturer of precision coaxial connectors, has appointed RF Connections LLC as Sales Representative in the Southeast United States. RF Connections will cover the states of Florida, Georgia, North Carolina, South Carolina, Tennessee, Mississippi and Alabama.



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Simply calling the ZVA-183X and ZVA-213X "wideband" amplifiers doesn't begin to describe them. The super ultra wideband ZVA-183X amplifier operates from 0.7 to 18.0 GHz while the ZVA-213X amplifier covers even more "spectral ground," with a range of 0.8 to 21.0 GHz. Both super ultra wideband amplifiers deliver +24 dBm typical output power at 1 dB compression by merit of 26 dB typical small-signal gain with ±1 dB typical gain flatness. Both provide wide dynamic range along with the bandwidth, with typical noise figure of 3 dB and typical IP3 of +33 dBm. These versatile amplifiers are ideal for broadband commercial and military applications, from radar systems to test equipment. The ZVA-183X and ZVA-213X amplifiers are unconditionally stable. In fact, they are so rugged, they can even withstand load mismatches as severe as an open or short circuit at full 1dB compression output power.

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# BACKFIRE DISK-ON-ROD ANTENNA FOR LONGRANGE POINT-TO-POINT COMMUNICATIONS

This article describes a handy design method for a long backfire antenna, called for short a backfire antenna (BFA). It consists of the following basic elements: A feed F (dipole or assembly of crossed dipoles), a surface wave (SW) structure S (dipole array, metal disk-on-rod, dielectric rod, dielectric-covered metal rod or endfire dipole array), and two parallel disk reflectors: A small or feed R<sub>1</sub> and a big or surface-wave reflector R<sub>2</sub>. The SW structure in use is a metal disk-on-rod (cigar) construction, although the same design method can be applied to backfire antennas with other types of SW rods. The presented design scheme is based on simple empirical equations, graphs and tables, and is validated by measurements of BFA prototypes with disk-on-rod structures, two to four wavelengths long, though by a simple extrapolation the scheme can be extended to antennas up to six wavelengths long. The gain range from 17 to 25 dB is covered by 2 to 5λ backfire antennas operating at the lower microwave WLAN, ISM, GPS and other bands between 1.5 and 3.5 GHz.

As a specific case, a  $4\lambda$  backfire disk-on-rod antenna for the WLAN/ISM frequency band 2.4 to 2.5 GHz was designed, built and studied experimentally. To obtain a maximum gain of approximately 24 dBi, the big antenna reflector was made with a plane-conical profile. This

BFA was contrasted to a commercial parabolic antenna of similar gain and dimensions, and it was found that for the chosen frequency band and required gain the well optimized BFA is a more compact and effective radiator.

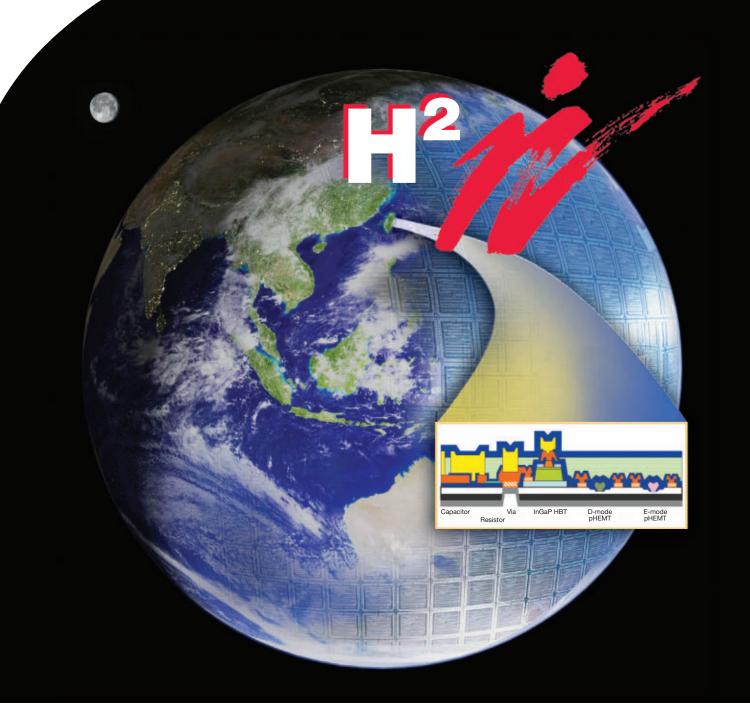
The backfire antenna (BFA) was created by H.W. Ehrenspeck and his associates at the Air Force Cambridge Research Center, Bedford, MA, in 1959.1,5 Because of its compact and robust construction and very good radiation performance, this antenna has been used in various wireless systems, mostly military, earth and spacecraft. A BFA comprises an axial surface wave (SW) structure typically 2 to 4 wavelengths long. If the BFA is equal or shorter than one wavelength, the SW structure becomes unnecessary and the antenna is converted into a short backfire antenna (SBFA). The SBFA is very popular today, mainly in satellite communications and WLAN links. It has a medium directivity and gain of approximately 12 to 16 dB. For long-range point-to-point applications, say WLAN, WISP and satellite links, a bigger

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	Parameter	Spec
	Beta	75
HBT	Ft	30 GHz
	Fmax	110 GHz
	BVceo	19 V
	Gm_Peak	500 mS/mm
I	Idss	0.01 uA/mm
M	BVdg	21 V
e-pHEMT	Vth	0.35 V
ŀď	Fmin	0.44 dB
ė	Ft	30 GHz
	Fmax	90 GHz
	Gm_Peak	330 mS/mm
r .	Idss	230 mA/mm
Ę	BVdg	20 V
	Vp	-1.0 V
d-pHEMT	Ron	2.0 Ohm-mm
<del> </del>	Fmin	0.31 dB
	Ft	30 GHz
	Fmax	70 GHz

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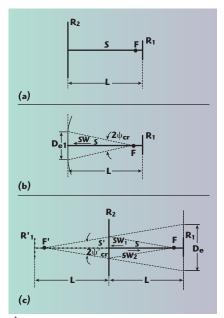


gain from 17 to 25 dB is desired, and the BFA along with the parabolic dish antenna (PDA) and antenna dipole arrays proved to be very good choices. For comparison, a 4λ long S-band BFA, with a Yagi-type SW structure, is almost comparable in gain to an array of 16 (4 x 4) Yagi antennas, each of them comprised of nine elements.<sup>6</sup> Both antennas, the BFA and the Yagi array, have a gain of approximately 23.5 dB, but while the BFA has sidelobe levels more than 20 dB below the main lobe, the Yagi array sidelobes are much higher (-11 dB). Furthermore, the BFA is more compact, has a simpler feed system and reduced complexity.

The BFA geometry is illustrated in **Figure 1**. It consists of the following basic elements: A feed F (dipole or assembly of crossed dipoles), SW rod S (dipole array, metal disk-on-rod, dielectric rod, dielectric-covered metal rod or endfire dipole array), and two parallel disk reflectors: A small or feed reflector  $R_1$  and a big or surface-wave reflector  $R_2$ . In the figure, the antenna length L is the distance between  $R_1$  and  $R_2$ .

The dipole feed location between the two reflectors is of great importance for the BFA radiation and input characteristics. The antenna works normally only for two feed locations: Superior, if the feed F is near the small reflector R<sub>1</sub>, and inferior, if F is near the big reflector R<sub>2</sub>. In both cases, the distance between the feed and respective reflector is  $\lambda/4$ . Other feed location points along the SW structure are not recommended. In this article, only a BFA with superior feed location has been considered, since it has approximately 3 to 4 dB higher gain, compared to the BFA with inferior feed location.<sup>6,7</sup>

The simplified radiation mechanism of a BFA has been described in early references  $^{1-5}$  and can be summarized as follows. A larger amount of the spherical wave radiated from F is transformed by S into a traveling wave, aimed at the big reflector  $R_2$ . The feed or launching efficiency is measured as the ratio between the power carried by the surface wave and the total radiated power. Thus, the feed efficiency is considered big if the power coupled to the spherical wave is small compared to power tied to



▲ Fig. 1 Simplified operation of the back-fire antenna: (a) geometry, (b) end-fire antenna model and (c) image model.

the surface wave. If R<sub>2</sub> is not present, the assembly R<sub>1</sub>-F-S acts as an endfire antenna (EFA) with an effective aperture of diameter Del radiating in the axial direction. The big reflector R<sub>2</sub> turns back the surface wave towards the BFA virtual aperture, where it is partially reflected by the small reflector  $R_1$ . Thus, according to this simple image approach, R<sub>2</sub> forces the surface wave to traverse the physical antenna length L at least twice. As a result, the BFA operates as an EFA of effective length equal to double the physical length, or  $L_e = 2$  L. Consistent with the Hansen-Woodyard (HW) condition,<sup>5,8</sup> the maximum gain of the EFA is proportional to the length of its surface wave structure, provided that the SW phase velocity v is adjusted to its optimum value corresponding to the effective length L<sub>e</sub>. This implies that the BFA design may have an effective radiation aperture of diameter D<sub>e</sub> much larger than the corresponding endfire aperture D<sub>e1</sub>. The BFA with an optimum SW phase velocity v ( $L_e$ = 2 L) should yield as a minimum four times (6 dB) higher gain than the EFA having an optimum SW phase velocity v(L).

More rigorous theoretical and further experimental studies of the BFA<sup>6,8</sup> have revealed that the successive SW reflections (and diffractions) by the small and big reflectors produce more complicated standing-wave field modes between them. The best BFA

gain performance is obtained if the antenna physical length is approximately equal to a multiple of the freespace half wavelength. Our experiments with backfire antennas have shown that  $L_{\rm e}$  equal to 6L is a better choice in finding the optimum surface wave velocity. Such approximation of the inner standing wave process corresponds to six forward and backward travels along the surface wave structure or to a triple wave reflection from the big reflector.

#### RELATIONS BETWEEN SURFACE-WAVE PHASE VELOCITY AND ANTENNA LENGTH

Based on the experimental and computer phase visualization of the EFA, it is assumed  $^{2,6,8}$  that at its end plane, in the limits of so-called critical angle  $\Psi_c$  (or if  $\Psi \leq \Psi_c$ ), the SW has a quasi-plane phase front and effective radiation aperture of diameter  $D_{e1}$ . Otherwise, if  $\Psi > \Psi_{cr}$ , the phase surface wave front looks like a spherical one. This deviation from the plane SW is due to the primary feed field radiated directly as a free-space spherical wave. The critical angle depends on the SW phase velocity v and is approximately found by  $^{2,4}$ 

$$\tan \Psi_{\rm cr} = \sqrt{\xi_s^2(L/\lambda) - 1} \tag{1}$$

where

$$\xi_{s}(L/\lambda) = \frac{c}{v(L/\lambda)} = 1 + 0.23 \frac{\lambda}{L} \qquad (2)$$

Here,  $v(L/\lambda)$  is the SW velocity delay factor as a function of the length expressed in wavelengths. Equation 2 is derived from the simplified singleimage model of BFA and the Hansen-Woodyard optimum phase condition for a surface wave rod with an effective length  $L_{\rm e}$  = 2 L; c is the free-space wave velocity.<sup>2,5</sup> The ideal image model is introduced<sup>2</sup> for the case of a big reflector of infinite dimension. The multiple reflection and diffraction effects on both reflectors and the feed dipole should also be taken into account. The studies have shown<sup>6-8</sup> that the simple image model and Equation 2 are not suitable for making a correct BFA design, and thus, a bigger L<sub>e</sub> should be chosen.

Here, an effective BFA length that is equal to six physical lengths is supposed, that is  $L_{\rm e}$  = 6 L. This assump-



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P1dB*	600 mW/mm
Ron	1 Ohm-mm
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Thin Film Resistor	50 ohm/sq
MIM Capacitor	600 pF/mm2

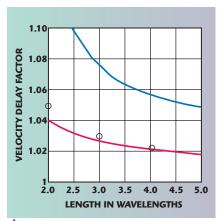
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▲ Fig. 2 Phase velocity factor vs. length for different number of reflections from the big reflector.

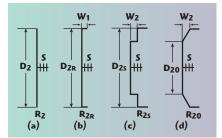


Fig. 3 Big reflector profiles.

tion corresponds to six wave travels along the physical antenna length or three reflections from the big reflector. For  $\rm L_e$  = 6 L, Equation 2 is modified to

$$\xi_s(L/\lambda) = 1 + 0.08 \frac{\lambda}{L} \tag{3}$$

Figure 2 illustrates the change of velocity delay factor  $\xi_S$  as a function of the BFA antenna physical length L in wavelengths, calculated for an effective length L<sub>e</sub> equal to 2L (blue line or Equation 2) and 6L (red line or Equation 3). Three measured values<sup>3,7</sup> of the SW velocity delay factor versus the physical antenna length expressed in wavelengths, or= Ψ<sub>S</sub> (L/λ), for an optimally designed disk-on-rod BFA SW rod: Ψ<sub>S</sub> =1.05, 1.03 and 1.02 for L/λ = 2, 3 and 4, are shown with circles. These points agree well with Equation 3 and the corresponding red line.

As mentioned in the previous section, the BFA can be considered as a parallel-plane resonator antenna with a standing surface wave field excited inside. In the antenna aperture that is partially closed by the small reflector  $R_1$  two basic wave phenomena take place: Multiple partial reflections

from  $R_1$  and multiple intensive radiations from the open aperture area. The length of such radiating cavity can be expressed as

$$L = n \frac{\lambda_s}{2} + \Delta L$$
, for  $n = 1, 2, 3...$ , (4)

where  $\lambda_S = v/f$  is the surface-wave wavelength,  $\Delta L$  is the length correction due to the radiation, n is a real integer called standing-wave number and f is the design (resonance) frequency.

On the other hand, the BFA studies have shown that its length L takes discrete resonance values, equal to n free-space half wavelengths, or

$$L = n \frac{\lambda}{2} \tag{5}$$

where n has the same integral values as in Equation 4.

In practice, the standing-wave number n usually takes values from 4 to 8 to which correspond the next five values of  $L/\lambda = 2, 2.5, 3, 3.5$  and 4. For n = 1, the BFA is just a half-wavelength long and becomes a short backfire antenna or SBFA. In this case, the SW structure is missing.

The length correction  $\Delta L$  in Equation 4 is found by the equality of Equations 4 and 5, or

$$\Delta \mathbf{L} = n \frac{\lambda}{2} \left( 1 - \frac{1}{\xi_{s}(\mathbf{L} / \lambda)} \right) \tag{6}$$

From Equations 3 and 5, the backfire antenna Equation 6 becomes

$$\Delta L = L \left( 1 - \frac{1}{1 + 0.08 \frac{L}{\lambda}} \right) \tag{7}$$

 $\Delta L$  is small compared to the BFA length L. For instance, if L/ $\lambda$  varies from 2 to 4, the ratio  $\Delta L$  ranges from 0.038 to 0.02.

#### **BIG REFLECTOR PROFILES**

Four different profiles of the big reflector are shown in **Figure 3**: (a) disk reflector  $R_2$  of diameter  $D_2$ , (b) rimmed disk reflector  $R_{2R}$  of diameter  $D_{2R}$ , (c) rimmed stepped-corrected disk reflector  $R_{2S}$  of diameter  $D_{2S}$  and (d) rimmed conically-corrected disk reflector  $R_{2C}$  of diameter  $D_{2S}$ . The effective diameter  $D_{e1}$  of the EFA effective aperture area depends on the

antenna length L and the critical angle  $\Psi_{\rm cr}$ , or

$$D_{e1} = 2L \tan \Psi_{cr} \tag{8}$$

which, having in mind Equation 4, can be approximately given as a function of  $L/\lambda$  as

$$D_{e1} = 1.4 \, \lambda \sqrt{\frac{L}{\lambda}} \tag{9}$$

In the image model, the big reflector of BFA lays in the EFA effective aperture plane and its minimum diameter  $D_2$  is equal to the constant-phase effective aperture, or  $D_2 = D_{e1}$ .

With the increase of the disk diameter, so that  $\Psi > \Psi_{cr}$ , the phase front becomes spherical and a quadratic phase distortion on the reflector plane occurs. If the tolerable phase distortion at the disk edge is  $\pi/2$ , the disk diameter  $D_2$  set equal to  $D_e$  will be bigger than  $D_{e1}$ , and can be found roughly as<sup>2</sup>

$$D_2 = 2 \lambda \sqrt{\frac{L}{\lambda}}$$
 (10)

The disk reflector  $R_{2R}$  with a quarter-wavelength rim  $(w_1 = 0.25 \ \lambda)$  has a diameter  $D_{2R}$  equal to that of reflector  $R_2$ , that is  $D_{2R} = D_2$ . The rim reduces the sidelobe and backlobe levels, and results in an antenna gain increase.

The step-phase correction in reflector  $R_{2S}$  and the conical-phase correction in reflector  $R_{2C}$  allow further enlargement of reflector diameter and antenna gain. These two reflectors are normally used for antenna lengths equal or greater than  $3\lambda$ . The inner or disk area diameter  $D_{20}$ , and the outer (peripheral) diameters  $D_{2S}$  and  $D_{2C}$  of the two reflectors  $R_{2S}$  and  $R_{2C}$ , respectively, are given by  $^{2,6}$ 

$$D_{20} = (1.9 \div 2.0) \lambda \sqrt{L / \lambda}$$
 (11)

$$D_{2C} = D_{2S} = (2.9 \div 3)\lambda\sqrt{L/\lambda}$$
 (12)

The step width  $w_2$  and rim width  $w_1$  are also chosen equal for both reflectors, or

$$w_1 = w_2 = 0.25\lambda$$
 (13)

Though the BFA with large reflectors  $R_{2S}$  and  $R_{2C}$  are equal in diameter, the phase-correction in the latter is slightly better and the antenna gain is a bit higher.<sup>2</sup> Naturally, the compound plane-parabolic reflector will



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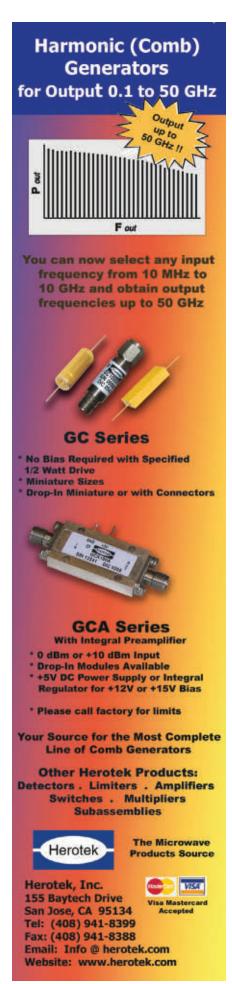
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have the best phase correction, but this would require more complex fabrication technology.

Note: The equations and experimental results for the antenna parameters presented next are applicable for backfire antennas having either type of big reflectors:  $R_{2R}$  or  $R_{2C}$ . The study concentrated on them only, because the BFA antenna with reflector R<sub>2B</sub> is of simpler construction and has fairly low side and back lobes, while the BFA antenna with reflector  $R_{2C}$ produces higher gain, compared to the other antenna's reflectors.

#### **SMALL REFLECTORS**

The small reflector  $R_1$  in all BFA antennas is usually a simple thin disk with a diameter  $D_1$ . It has a great importance on the SW launch process and aperture field distribution. For very small values of  $D_1$ , the BFA essentially radiates as an EFA. For a constant big reflector diameter and antenna length, the small reflector has an optimum diameter for which the BFA antenna reaches a maximum gain. If  $D_1$  is bigger than its optimum size, the antenna gain reduces, and for values of  $D_1$  close to the big reflector diameter, the antenna practically does not radiate as it is transformed into a very high quality-factor resonator. The experimental study has proved that, for all types of big reflector, the BFA small reflector optimum diameter can be found by<sup>7</sup>

$$D_1 = (0.25 \div 0.45)\lambda\sqrt{L/\lambda} \tag{14}$$

With the BFA length increasing, both the big and the small reflectors grow in diameter according to the quadratic relations in Equations 10 to 12 and 14. The minimum and maximum values in Equations 11, 12 and 14 define the optimum ranges of diameters  $D_{20}$ ,  $D_{2S}$  (or  $D_{2C}$ ) and  $D_1$  in different practical BFA designs. They have been validated for BFA lengths from  $2\lambda$  to  $4\lambda$ . 1-4,6,7

#### **DIRECTIVE GAIN AND BEAM WIDTH**

In what follows, the empirically obtained equations for the directive gain G of EFA and BFA as a function of  $L/\lambda$  (the directive gain or directivity will be simply called the gain) are listed.

#### **Gain of EFA**

This antenna should be designed according to the original HW phase condition, where  $L_e = L$  and the SW velocity  $v(L/\lambda)$  satisfies the equation  $\xi_{\rm S}({\rm L}/\lambda) = 1 + 0.46 \ \lambda/{\rm L}$ . Under this condition, the gain of a very long homogeneous EFA is proportional to  $L/\lambda$ , or<sup>5,8</sup>

$$G = 10 \log(7L / \lambda), dB$$
 (15)

If the design is based on the HW phase condition and the SW rod is tapered accordingly, the gain of the EFA for L between 3 and  $8\lambda$  is<sup>5,8</sup>

$$G = 10 \log(10L / \lambda), dB$$
 (16)

#### Gain of BFA

The BFA gain is much higher than the gain of EFA and can be found by the basic aperture antenna equation<sup>8,9</sup>

$$G = (4\pi / \lambda^2) A_e \eta_e \tag{17}$$

where  $A_e = \pi (D_e/2)^2$  is the effective aperture area, expressed by the effective aperture diameter D<sub>e</sub>. In decibel form, Equation 17 is given by

$$G = 20 \log(\pi D_e/\lambda) + 10 \log \eta_e, dB (18)$$

In Equation 18,  $D_e = D_{2R}$  for the rimmed disk reflector is calculated with Equation 10, and for a rimmed disk-conical reflector  $D_e = D_{2C}$ , by Equation 11;  $\eta_e$  is the radiation efficiency, which takes into account the field amplitude distribution in the BFA effective aperture.

Independently of the partial blockage by R<sub>1</sub>, the BFA has a relatively constant field distribution outside the blocked aperture area, which makes the aperture radiation efficiency too big. In accordance with the gain measurements,  $\eta_e$  may be set as  $\eta_e = 0.6$ to 0.8.

The average antenna beamwidth may be defined as  $B = \sqrt{B_E B_H}$ , in degrees, where  $B_E$  and  $B_H$  are the E-and H-plane -3 dB beamwidths. If the BFA has a phase-corrected big reflector  $R_{2C}$  its average beamwidth can be found approximately by<sup>6</sup>

$$B = 22\sqrt{\lambda/L}, \text{ deg}$$
 (19)

Knowing B, the BFA gain can be computed by the following empiric equation, valid for a moderately high gain aperture antenna<sup>8,9</sup>

$$G = 10 \log (33000 / B^2), dB$$
 (20)

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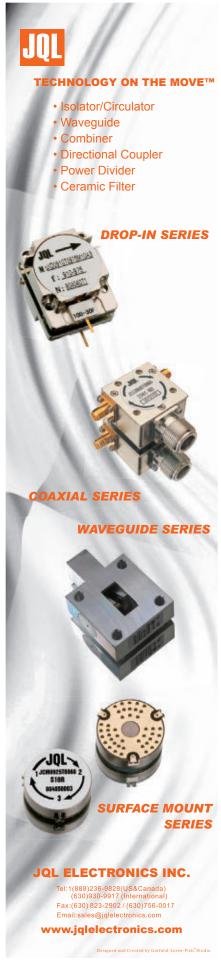
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Equation 19 is not valid for the BFA with a rimmed disk reflector  $R_{2R}$ , which for the same SW rod length has a much smaller effective aperture. Equation 19 was corrected as follows to match better the realistic beamwidth and gain values in the case of a BFA having a reflector  $R_{2R}$ 

$$B = 33\sqrt{\lambda} / L, deg$$
 (21)

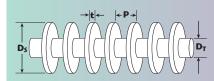
**Table 1** illustrates the gain property of BFA depending of the large reflector size and shape, and SW rod length. The gain values have been estimated by use of Equations 18 or 20 in the case of reflector  $R_{2C}$  or by Equations 18 or 21 and 20 for a BFA with reflector  $R_{2R}$ . From this table, it is evident that for all BFA lengths, the use of the plane-conical reflector  $R_{2C}$  leads to an approximately 3.5 dB higher gain, compared to a BFA with a plane reflector  $R_{2R}$ . On the other hand, if a gain of approximately 20 to 21 dB or less is needed, the more compact and simpler BFA having a reflector  $R_{2R}$  is to be preferred. For instance, the  $2\lambda$ -long BFA with reflector R<sub>2C</sub> has approximately the same gain as the  $4\lambda$ -long BFA with a reflector R<sub>2R</sub>, but the former is of more complex construction and occupies 1.5 times as much volume. The studies have shown that the more complex BFA with a phase-correcting reflector  $\rm R_{2C}$  (or  $\rm R_{2S})$  should be considered only when gain values equal or greater than 22 to 24 dB are required.

in fact disk-on-tube) structure (see *Figure 4*) are: DS or the outer diameter of the SW structure rings, DT or the inner rings' diameter (outer tube diameter), and P, the disk array period (inter-disk distance). They can be found by use of the known disk-on-metal rod design procedure. 9-12

The metal disk-on-rod SW structure, known also as disk-on-rod SW waveguide, usually consists of rings welded on a tube T, which serves also as an outer (shield) conductor of the feed rigid coaxial line. In a heavy-duty BFA, the disk-on-tube assembly can be replaced by a single-piece corrugated rod (tube).

Next, the design procedure of diskon-rod surface wave structure is summarized. For a given antenna length L and design wavelength  $\lambda$ , the phase delay factor  $\xi_S$  was calculated from Equation 3. In **Table 2** are some typical BFA values of  $\xi_S$  corresponding to different pairs of disk-on-rod dimensions  $\Delta D = D_S - D_T$  and P. The table was prepared on the basis of two classical references on the subject. <sup>10,11</sup> The thickness t of the disks (rings) is usually taken according to  $0.01\lambda \leq \tau \leq 0.02\lambda$ .

One of the possible ways of BFA



▲ Fig. 4 Sketch of the surface-wave discon-rod structure.

### DISK-ON-ROD (CIGAR) SURFACE-WAVE STRUCTURE

### Feed Location and Design

The phase velocity delay factor  $\xi_S$  (L/ $\lambda$ ) of the SW rod is found from Equation 3 or Figure 2 (red line). For a given  $\xi_S$  (L/ $\lambda$ ), the basic dimensions of the disk-on-rod (or

ESTIMATED GAIN OF A BFA WITH REFLECTOR $\rm R_{2R}$ OR $\rm R_{2C}$ FOR THREE ANTENNA LENGTHS								
BF antenna length in wavelengths	<b>2</b> λ	<b>3</b> λ	<b>4</b> λ					
Diameter of reflector $R_{2R}$ , $(m)$	0.35	0.42	0.49					
Diameter of reflector $R_{2c}$ , (m)	0.52	0.64	0.73					
Gain for reflector $R_{2R}$ , (dB), eqs. (18) or (21)/(20)	17.7/17.8	19.5/19.6	20.7/20.8					
Gain for reflector R <sub>2c</sub> , (dB),	21.2/21.3	23.0/23.1	24.2/24.4					

**TABLE I** 

TABLE II								
COMBINATIONS OF $\Delta_{\text{D}}/\lambda$ AND P/ $\lambda$ THAT MATCH SPECIFIC VALUES OF $\xi_{\text{S}}$								
$\Delta_{m{D}}/\Delta$	0.2	200	0.225		0.250		0.275	
Ρ/λ	0.125	0.250	0.125	0.250	0.125	0.250	0.125	0.250
ξ <sub>s</sub>	1.02	1.01	1.02	1.01	1.03	1.01	1.05	1.02

eqs. (18)/(20)

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IABLE III BACKFIRE AND PARABOLIC DISH ANTENNAS: COMPARATIVE DATA									
Antenna Data Antenna Brand	BFA (prototype)	PDA (commercial)							
Design frequency f, GHz, wavelength $\lambda$ , (m)	2.45/0.12245	2.45/0.12245							
Design gain G, (dB)	24	24							
Length L in wavelengths/in meters	4.0/0.49, eq. (5)	3.6/0.44							
SW velocity delay factor $\xi_s(L/\lambda)$	1.02, eq. (3)	No							
Diameter D <sub>20</sub> , (m)	0.6, eq. (11)	No							
Aperture diameter, m ( $\mathrm{D}_{\mathrm{2C}}$ in case of BFA)	0.73, eq. (12)	0.89							
Diameter D <sub>1</sub> , (m)	0.11, eq. (14)	No							
Step and rim widths $w_1 = w_2$ , (m)	0.31, eq. (13)	No							
Antenna cylindrical volume V <sub>a</sub> , (m <sup>3</sup> )	0.21	0.28							
Outer tube diameter $D_T$ (selected), $(m)$	0.012	No							
Period P (selected), (m)	0.015	No							
Diameter difference $\Delta_{\mathrm{D}}$ , (m), by Table II	0.024	No							
Outer ring diameter $D_S = \Delta_D + D_T$ , (m)	0.036	No							
Estimated gain, (dBi)	24.3, eq. (18)	-							
Measured gain, (dBi)	23.8	24							
Average beamwidth, (deg)	10.2	10							
Max. E-plane sidelobe, (dB)	-22	-23							
Max. H-plane sidelobe, (dB)	-26	-							
Backlobe level, (dB)	-30	-							
Linear polarization	V/H	V/H							
Aperture efficiency	0.75	0.55							
Maximum VSWR in 2.4 to 2.5 GHz band	1.5:1	1.5:1							
Minimum Gain, dBi in 2.4 to 2.5 GHz band	23	23.5							

TARIF III

feeding is by means of a dipole backed by a small reflector. All the results presented in this article have been obtained with BFA prototypes having the following feed configuration. An input coaxial-type connector is bonded at one side of a rigid feed coaxial line and fixed to the big reflector rear. The inner cylindrical conductor of the coaxial line is set along the antenna axis and is air-spaced from the outer tube conductor. On the opposite side, the feed coaxial line is short-circuited at the small reflector plane and the dipole feed F is connected to the coaxial line by means of a half-wave slot balun, known as a split coaxial line-dipole balun. This feed construction is a classical topic and can be found in many references.8,9

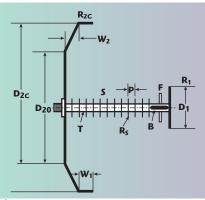


Fig. 5 Sketch of the BFA prototype constructed.

#### PRACTICAL BFA DESIGN AND STUDY

Based on the equations listed in this article, several backfire antennas with metal disk-on-tube SW struc-

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▲ Fig. 6 Photograph of the BFA prototype.

tures of different resonant lengths (L =  $2\lambda$ ,  $3\lambda$  and  $4\lambda$ ), tuned at the design frequency f = 2.5 GHz and working over the frequency band of 2.4 to 2.5 GHz, were built and examined experimentally. As an example, the BFA prototype that produced the largest gain is described. This is a  $4\lambda$ -long backfire antenna with a big planeconical reflector R<sub>2C</sub>. The sketch of this antenna is shown in *Figure 5* and a picture of the prototype is shown in Figure 6.

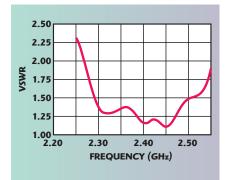


Fig. 7 Measured VSWR as a function of frequency.

Figure 7 illustrates the input match bandwidth of the experimental BFA antenna. Its dimensions, design and measured parameters are listed in **Table 3**. The equations used for obtaining the BFA table data are quoted in round brackets.

At the design frequency of 2.45 GHz, the VSWR curve has a bare minimum of about 1.1. The input frequency bandwidth is 11 or 8.5 percent at a VSWR level of 2.0 or 1.5, respectively. This band is more than double the whole WiFi/ISM spectrum that ranges from 2.4 to 2.5 GHz. For comparison, the basic antenna data of a commercial WLAN parabolic dish antenna (PDA), operating in the same frequency band and having similar gain and radiation patterns, Y3 is also listed. Compared to the BFA, the PDA is not as compact and has a 35 percent less radiation efficiency. Obviously, the PDA is not acting in a typical quasi-optical manner, because its dimensions are relatively small compared to the design wavelength.

#### **ACKNOWLEDGMENT**

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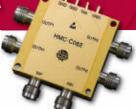
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NEW.	43 / 43	D-Type Flip-Flop	9 / 10	1.5	0.5	580	-3.3	C-13 / 1.85mm	HMC-C060
NEW	50 / 25	D-Type Flip-Flop Double Edge Triggered	9 / 11	1.5	0.5	690	-3.3	C-13 / 1.85mm	HMC-C061
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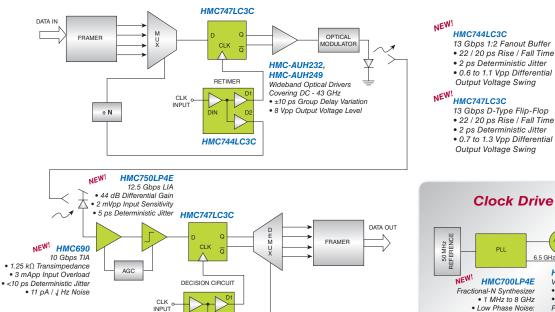
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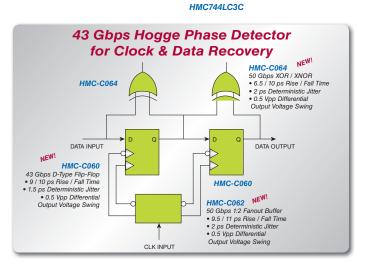
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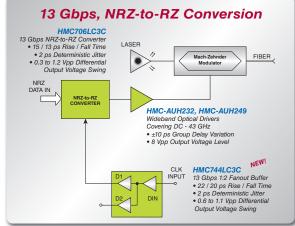
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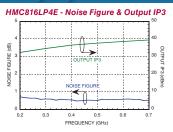
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	0.7 - 1.1	High IP3, DBL-BAL, 0 LO	DC - 0.5	-7.5	24	34	LP4	HMC686LP4E
NEW!	0.7 - 1.1	High IP3, DBL-BAL, 0 LO	DC - 0.5	-7.5	22	40	LP4	HMC786LP4E
	1.7 - 2.2	High IP3, DBL-BAL, 0 LO	DC - 0.5	-8	30	35	LP4	HMC685LP4E
	1.7 - 2.2	High IP3, DBL-BAL, 0 LO	DC - 0.5	-8	31	34	LP4	HMC687LP4E
NEW!	1.7 - 2.2	High IP3, DBL-BAL, 0 LO	DC - 0.5	-8	28	38	LP4	HMC785LP4E
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## PIN DIODE PERFORMANCE TRADEOFFS ACROSS PACKAGE AND PROCESS Types

In today's global wireless industry, demands for semiconductor performance are becoming increasingly more challenging. Higher power and higher operating frequencies are two themes that permeate throughout this market space. Applications such as Magnetic Resonance Imaging (MRI) and UHF/VHF Tactical Radios require extremely high power handling PIN diodes at lower frequencies. Alternatively, broadband and high frequency applications such as Test Instrumentation, RADAR and Sensors require PIN diodes to push frequency ranges beyond 70 GHz.

PIN diodes typically come in several semi-

conductor flavors—Silicon. GaAs and AlGaAs. Not only does the semiconductor process play a significant role in the performance of PINs, but also the packaging medium. Many suppliers have subsequently developed unique process and packaging technologies designed to address the various frequency, power and mounting needs of customers. Three PIN diode products that have pioneered the diode industry are Silicon Metal Electrode Leadless Face (MELF) packaged PINs for high power applications, packageless PINs for broadband surface-mount applications, and flip chip AlGaAs PINs for ultrahigh frequency applications. In this paper, the processes and packages of these devices will be explored, compared and contrasted.

#### **MELF PIN DIODES**

MELF package PIN diodes were designed with the intention of operating in high power, low frequency environments. The rugged MELF design hermetically encloses the PIN diode in ceramic, as shown in Figure 1. The diode is sandwiched between two Molvbdenum plugs from the top and bottom. With a thermal conductivity at 20°C of 142 W/mK, these Moly plugs provide an optimal thermal contact with the diode die to facilitate heat conduction. A solder preform is then added on the external side of the plug. The combination of this RoHS solder preform and the metallized ceramic on the top and bottom of the package allows for these devices to be surface mounted using Sn63/Pb37 solder or some other RoHS compliant solders. The tin plated, rectangular construction was done intentionally to enhance

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▲ Fig. 1 MELF package construction.

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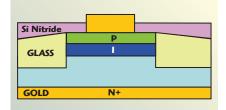
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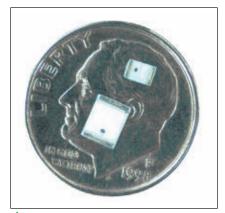
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▲ Fig. 2 Silicon PIN diode construction.

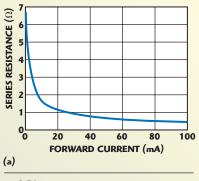


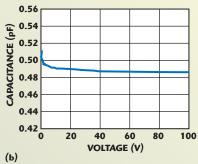
▲ Fig. 3 MELF package styles.

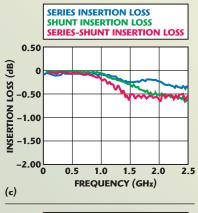
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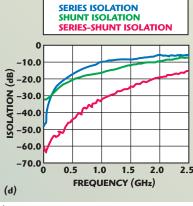
The construction of the MELF PIN is critical to an RF designer due to the efficient heat dissipation and consequent power handling up to 200 W. In addition, PIN diodes with different I-region thicknesses ranging from 30 to 350 micron can be mounted into this package style. Thicker I-regions handle higher RF voltages and provide higher linearity (IIP3) due to the increased breakdown voltage (Vb). In contrast, thinner I-regions will have faster switching/settling speeds as well as lower series resistance (Rs). *Figure* 2 shows the construction of the PIN diode. These MELF PINs work well down to 300 kHz and up to about 2 GHz before package parasitics impact their RF performance.

MELF PIN diodes have two package styles, as shown in *Figure 3*. The first is the smallest MELF with a parasitic capacitance of 0.16 pF and a parasitic inductance of 0.15 nH per Moly plug. *Figure 4* shows the DC and RF performance of a typical MELF PIN with the DC parameters measured by an impedance analyzer on a single diode, and the S-parameter performance measured on a vector network analyzer. The series resistance, capacitance, insertion loss and isolation are shown for a MELF PIN soldered









▲ Fig. 4 DC and RF performance of a MELF PIN diode.

down onto a Rogers 4350 microstrip line in series. Insertion loss and isolation are also shown for a shunt MELF PIN soldered to ground. Combining both series and shunt MELF PINs into a single configuration shows that the isolation improves dramatically without significantly degrading the insertion loss.

The performance can be optimized for both bandwidth and high frequency performance very easily with additional matching elements. These PINs are typically used as building blocks for more complex circuits such as multi-throw RF switches and attenuators. The low Rs is critical for low insertion loss series switching applications while the low distortion versus forward current is equally as important for attenuator applications.

These diodes are also available in non-magnetic packages for MRI applications, which require high voltage handling below 1 GHz. The existence of magnetic materials in a PIN diode structure distorts the static magnetic fields associated with various coils and will interfere with calibration and accuracy. Consequently, non-magnetic MELFs have the ability to optimally receive low power return signals from the human body.

#### **HMIC SURMOUNT PIN DIODES**

M/A-COM Technology Solutions has developed a Heterolithic Microwave Integrated Circuit (HMIC) process. It is a silicon and glass-based process that uses silicon pedestals embedded in a low loss, low dispersion glass. Selective backside metallization is utilized with via connectivity to the topside RF traces and air-bridges to produce a surface-mount device. The topside of the die is fully encapsulated with silicon nitride, and has an additional polymer layer to help protect against damage during handling and assembly. This surface mountable solution effectively created is called "surmount" throughout this article. A cross-section of the HMIC process as applied to both series and shunt configured PIN diodes is shown in Figure 5.

The shunt diode is realized with the anode, cathode and "I" region contained within a silicon pedestal. The cathode of the PIN diode serves as an electrical contact to the ground plane, and since silicon has a thermal conductivity approximately one third that of gold, acts as a low thermal resistance heat spreader. In addition, HMIC provides a simultaneous cathode contact on the top surface

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XC0900B-30	0.8-1.0	355		
XC1500A-20	1.0-2.0	150		
1P510	1.7-2.0	20		
1P520	1.7-2.0	25		
XC1900E-10	1.7-2.0	175		
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XC1900A-10	1.7-2.0	175		
XC1900A-20	1.7-2.0	150		
JP506	2.0-2.3	20		
JP510	2.0-2.3	20		

Part Number	Frequency (GHz)	Power (W)
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XC2100A-05	2.0-2.3	175
XC2100A-10	2.0-2.3	175
XC2100A-20	2.0-2.3	150
XC2100A-30	2.0-2.3	120
XC2100B-30	1.8-2.7	300
1P610	2.3-2.7	20
1P620	2.3-2.7	25
XC2500P-20	2.3-2.7	20
XC2500E-10	2.3-2.7	145
1M710	3.3-3.7	22
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XC3500M-20	3.3-3.8	60
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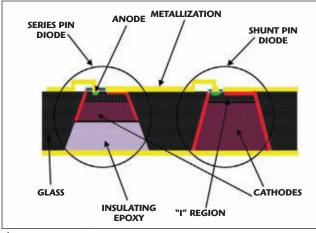
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▲ Fig. 5 HMIC process cross-section.

of the via enabling more complex switch configurations to be realized. Silicon vias to achieve vertical connections (front to back) are a natural consequence of the HMIC fabrication process. The top surface of these vias typically serves as the "active" layer for the formation of the required diode-based active devices and as interconnection paths for the requisite passive elements. The various circuit

elements, either active or passive, are then laterally linked using standard photolithography and metallization techniques.

The shunt diode has the highest power handling so it has a very high thermal conductivity from the surface to ground since its cathode is directly connected to the backside. A series diode, by contrast,

is always the weak thermal link in the design since it has the lowest thermal conductivity. A thermally conductive but electrically insulating epoxy isolates the cathode of the diode from the backside of the entire structure. The formation of the series diode is initially identical in formation to the shunt diode. A cavity is created in the silicon cathode using a selective etch that is then packed with a low dielectric con-

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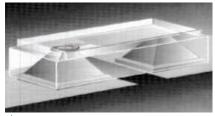
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stant, high field strength, silica filled epoxy. This epoxy works very well as a DC and RF isolation medium. The limitation with the surmount diode lies with the silica filled epoxy used to isolate the diode when in series from the RF ground plane. The silica filled material is essentially a thermal open and the only heat sinking that is occurring in the series diode is a result of heat flow along the metallization structures to the nearest silicon via. Using 175°C as the maximum reliable operating junction temperature of the switch, which always occurs at the series diode, the diode insertion loss and thermal resistance become the limiting factors to incident power levels.

Combining glass and silicon enables the high frequency and high power handling properties of the two materials to be optimized while allowing true surface-mount device structures to be produced using standard semiconductor processing equipment and techniques. Glass has a low dielectric constant and a low, high frequency loss tangent, while silicon has high thermal conductivity and low electrical resistance. In addition, both materials have a nearly identical thermal coefficient of expansion.

When using this process to design discrete surmount PIN diodes, as shown in Figure 6, the shunt construction shown in Figure 5 is used. The anode connection at the top of the pyramid pedestal on the left is connected to an air-bridge. This airbridge extends over to a via on the right. This via creates an RF connection from the anode through the airbridge down the via to the backside of the device. The cathode of the diode is also connected to the backside of the device, yielding a direct cathode heatsink and provides for optimal heat transfer. These backside connections also provide for the surface mountable ability. In addition, thermal conductivity and dissipated power are optimized because these diodes are





📤 Fig. 6 Discrete surmount PIN diode.

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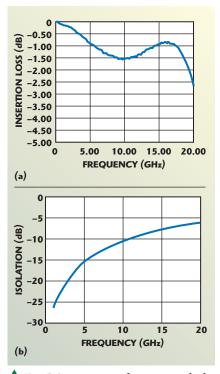


Fig. 7 S-parameters of a surmount diode.

electrically in series, but thermally in shunt. Surmount diodes have I-region

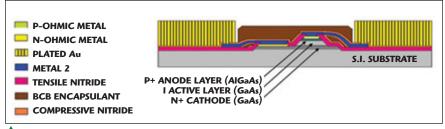


Fig. 8 AlGaAs flip chip process.

widths that range from 10 to 50 microns are available in different sizes. HMIC surmount PINs are useable in MRI applications as they are nonmagnetic devices.

Surmount PIN diodes can exceed 100 W CW power handling at 2 GHz. The "packageless" surmount construction minimizes parasitic capacitances and inductances to minimal values, resulting in performance from 50 MHz to 26 GHz. Figure 7 demonstrates the broadband small-signal performance of a series mounted surmount diode. Power and bandwidth are two critical attributes and are major differentiators for the HMIC surmount PIN diode option.

## forms is flip chip PIN diodes. The AlGaAs diodes combine Aluminum

FLIP CHIP AIGaAs PIN DIODES

One chip type that currently tran-

scends multiple semiconductor plat-

(in the P+ region) and Gallium Arsenide (in the I and N regions), which improves the insertion loss significantly at higher frequency ranges. Due to the reduced recombination rate for electrons and the higher carrier injection rate with an Aluminum-GaAs heterojunction, a greater number of carriers can flow through the I-region, thereby lowering the effective resistivity of the I-region. Fabricated AlGaAs diodes effectively have lower diode "ON" resistance than conventional GaAs devices by as much as 25 percent. Consequently, AlGaAs PIN diodes outperform silicon beam leads and chip devices for a variety of broadband switching applications. *Figure* 8 shows the vertical construction of the PIN diode and Figure 9 shows several flip chips from the top view.

A flip chip PIN diode connects to a substrate from the top pads of the package. Consequently, the chip has to be flipped and epoxied down to a medium using electrically conductive Ag epoxy. The BCB encapsulant covering the die acts as protection upon the flipping of the diode. This flip chip package construction combined with the AlGaAs process yields a device with capacitance as low as 0.025 pF and operational frequencies beyond 70 GHz. The AlGaAs PIN diode flip chip has good broadband high frequency performance and the fastest switching performance because of its low parasities and thin I-regions. A common tradeoff with high frequency performance is lower power handling capability, as is the case with flip chips. The PIN diodes are rated up to 23 dBm of CW input power. Figure 10 shows small-signal S-parameter data for a typical AlGaAs flip chip in a series configuration. The device pro-



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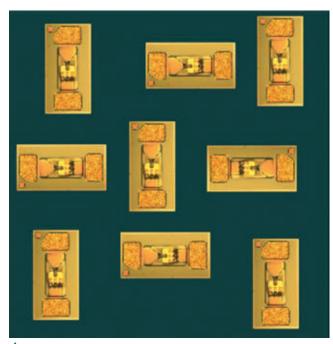




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▲ Fig. 9 Flip chips—top view under magnification.

vides significant circuit tuning advantages due to the low total capacitance Ct (< 18 fF), series resistance Rs (4 ohms at 20 mA) and series inductance

Ls (0.5 nH). These specifications provide a 0.072 ps RC time constant that affords greater operating bandwidth.

#### COMPARISON OF TECHNOLOGIES

One major advantage to discrete PIN diodes is that customers are able to easily and quickly customize their diode topology to meet their RF perneeds. formance Table 1 shows three popular PIN diode switch topologies and each of their strengths and weaknesses. These three switch topologies

are the most basic, but there are also designs with multiple cascaded series diodes and multiple shunt diodes on a single arm.

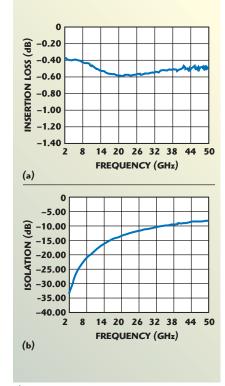


Fig. 10 S-parameters of a AlGaAs flip chip.

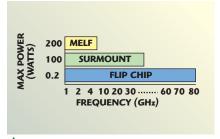
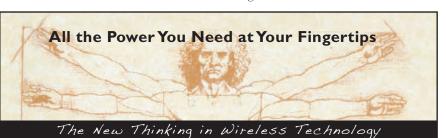


Fig. 11 Diode comparison, frequency vs. power.

**Figure 11** shows how the three diode processes and packaging technologies compare with each other over frequency and maximum CW input power. The trend in performance is typically the maximum operating frequency and maximum CW incident power are inversely related. The MELF PIN diode can handle up to 200 W of CW incident power, but has the narrowest and lowest frequency band of operation. Alternatively, the flip chip PIN diode has been shown to operate beyond 80 GHz with the broadest bandwidth performance, but with limited power handling of 0.2 W incident power. The optimal compromise between frequency and power was described with the HMIC surmount PIN diodes, which can han-

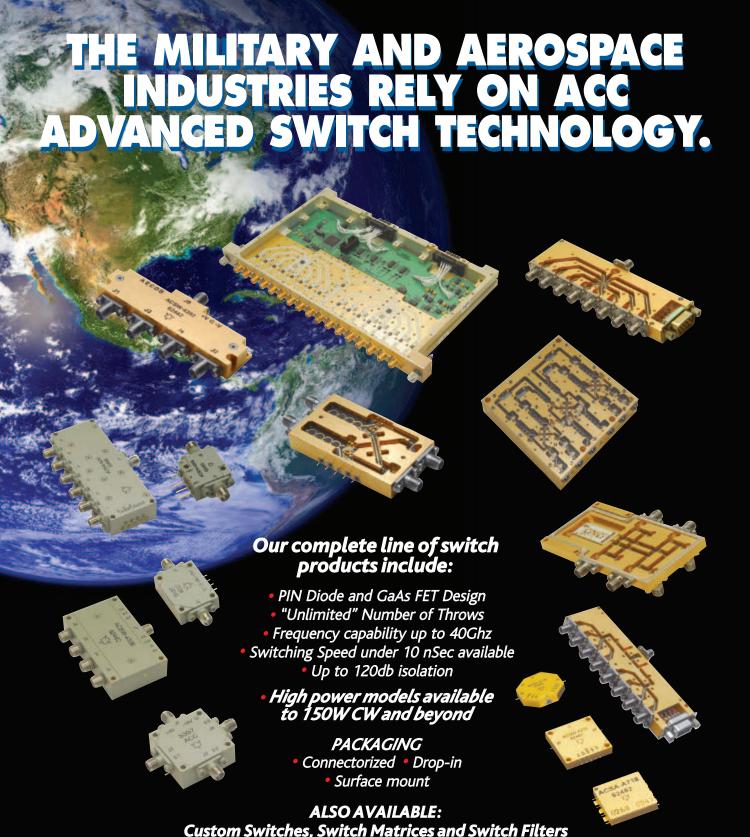


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TABLE I
SWITCH TOPOLOGY STRENGTHS AND WEAKNESSES

	Swi	tch Design Configurati	ions		
Parameter	Series Diodes	Shunt Diodes	Series-shunt Diodes		
Insertion Loss	Best at Higher Freq.	Best at Lower Freq.	Moderate		
Isolation	Worst	Moderate	Best		
Return Loss	Moderate	Worst	Best		
RF Incident Power	Worst	Best	Moderate		
RF Power Dissipation	Worst	Best	Moderate		
Switching Speed	Worst	Best	Moderate		
DC Power Consumption	Best	Moderate	Worst		
PIN Diode Driver Simplicity	Best	Moderate	Worst		

dle up to 100 W of incident power while still achieving broadband performance up to 26 GHz.

#### **CONCLUSION**

MELF, surmount and AlGaAs flip PIN diodes were described and compared against each other. Each type of PIN diode has clear advantages, depending on the end application. The PIN starting material, I-region thickness and packaging technology play major roles in the diode performance.



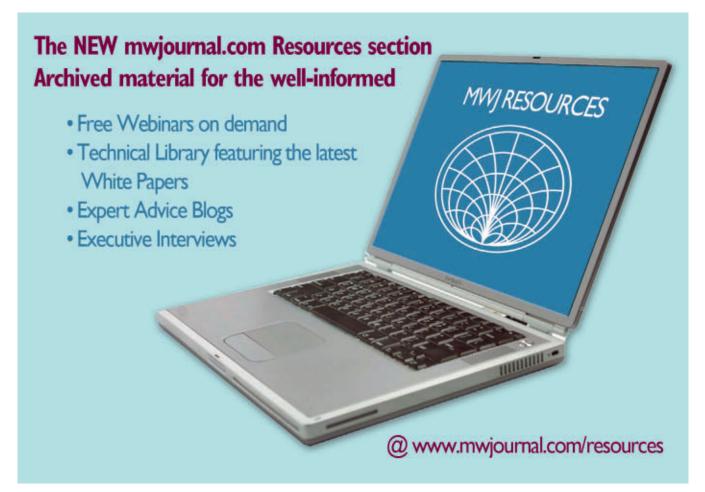
Kevin Harrington holds his MS degree in Electrical Engineering from the University of Massachusetts, Amherst. He brings to M/A-COM Technology

Solutions more than 13 years of experience in GaAs RF IC design and five years of product management. He is currently Product Development Manager responsible for HMIC diode & GaAs IC product development across multiple markets.



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holds his MS degree
in Electrical
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# THEORY AND PROPOSED METHOD FOR DETERMINING LARGE-SIGNAL RETURN LOSS OR "HOT S<sub>22</sub>" FOR POWER AMPLIFIERS

ower amplifiers (PA) are a critical functional block in today's wireless communications. They are found in every cell phone, cordless phone, RF remote controller, etc. Any application requiring the wireless transmission of analog or digital signals will require a PA. In wireless equipment, the PAs are usually placed as close as possible to the antenna to minimize RF losses, maximize power efficiency and maximize battery life. RF systems engineers need to determine the PA return loss under actual output power drive levels. This so-called "Hot  $S_{22}$ " is needed to calculate the mismatch loss at the antenna interface and to determine the actual wireless system transmit power (a key requirement for regulatory bodies, such as the FCC).

The verification of a PA output return loss has proven to be a problematic and challenging endeavor when the PA is delivering high output power. High power PAs will inadvertently heat up as the output power levels are increased.

Under high output power conditions, the power transistor's parameters may significantly change as temperature and bias conditions change. Therefore, the PA output return loss may be substantially different when operated under low output power versus high output

power. Most PA suppliers will only publish return loss values under small-signal conditions. These values should be checked against actual high power conditions when conducting systems transmit power budgets. A number of test equipment suppliers have "off-the-shelf" test hardware for measuring the return loss of high power units, <sup>2,3</sup> but these solutions are usually very expensive, and may not justify the investment for engineers conducting only occasional high power tests.

This article outlines a simple and cost-effective solution for determining the return loss of a high power PA. A test procedure is outlined, based on a mathematical approach, to determine the PA large- (or small-) signal return loss by measuring the insertion phase variation of the PA at specific VSWRs, using an inexpensive and simple test arrangement.

#### PA REFLECTION COEFFICIENT

Any RF test configuration can be expressed by a source impedance  $Z_L$ , and a characteristic impedance  $(Z_0)$ , as shown in **Figure 1**. If the load impedance is equal to the source characteristic impedance then the reflected traveling

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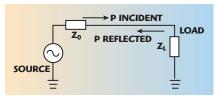


Fig. 1 Power transmission from source



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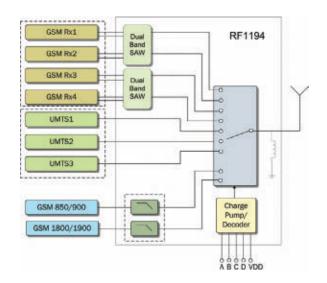


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#### **RF1193 & RF1194 OVERVIEW**

						In	put Pow	ver	Insertion Loss										
Part Number	Switch Type	Interface	Integrated Harmonic Rejection LPF's		DC Blocking Capacitors	GSM LB (dBm)	GSM HB (dBm)	UMTS (dBm)	GSM LB Tx (dB)	GSM HB Tx (dB)	UMTS Tx (LB/HB) (dB)	UMTS Rx (LB/HB) (dB)	GSM Rx (LB/HB) (dB)	Second Harmonics (dBc)	Third Harmonics (dBc)	IIP2 (dBm)	IIP3 (dBm)	Pkg Size (mm)	
RF1193 SP10T	ASM (QB GSM, QB UMTS)	GPIO	Yes	No	Not Required	35	33	26	1.05	1.3	0.5 / 0.75	0.5 / 0.75	0.8 / 1.2	<-78	<-78	110	65	3.0 x 3.8 x 0.85	
RF1194 SP9T	SFM (QB GSM, TB UMTS)	GPIO	Yes	Yes	Not Required	35	33	26	1.2	1.3	0.75 / 1.0	0.75 / 1.0	2.3 / 3.1	<-78	<-73	110	65	4.5 x 4.5 x 1.3	

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wave does not exist (as is the case for a matched load). However, when  $Z_L$  is not equal to the PA output impedance  $Z_0$ , then the traveling wave V between the PA to the load contains two components: one is traveling in the +z direction and the other traveling in the -z direction.

$$V = V_{+}e^{-\gamma Z} + V_{-}e^{+\gamma Z} \tag{1}$$

The traveling wave in the +z direction is the incident power, and the traveling wave on the -z direction is the reflected power.

$$V_{inc} = V_{+} e^{-\gamma \bullet Z}$$
 (2)

$$V_{ref} = V_{-}e^{+\gamma \bullet Z} \tag{3}$$

where  $\gamma$  is the propagation constant.

Now replace the source with an actual PA and the load with a phase tuner, which rotates the phase by  $2\pi$  radians and causes, in theory, full reflection back to the PA, as illustrated in *Figure 2*. The reflection coefficient is determined to be the ratio between the reflected and the incident vector as follows:

$$\begin{split} &\Gamma_{L} = \left| \Gamma_{L} \right| \cdot e^{j\theta} \\ &\Gamma_{L} = \frac{V_{-} e^{j\omega_{_{0}} t + (\theta + \phi)}}{V_{+} e^{j\omega_{_{0}} t + \phi}} \end{split} \tag{4}$$

$$\Gamma_{\mathrm{PA}} = \left| \Gamma_{\mathrm{PA}} \right| \cdot \mathrm{e}^{\mathrm{j} \Psi}$$

$$\Gamma_{PA} = \frac{V_{+}^{'} e^{j\omega_{_{0}}t + (\theta + \phi + \Psi)}}{V \ e^{j\omega_{_{0}}t + (\theta + \phi)}} \eqno(5)$$

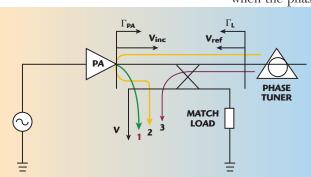
where:

 $\boldsymbol{\Phi}$  is the shifted phase caused by the PA

 $\boldsymbol{\Theta}$  is the phase angle of the reflection coefficient  $\boldsymbol{\Gamma}_L$ 

 $\Psi$  is the phase angle of the reflection coefficient  $\Gamma_{PA}$ 

The summing vector, V, in the coupled port contains three vectors that are directed from three different paths, that is:



📤 Fig. 2 PA in a mismatch system.

$$V_1 = V_{inc} \cdot CF$$
 (6)

$$V_2 = V_{inc} \cdot \Gamma_{PA} \cdot \Gamma_L \cdot CF \tag{7}$$

$$V_3 = V_{inc} \cdot \Gamma_L \cdot CF \cdot DR \tag{8}$$

where CF is the bidirectional coupling factor and DR is the directivity for the bidirectional coupler.

$$V=V_1+V_2+V_3$$

$$V=CF \cdot V_{\perp} e^{j\omega_0 t + \phi} +$$

$$(9)$$

$$CF \cdot \Gamma_{PA} \cdot \Gamma_{L} \cdot V_{+} e^{j\omega_{0}t + \varphi} +$$

$$CF \cdot DR \cdot \Gamma_{L} \cdot V_{+} e^{j\omega_{0}t + \phi}$$
 (10)

Using directional couplers with DR > 20 dB, ensures that  $V_3$  is much smaller than  $V_2$ , that is:

$$\begin{array}{l} V_2 >> V_3 \\ V_{inc} \cdot \Gamma_{PA} \cdot \Gamma_L \cdot CF >> V_{inc} \cdot \Gamma_L \cdot CF \cdot DR \\ \Gamma_{PA} >> DR \end{array} \eqno(11)$$

It is recommended that the directivity for the bidirectional coupler should be higher than the PA return loss by 15 dB. This will ensure that the vector  $V_3$  will remain negligible.

Directivity≥ PA R.L + 15 dB

If  $V_3$  is negligible, then the vector V can be reduced to:

$$V = V_1 + V_2 \tag{12}$$

$$V = CF \cdot V_{+} e^{j\omega_{0}t + \varphi} \left(1 + |\Gamma_{PA}| \cdot |\Gamma_{L}| \cdot e^{j(\theta + \psi)} \right)$$
(13)

$$\begin{split} &\Gamma_{Total} = \Gamma_{PA} \cdot \Gamma_{L} = \\ &\frac{V_{+}^{'} e^{j\omega_{_{0}}t + (\theta + \phi + \Psi)}}{V_{_{+}} e^{j\omega_{_{0}}t + \phi}} \end{split} \tag{14}$$

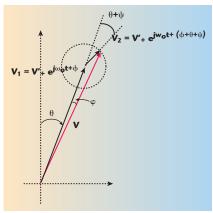
$$V = CF(V_{+}e^{j\omega_{0}t+\varphi} + V_{+}'e^{j\omega_{0}t+(\theta+\varphi+\psi)}) \quad (15)$$

The summing vector V, as illustrated in **Figure 3**, contains the vector  $V_1$ , which represents the incident wave and the vector  $V_2$ , which represents the reflected wave.

The angle  $\phi$  is the angle between the incident vector  $V_1$  to the summing vector V and is also determined as the variation in PA insertion phase between the PA insertion phase at VSWR=1:1 to the PA insertion phase when the phase tuner is shifted with-

in  $2\pi$  radians with VSWR>1.

There are two locations on the phase tuner where the maximum and minimum PA insertion phase is achieved. At these two locations, the reflected vector is perpendicular to the incident vector



ightharpoonup Fig. 3 The reflected wave vector is rotating  $2\pi$  radians across the incident wave vector.

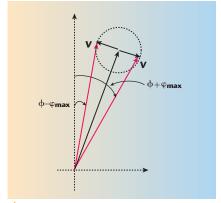


Fig. 4 Vector diagram for maximum and minimum insertion.

$$(\theta + \Psi = \frac{\pi}{2} \text{ or } \theta + \Psi = -\frac{\pi}{2})$$

and the angle  $\phi$  reaches the highest value,  $\phi_{MAX}$ , as shown in **Figure 4**. At these two locations of 90° insertion phase, the product of the load and PA reflection coefficients can be written as:

$$\Gamma_{Total} = \Gamma_L \cdot \Gamma_{PA} = \frac{V_+^{'} e^{j\omega_0 t + (\varphi + \frac{\pi}{2})}}{V_+ e^{j\omega_0 t + \varphi}} =$$

$$\frac{V_{+}^{'}e^{j\omega_{_{0}}t+(\varphi-\frac{\pi}{2})}}{V_{_{*}}e^{j\omega_{_{0}}t+\varphi}}=\tan\phi_{max} \tag{16} \label{eq:16}$$

$$-20\log|\Gamma_{\text{Total}}| = -20\log\tan\varphi_{\text{max}}$$
 (17)

$$-20\log|\Gamma_{PA}|-20\log|\Gamma_{L}| =$$

$$-20\log\tan\varphi_{max}$$
 (18)

$$\begin{array}{ll} -20log|\Gamma_{PA}| \text{=-}20log\;tan\phi_{max} \\ +20log|\Gamma_{L}| \end{array} \tag{19}$$

Since the phase tuner has a full reflection then  $G_{L=1}$  and the PA return loss (in dB) can be expressed as:

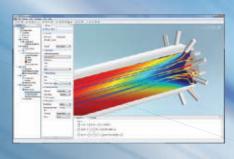
PA\_R.L=-20log 
$$tan\phi_{max}$$
 (20)

 $\phi_{\text{MAX}}$  can be found by rotating the



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Fig. 5 Test setup for measuring maximum

PAR.L

phase tuner within  $2\pi$  radians and the maximum insertion phase can be searched using a phase detector with the test setup shown in **Figure 5**.

### PA REFLECTION COEFFICIENT WITH A DETERMINED MISMATCH LOAD

In practice, PAs are specified over a limited VSWR range. The PA can be damaged or unstable with a load VSWR above what has been specified by the vendor.

Therefore, the same analysis will be given when the load phase tuner is connected to the PA through an attenuator in order to limit the VSWR that will reflect on the PA (see *Figure 6*).

$$V=V_1+V_2 \tag{21}$$

 $\begin{array}{c} V = CF \cdot (V_{+} e^{j\omega_{0}t + \varphi} + \\ (Att)^{2} \cdot V_{+}^{t} e^{j\omega_{0}t + (\theta + \varphi + \psi)}) \end{array}$ 

$$\tan\phi_{max}=(Att)^2\cdot\frac{V_{+}^{'}e^{j\omega_{_{0}}t+(\theta+\varphi+\psi)}}{V_{+}e^{j\omega_{_{0}}t+\varphi}}=$$

$$(Att)^2 \cdot \Gamma_L \cdot \Gamma_{PA} \tag{23}$$

$$\Gamma_{PA} = \frac{\tan\phi_{max}}{(Att)^2 \cdot \Gamma_{L}} \tag{24}$$

$$\mathrm{PA}_{-}\mathrm{R.L} = -20\log\Gamma_{\mathrm{PA}} =$$

$$-20 \log \left( \frac{\tan \phi_{max}}{(Att)^2 \cdot \Gamma_L} \right) \tag{25}$$

Since the phase tuner has a full reflection,  $\Gamma_{L=1}$ , the PA return loss can be expressed as:

$$PA_R.L = -20 \log \Gamma_{PA} =$$

$$-20 \log \left( \frac{\tan \varphi_{max}}{(Att)^2} \right)$$
(26)

01

$$\begin{array}{lll} -20log(tan\phi_{max}) = PA\_R.L(dB) + \\ 2 \cdot Att(dB) \end{array} \eqno(27)$$

If the PA return loss is high and the attenuator used between the PA to the phase tuner is high, then the phase

angle  $\phi_{MAX}$  may be small and difficult to measure in order to have accurate results. Therefore, it is suggested to use a small attenuator (1 to 3 dB) between the PA and the phase tuner.

## PHASE TUNER PHASE TUNER PHASE DETECTOR PHASE DETECTOR

**PHASE** 

DETECTOR

insertion phase.

▲ Fig. 6 Test setup for measuring maximum insertion phase with limited VSWR.

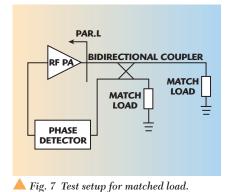
#### **TEST METHOD**

#### Step 1:

Connect the PA as illustrated in *Fig*-

ure 7 using a 50  $\Omega$  load at the output of a bidirectional coupler (additional attenuation can be connected in front of the phase detector whenever it is desired to measure the return loss for a very high power PA).

Measure the insertion phase at the various frequencies of interest using small-signal or large-signal input power. The insertion phase with a 50  $\Omega$  load will be the reference insertion phase before loading the PA with different VSWRs.



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LZY-2X+	500-1000	46	+45	-	8.0	+54	28	8.0	1895.00
ZHL-5W-2GX	800-2000	45	+37	+38	8.0	+44	24	2.0	945.00
ZHL-10W-2GX	800-2000	43	+40	+41	7.0	+50	24	5.0	1220.00
<ul> <li>ZHL-20W-13X</li> </ul>	20-1000	50	+41	+43	3.5	+50	24	2.8	1320.00
ZHL-30W-252X+	700-2500	50	+44	+46	5.5	+52	28	6.0	2920.00
<ul> <li>ZHL-50W-52X</li> </ul>	50-500	50	+46	+48	4.0	+55	24	9.3	1320.00
<ul> <li>ZHL-100W-52X</li> </ul>	50-500	50	+47	+48.5	6.5	+57	24	10.2	1920.00

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OWith heat sink/fan removed, customer must provide adequate cooling to ensure that the base plate temperature does not exceed specified temperature. See data sheets on Mini-Circuits web site.



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SBT-GF0702 BIAS-T

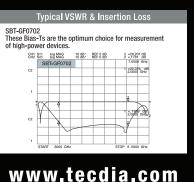
The SBT-GF0702 is capable of handling up to 10 amps of DC current at 150V to apply bias to RF signals within the range of 2~7 GHz.

For many years Tecdia has produced top of the line high current (5, 10 and 20A) bias tee models capable of handling a DC bias voltage of 30V, and RF power of 50W. Now, to meet the higher voltage and power requirements of GaN devices, Tecdia is introducing this new design that has the following specifications:

#### **SPECIFICATION**

Series		SBT				
Model		SBT-G	F0702			
Frequency Ra	nge	2~7	'GHz			
Insertion Lo	Insertion Loss		max.			
VSWR (Return	loss)	1.22 max.	(20dB min.)			
Connectors	RF	APC-7				
Connectors	DC	BNC-R (Female)				
RF Power		50W max.	100W max.			
Bias Currer	nt	20A max.	10A max.			
Bias Voltag	е	30V max. 150V ma				
Dimensions (mm)*		50 x 52 x 20				
Weight		200g				

\* Excluding Connectors



In *Table 1*, the measured value for a high power (2 W), 350 to 470 MHz, Skyworks' PA (SKY65141), is shown.

#### Step 2:

Disconnect the 50  $\Omega$  load at the output of the bidirectional coupler and connect a 1.5 dB pad in order to present the PA with a VSWR = 6. Place a phase tuner after the fixed attenuator pad. The phase tuner must be capable of continuously varying

the insertion phase from 0 to  $360^{\circ}$ . The test setup is illustrated in Figure 8. Adjust the phase tuner in order to find the highest and lowest insertion phase and calculate at each frequency what the maximum phase variation is, compared to the insertion phase at 50  $\Omega$ , as indicated in **Table 2**. Note that

the attenuator value is selected to be within the specified PA load VSWR range. The total output insertion loss should be measured at each maximum insertion phase location on the phase tuner in order for the return loss to be calculated accurately.

In theory  $\phi_{MAX} \stackrel{\cdot}{=} \phi_{MIN}$  , therefore the following equation is valid:

$$\begin{split} &\frac{\phi_{max} - \phi_{min}}{2} = \phi_{max} - \phi_{50\Omega} = \\ &\phi_{50\Omega} - \phi_{min} \end{split} \tag{28}$$

However, in practice  $\phi_{MAX}$  and  $\phi_{MIN}$  may not be equal since the phase tuner may not be ideal and symmetric. Therefore, the insertion phase at VSWR = 1 ( $\phi_{50\Omega}$ ) is subtracted from the absolute value for the maximum phase variation ( $\phi$ - $\phi_{MAX}$  or  $\phi$ + $\phi_{MAX}$ ).

The return loss of the PA is calculated according to the following formula:

$$PA_R.L = -20 \log \left[ \frac{\tan \varphi_{max}}{(Att)^2} \right]$$
 (29)

where  $\theta_{MAX}$  is in degrees and Att is the measured attenuation from the PA output to the phase tuner input.

#### **TEST RESULTS**

The theoretical analysis shown in

## TABLE I INSERTION PHASE WITH VSWR=1 FOR A SKYWORKS PA Frequency (MHz) Insertion Phase at VSWR 1:1 and Pin=4 dBm θ<sub>50Ω</sub> 350 171.4 410 71.2 470 -30.5

### TABLE II MEASURED MAXIMUM AND MINIMUM INSERTION PHASE WITH VSWR=6

Frequency (MHz)	Minimum Insertion Phase $\left( \phi - \varphi_{max} \right)$	Maximum Insertion Phase $(\phi + \phi_{max})$	Maximum Insertion Phase Variation φ <sub>max</sub>
350	157.1	179.9	12.2
410	62.3	75	6.7
470	-42	-26.2	8.6

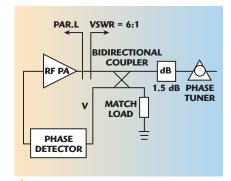


Fig. 8 Test setup for mismatched load.

the above sections was verified using a high power 2 W SMT PA from Skyworks (SKY65141). The PA was tested over its entire operating frequency range, 350 to 470 MHz. The actual return loss measurement was made with a network analyzer at small input signal and the results are given in *Figure 9*.

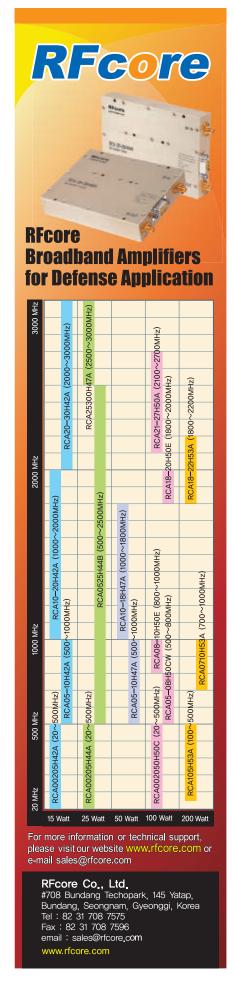
The measurement results are compared to the calculated return loss using the proposed phase measurement procedures outlined in the above sections.

The new test procedure was done using different load VSWRs to demonstrate that the return loss measurements are repeatable at different VSWRs. The return loss obtained using the new proposed phase technique is shown in *Figures 10* and *11*.



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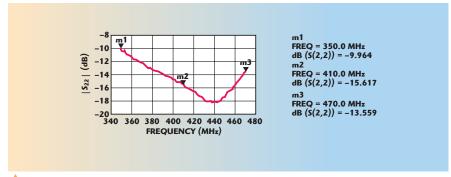


Fig. 9 Return loss measured at low power.

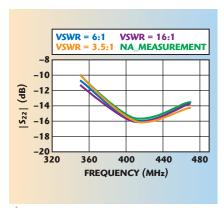


Fig. 10 Calculated PA return loss at P<sub>in</sub> = -30 dBm.



Fig. 12 Photo of high power PA (SKY65141) mounted in its test fixture.

The same method was used to calculate the PA return loss using higher input signal with VSWR = 3.5. A photo of the PA mounted in its test fixture is shown in *Figure 12*.

#### CONCLUSION

A PA return loss is a parameter, which can vary depending on the PA output power, the PA bias current, etc. Therefore, the PA return loss under high output power conditions should be measured and not be assumed to be the same as the return loss measured under small-signal output power conditions. The PA

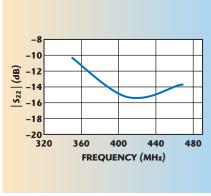


Fig. 11 Calculated return loss P<sub>in</sub> = -4 dBm and VSWR = 3.5.

return loss can be calculated from the phase between the summing (incident and reflected vectors) to the incident vector, which is measured with a matched-load.

This article demonstrates that the "hot" PA return loss can be accurately calculated by measuring the maximum insertion phase variation at any given VSWR, and at any given input drive level. The proposed return loss measurement technique can be implemented using low cost test components, eliminating the need for costly network analyzers.

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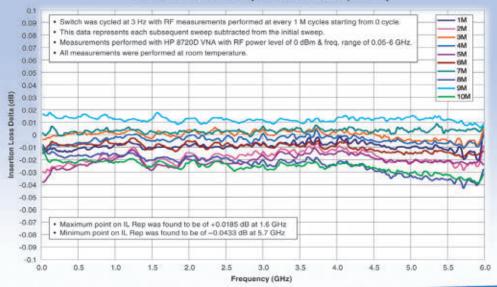


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## KA-BAND BANDPASS FILTER USING A CPW STRUCTURE TECHNOLOGY WITH COPPER ON AN AL<sub>2</sub>O<sub>3</sub> Substrate

This article presents the performance of a Ka-band bandpass filter (BPF) using a coplanar waveguide (CPW) topology on an Al<sub>2</sub>O<sub>3</sub> substrate. A copper (Cu) metallization was also used in this investigation to improve the characteristics of the filter. The measured results of the BPF, with a chip size of  $2423 \times 424 \,\mu\text{m}$ , show a return loss of 25.3 dB and an insertion loss of 0.6 dB at 27 GHz. A comparison between the simulated and experimental results shows good agreement. The overall filter characterization exhibits a broad bandwidth of 18.8 to 38.2 GHz, a high return loss and a low insertion loss, which illustrate that the BPF shows favorable RF characteristics in Ka-band with a compact cir-

The communication applications have increased noticeably in recent years. Apparently, the RF channel bandwidth allocated to communication system applications is approaching saturation. The providers of communication systems are now interested in the microwave band for the next-generation terrestrial systems, including military and satellite communication systems in Ka-band. Several researchers<sup>1,2</sup> have reported that microwave monolithic integrated circuits (MMIC) using coplanar waveguide have been adopted in transmitter communication systems. In the

CPW structure, the ground plane is placed on the top surface of the substrate. Thus, many advantages have been obtained with this CPW schematic layout, such as unnecessary backside fabrication, good electronic isolation property and compact drawing in the circuit layout.<sup>1-3</sup>

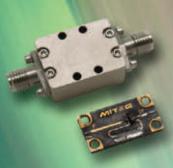
As clearly shown in some review papers, CPW has been extensively studied for MMIC applications. However, little attention has been devoted to the conductor losses in the signal transmission path.<sup>2,3</sup> A copper metal, with an extremely low electrical resistivity  $(1.7 \times 10^{-8} \Omega \text{m})$ , could significantly improve the insertion loss in the BPF.<sup>4</sup> This study investigated a Ka-band BPF circuit using a CPW structure and a copper metallization on the Al<sub>2</sub>O<sub>3</sub> substrate. A Ka-band BPF was fabricated and its S-parameters were measured with a vector network analyzer. The results demonstrated that the fabricated Ka-band BPF exhibited favorable MMIC characteristics within a small size.

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DM0052LA2	0.5 - 2	DC - 0.5	7 – 13	6.5/8.5	30				
DM0104LA1	1 – 4	DC - 1	7 – 13	5.5/7	30				
DM0208LW2	2 – 8	DC - 2	7 – 13	7/8	30				
DM0408LW2	4 – 8	DC - 2	7 – 13	5/6	30				
DM0812LW2	8 – 12	DC - 4	7 – 13	4.5/6	30				
DM0416LW2	4 – 16	DC - 4	7 – 13	7/8	30				
DB0218LW2	2 – 18	DC - 0.75	7 – 13	6.5/8.5	22				
DB0226LA1	2 - 26	DC - 0.5	7 – 13	9/10	20				
DB0440LW1	4 - 40	DC - 2	10 – 15	9/10	20				
M2640W1	26 - 40	DC - 12	10 – 15	10/12	28				
TRIPLE-BALANCED VERSIONS									
TB0218LW2	2 – 18	0.5 - 8	10 – 15	7.5/9.5	20				
TB0426LW1	4 – 26	0.5 - 8	10 – 15	10/12	20				
TB0440LW1	4 – 40	0.5 – 20	10 – 15	10/12	18				



	Model Number	Input Frequency (GHz)	Input Power (dBm)	Output Frequency (GHz)	Conversion Loss (dB) Typ./Max.	(dB	jection c) Typ. Odd Harm.			
ı	DROP-IN VERSIONS									
۰	SXS01M	0.5 - 3	8 – 12	1 – 6	13/16	-20	-25			
۰	SXS04M	2 – 9	8 – 12	4 – 18	13/15	-20	-25			
п	SXS07M	3 – 13	8 – 12	6 – 26	13/18	-18	-25			
ı	CONNECTORIZED VERSIONS									
п	SXS2M010060	0.5 - 3	8 – 12	1 – 6	13/16	-20	-25			
н	SXS2M040180	2 – 9	8 – 12	4 – 18	13/15	-20	-25			
п	SXS2M060260	3 – 13	8 – 12	6 – 26	13/17	-18	-25			
	MX2M130260	6.5 - 13	8 – 12	13 – 26	11/13	-15	-15			
ı	MX2M004010	0.02 - 0.5	8 – 12	0.04 – 1	10.5/13	-25	-25			









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#### DESIGN AND FABRICATION OF A KA-BAND BANDPASS FILTER

The Ka-band BPF circuit was designed using a CPW structure. Figure 1 shows the schematic layout of the Ka-band BPF, which uses two series open stubs with a characteristic impedance  $Z_0 = 50 \Omega$  and a length (l), which was designed to be approximately a quarter wavelength at the Ka-band center frequency ( $\lambda_{eff}$ ), that is,  $l = \lambda_{eff}/4.5$  Ports 1 and 4 are the input and output of the filter, while Ports 2, 3, 5 and 6 are connected to ground. The lumped equivalent circuit model of the BPF is shown in Figure 2. In effect, each open stub is equivalent to three LC tanks (L<sub>1</sub>/C<sub>1</sub>,  $L_2/C_2$  and  $L_3/C_3$ ) with an air-gap  $(C_0)$ series connection. This circuit permits a low transmission loss and easy fabrication.<sup>3</sup> These resonators, with LC tanks, can operate in a wideband BPF. The resonators are operating in a mixed coupled mode, meaning partially magnetically and partially electrically coupled.

The S-parameters of the coupled resonating filter were simulated with the Advanced Design System (ADS), and the effect of the electric-magnetic coupling within the Ka-band BPF layout were computed with the HP-Momentum. Subsequently, the Ka-band BPF was laid-out and fabricated on an  ${\rm Al_2O_3}$  substrate 0.5 mm thick and with a conductor layer 2 µm thick, consisting of a Ti layer, 300 Å thick, to

enhance adherence, the copper layer and a thin Au layer, 2000 Å thick, to prevent oxidation. **Figure 3** shows a microphotograph of the Ka-band BPF, with a chip area of  $2423 \times 424 \ \mu m$ .

#### THE S-PARAMETERS OF A KA-BAND BANDPASS FILTER

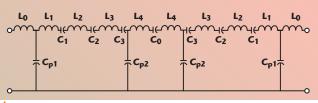
Figures 4 and 5 show the measured and simulated S-parameters of the Ka-band BPF. A simulated insertion loss ( $S_{21}$ ) of -0.6 dB and return loss ( $S_{11}$ ) of -10 dB were obtained within a bandwidth of 21.6 GHz, in the range 17.2 to 38.8 GHz. The BPF showed an input return loss exceeding -20 dB, from 25 to 35 GHz, in both measurements and simulation, as well as a maximum simulated return loss of -55 dB at 30 GHz.

The results indicate that the measured return loss is slightly degraded and shifted in frequency, compared with the simulation. The most likely explanation was that the variations in fabrication might be the cause of the negligible shift in the center frequency and the small degradation in the return loss. The simulated and measured S<sub>21</sub> results agree fairly well, with the insertion loss remaining approximately constant in the range of 20 to 35 GHz. Overall, the S-parameters characterization confirms the low insertion loss and high return loss in this Ka-band BPF.

Finally, the S-parameters of the Kaband BPF are summarized in *Table 1*.



Fig. 1 Schematic of the CPW Ka-band bandpass filter.



with a chip area of AFig. 2 Equivalent circuit of the Ka-band bandpass filter.

#### **TABLE I** SUMMARY OF MEASURED AND SIMULATED S-PARAMETERS OF THE KA-BAND **BANDPASS FILTER** Center frequency 30 GHz 27.7 GHz Bandwidth 21.6 GHz @ 19.4 GHz @ 17.2 to 38.8 GHz 18.8 to 38.2 GHz -57 dB @ 30 GHz -25.3 dB @ 27.7 GHz Return loss (S<sub>11</sub>) Insertion loss (S21) -0.6 dB @ 30 GHz -0.6 dB @ 27.7 GHz

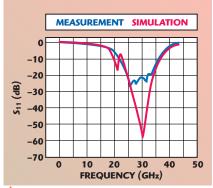
The experimental results appeared to be consistent with the simulation values. These S-parameter results indicate that the Ka-band BPF filter was well designed, demonstrating that the CPW structure with copper metallization on an  ${\rm Al_2O_3}$  substrate is adequate for the MMIC applications.

#### CONCLUSION

In this article, a Ka-band bandpass filter, using a CPW structure on an Al<sub>2</sub>O<sub>3</sub> substrate with a copper metallization, was described. The use of copper metallization, which has a high conductivity, can reduce the insertion loss and improve the return loss of the circuit. The Ka-band BPF design uses two series open stubs with a characteristic impedance  $Z_0 = 50 \Omega$ , whose lumped element equivalent circuit consists of three LC tanks. The measured S-parameters agreed well with the simulation values. The Ka-band BPF exhibits a low insertion loss and a high return loss, which shows that a



▲ Fig. 3 Microphotograph of the Ka-band bandpass filter fabricated on an Al<sub>2</sub>O<sub>3</sub> substrate.



ightharpoonup Fig. 4 Measured and simulated  $S_{11}$  of the bandpass filter.

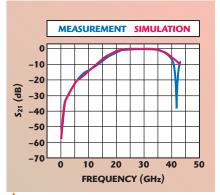


Fig. 5 Measured and simulated S<sub>21</sub> of the bandpass filter.



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CPW structure with copper metallization on an Al<sub>2</sub>O<sub>3</sub> substrate should be adopted for MMIC applications.

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**Yi-Feng Lin** received his MS degree in electronic engineering from Chang Gung University, Tao Yuan, ROC, in 2007. He is now a technology research engineer at Cyntec Corp., Hsinchu. His research interests include RFIC design and measurements and microwave passive

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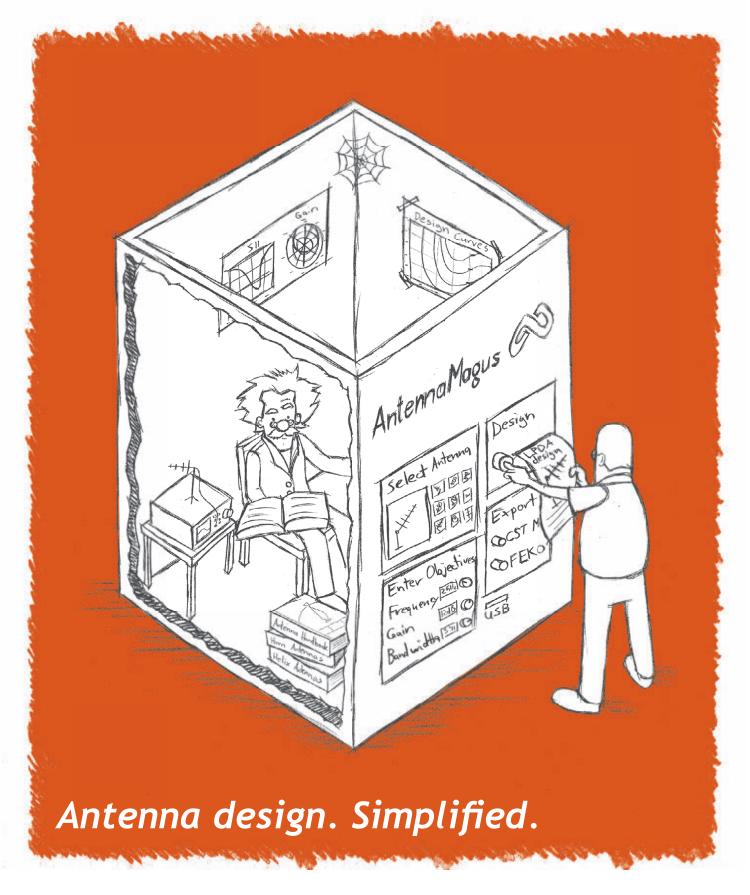
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# DESIGN OF SOURCE DEGENERATED CASCODE DUAL FUNCTIONALITY LNA/PA FOR IEEE 802.15.4 (ZIGBEE)

#### EXPERT ADVICE

ALI MUHAMMAD ABUELMA'ATTI DISCUSSES NEW DESIGN TECHNIQUES USING CMOS INTEGRATION. VISIT WWW.MWJOURNAL.COM.

his paper presents a new compact and comprehensive design methodology for RF CMOS source degenerated cascode dual functionality low noise amplifier (LNA) and power amplifier (PA) for the IEEE 802.15.4 standard (commercially known as Zig-Bee). Due to the need to meet the far apart performance requirements of both the LNA and the PA, the proposed design methodology is based on simultaneous graphical visualization of the relationship between all relevant performance parameters and the corresponding design parameters. To demonstrate the effectiveness of the proposed methodology, a design example is presented. The simulated performance of the designed amplifier at 2.4 GHz satisfies both the requirements of the Zig-Bee LNA and PA with noise figure (NF) of 1.6 dB, input third-order intercept point (IIP3) of 6 dBm and a 1 dB compression point (P1dB) of -3.5 dBm. At the high input power of 0 dBm,

the amplifier achieves 24 percent power added efficiency (PAE) with 8 dB gain and 22 mW power consumption.

#### INTRODUCTION

Over the years, the design of low noise amplifiers in CMOS technology has attracted the attention of many researchers. This is attributed to the rapidly improving CMOS technology as a result of transistor scaling. In designing a LNA the following should be considered: Power gain, noise figure, impedance matching, reverse isolation, stability, distortion and power

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Easy. Fast. Free. For the do-it-yourselfer. consumption. On the other hand, the design of the power amplifier is the most challenging task in a wireless communication transceiver. This is attributed to the trade-offs between the DC power supply voltage, output power, power efficiency and linearity. In designing a PA the following should be considered: High transmitted power, low power consumption, power added efficiency (PAE) nonlinear amplifier characteristics and design parameters, like third-order input intercept point (IIP3), carrier-to-intermodulation ratio (C/I), the input 1 dB gain compression point (P1dB) and adjacent channel power ratio (ACPR). Therefore, the LNA and PA designers are in front of a difficult trade-off among the competing goals of high performance in both amplifiers. In modern wireless communication systems, these two amplifiers are designed separately. No attempt has been reported, so far, for combining the two amplifiers in one.

In the IEEE 802.15.4 (ZigBee) standard, since the output power requirement is relatively modest, it is possible to consider the design of a single amplifier block that can act as a LNA in the receiver chain and a PA on the transmitter side. This would reduce the power consumption, chip area and size leading to cost savings of the transceiver that is vital to the widespread utilization of the ZigBee standard. However, since the achievable performances of the LNA and the PA are mainly limited by the CMOS transistors' parameters and operating conditions, the selection and implementation of a design methodology, leading to the solution of several design problems, is the crucial point in the design of such a dual functionality LNA/PA.

This article presents a new design methodology for a dual functionality LNA/PA. The proposed design methodology is based on simultaneous 3D graphical visualization of the relationship between all relevant performance parameters and corresponding design parameters. In this regard, it is intended to generate and provide a set of design graphs that can be used by the designer. A design example is then presented to demonstrate the effectiveness of the proposed methodology and the quality of trade-offs it allows the designer to make.

To read this article in its entirety, please visit the online version of the June issue at www.mwjournal.com. ■

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# NETWORK ANALYSIS DUO OFFERS EXTENDED FEATURES

the R&S ZVA24 network analyzer and the new R&S ZVAX24 extension unit combine to form a solution that adapts to user requirements. This combination facilitates faster and easier measurements on active components because it does not require any additional equipment or rewiring. Depending on the application, the extension unit can be equipped with combiners, harmonic filters, pulse modulators and power couplers. It is a scalable and compact test and measurement solution. Although the R&S ZVAX24 has been tailored to the R&S ZVA24, it can also be used with all other network analyzers of Rohde & Schwarz' R&S ZVA and R&S ZVT families.

#### **PLUG IN AND MEASURE**

The combination of a network analyzer and the R&S ZVAX24 extension unit is suitable for use in the development and production of active components. This powerful and modular test solution especially benefits developers and manufacturers of amplifiers for mobile phones and base stations as well as of components for the automotive sector, e.g. car radar.

It facilitates complex measurements and can be used for measurements to satisfy aerospace and defense requirements or for tests on antennas or amplifiers under pulsed conditions. The R&S ZVAX24 occupies only two height units in a 19-inch rack and can be easily placed underneath the R&S ZVA. Semi-rigid cables connect the instruments so that they constitute a single unit.

The extension unit and the components it contains are basically looped into the generator or receiver path by using the direct generator/receiver access. Only a USB cable (for path switching) and an LVDS (LAN) cable (for controlling the pulse modulators) are required as control lines. The unit is operated from the R&S ZVA network analyzer using a block diagram, shown in *Figure 1*, and dialog windows.

Depending on the measurement task, the required RF components such as combiners, pulse modulators or harmonic filters can be switched into the measurement path. The T&M solution's high level of integration means that both present and future functions of the R&S ZVA can be used to perform complex lin-

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ear and nonlinear measurements, in particular on active components (intermodulation measurements, pulse profile measurements, etc.).

#### INTERMODULATION MEASUREMENTS

Intermodulation products are unwanted spectral components that are caused by nonlinear circuit elements and a two-tone signal is required to measure them. If a conventional network analyzer with only one internal generator is used, an external generator and a combiner must be added to the test setup. This is not necessary with the R&S ZVA and R&S ZVAX24 combination because the internal combiner of the extension unit uses the two sources of the four-port network analyzer and generates a twotone signal for intermodulation measurements. Figure 2 shows a typical intermodulation output signal from the Rohde & Schwarz solution in blue and from a conventional one in yellow.

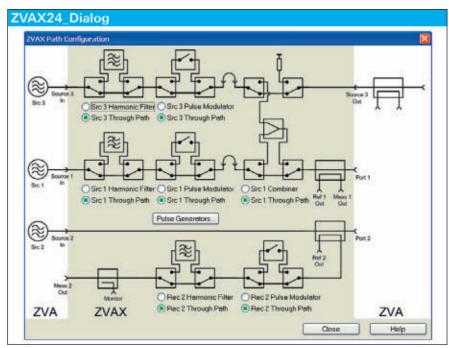
This signal is directly output on one of the four ports. This feature plus the intermodulation wizard make it very easy and convenient to measure the intermodulation parameters of amplifiers or mixers as a function of frequency and power. The combiner can also be used to measure the group delay of mixers without LO access.

#### **PULSE MODULATORS**

Many applications require that DUTs be characterized by using pulsed signals instead of CW signals. The pulse width for these applications typically varies between a few hundred nanoseconds and the upper microsecond range. To be able to characterize the pulse profile distortion of components, the network analyzer must have a time resolution that is considerably higher than the pulse duration.

For applications where the DUT requires a pulse-modulated input signal, either a pulse modulator or a generator with pulse modulation can be used. Since the R&S ZVA-B16 hardware option enables direct access to the network analyzer generator path, the pulse-modulated RF signal (instead of the unmodulated signal) is directly fed to the network analyzer test set.

The pulse modulators of the R&S ZVAX24 offer even more measure-



▲ Fig. 1 Easy and convenient control of the R&S ZVAX24 extension unit using the graphical user interface of the R&S ZVA.

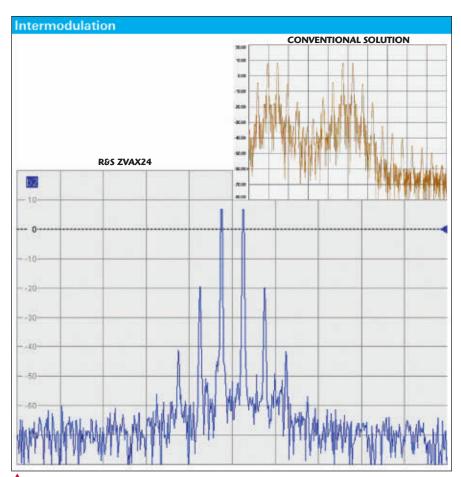


Fig. 2 Comparison of intermodulation signals: R&S ZVAX24 (blue curve) and conventional solution (yellow curve).

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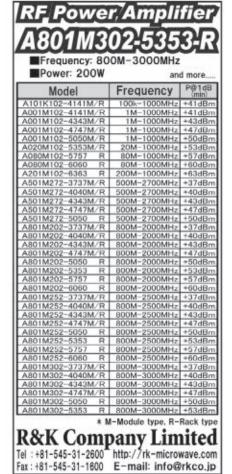
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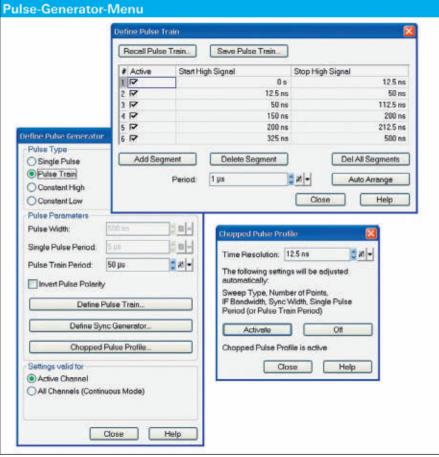
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A010K401-4444M/R	10k-400MHz	+44dBm
A001K101-4747M/R	1k-100MHz	+47dBm
A010K251-4747M/R	10k-250MHz	+47dBm
A010K401-4646M/R	10k-400MHz	+46dBm
A001K101-4949M/R	1k-100MHz	+49dBm
A010K251-4949M/R	10k-250MHz	+49dBm
A010K401-4848M/R	10k-400MHz	+48dBm
A001K101-5353M/R	1k-100MHz	+53dBm
A010K251-5353M/R	10k-250MHz	+53dBm
A010K401-5353M/R	10k-400MHz	+53dBm
A010K101-5757 R	10k-100MHz	+57dBm
A101K251-5757 R	100k-250MHz	+57dBm
A010K101-6060 R	10k-100MHz	+60dBm
A101K251-6060 R	100k-250MHz	+60dBm
A101K080-6363 R	100k- 80MHz	+63dBm
A101K251-6363 R	100k-250MHz	+63dBm
A101K080-6767 R	100k- 80MHz	+67dBm
A101K251-6767 R	100k-250MHz	+67dBm
A101K080-7070 R	100k- 80MHz	+70dBm
A101K251-7070 R	100k-250MHz	+70dBm

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▲ Fig. 3 The R&S ZVA-K27 option offers two independent, integrated pulse trigger generators in the R&S ZVA that deliver single pulses and user-configurable pulse trains.

ment convenience. They are configured and controlled via the graphical user interface of the network analyzer, shown in *Figure 3*, so that no additional switches or trigger generators are required. For measurements with pulsed signals, the extension unit contains two modulators for pulse generation (see Figure 1). Single pulses, periodic pulses or variable pulse trains can be generated.

The R&S ZVA-K7 pulsed measurements option with easy setup enables direct recording of amplitude and phase versus time. This functionality makes it possible to analyze the time-dependent behavior in T/R modules, amplifiers and mixers with a resolution of 12.5 ns. This high resolution, ten times higher than any solution currently available on the market, enables a more accurate characterization of short pulses. At a maximum IF bandwidth of 30 MHz, the signal rise/fall time can be determined with a resolution of up to 33 ns.

Since the pulse generators support user-configurable pulse trains (see Figure 3), the user can generate arbitrary sequences of any width, duration and power, and also characterize components under real-world conditions. Significantly, this measurement does not require a repetitive signal because the user can work with any pulse trains.

The high dynamic range and measurement speed of the new solution are complemented by an easy test setup and straightforward operation. In addition to typical measurements such as high-PRF-mode or point-inpulse measurements, the R&S ZVA-K7 option offers a very convenient pulse profile measurement facility.

A third modulator in the receiver path, shown in Figure 1, 'chops' the pulses. This can be useful in antenna measurements (e.g. in the case of pulsed radar cross-section [RCS] measurements), for example, because time gating allows direct crosstalk be-

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tween transmit and receive antennas with short delay and high amplitude. Pulse profile measurements can be implemented very easily by using the conventional high-PRF-mode.

The pulse modulators of the R&S ZVAX24 can be controlled either via an external trigger generator or directly by the R&S ZVA24 using the new R&S ZVA-K27 internal pulse generator option. The trigger signals are fed in via BNC connectors (if an external trigger generator is used) or via an RJ-45 cable (if the internal R&S ZVA pulse generators are used).

#### **GROUP DELAY MEASUREMENTS**

Mixers and frequency converters form the core of wireless and satellite communications systems. Especially in satellite systems, these frequency converters have to satisfy ever more demanding requirements regarding frequency response and phase linearity. Therefore, the measurement of relative and absolute group delay, of relative phase and of the group de-

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lay derivations (dispersion and scattering) in T/R modules is playing an increasingly important role.

Since there is no access to the local oscillator (LO), Rohde & Schwarz has developed the R&S ZVA-K9 option as a new method for characterizing the group delay and derived parameters without exactly knowing the LO signal. This option makes it possible to determine absolute and relative group delay, relative phase and scattering (group delay derivations).

This innovative method requires a four-port network analyzer with two sources for feeding a two-tone signal to the converter. The R&S ZVA24 measures the phase deviation between the two signals at the input and at the output of the DUT and determines the group delay. Neither the frequency drift nor the frequency modulation of the internal and unknown LO influences the measurement results. The R&S ZVA-K9 calculates the relative phase by integrating the group delay, and it calculates the DUT scattering by group delay derivation.

The conventional methods for determining group delay require a complicated test setup and a calibration. They are also associated with a significant level of uncertainty because they depend on the stability of the LO. Moreover, it is almost impossible to perform group delay measurements on converters having multiple mixer stages. This new approach, however, offers easy setup and calibration, and is independent of the LO's frequency stability. This method is ideal for investigating DUTs with multiple mixer stages.

#### HARMONIC AND INTERFERENCE TEST FILTERS

Two harmonic filters in the generator paths, shown in the block diagram of Figure 1, improve the spectral purity of the signals. Harmonic suppression is typically 60 dBc for the second and 70 dBc for the third harmonic. An additional filter in the receive path (see Figure 1) expands the receiver's dynamic range at test port 2, which is a crucial advantage when measuring harmonics or in-

terference signals. The filter also allows very low harmonic levels to be measured. Harmonic measurements are carried out using the R&S ZVA-K4 option.

#### **COUPLERS**

The R&S ZVAX24 can also be equipped with two high-power couplers, shown in Figure 1, to cover power levels up to 43 dBm (standard test port: 27 dBm). Preamplifiers can be inserted into the source path using connectors on the unit's rear panel in order to further increase the available power levels. A coupler in the measurement path allows the signals of port 2 to be monitored in parallel using a spectrum analyzer or power meter. Signal monitoring is a very helpful feature for complementary measurements or when controlling signals during S-parameter or intermodulation measurements. All these features enable the user to measure DUTs without reconnecting them.

#### CONCLUSION

The scalable T&M solution that consists of the R&S ZVAX24 extension unit and the R&S ZVA24 vector network analyzer (or any other R&S ZVA or ZVT network analyzer) enables linear and nonlinear measurements on active components without extra equipment and without reconnecting the DUT. This is a big step toward higher efficiency and measurement accuracy. Depending on the measurement task to be solved, users can customize a powerful test solution by adding combiners, harmonic filters, pulse modulators and high-power couplers in line with their needs.

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# AN OMNIDIRECTIONAL ANTENNA FOR INDUSTRIAL AND TRANSPORTATION APPLICATIONS

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ireless communications has revolutionized the way our society functions. It is a key element of modern life and its reach is extending far and wide, with new applications constantly coming to the fore. To address the increasing demand to connect the various types of devices and networks, HUBER+SUHNER has developed the new SENCITY® SWA-0825/360/5/30/DFRX30 antenna, which is a rugged omni-directional multiband antenna for GSM 900, GSM 1800, GSM 1900, UMTS, 2.4 GHz band and GPS/Galileo, aimed specifically at industrial and transportation applications.

The need for and proliferation of antennas in the transportation and industrial sectors is increasing rapidly. For instance, a modern car is equipped with numerous antennas for different tasks: mobile communication, GPS navigation, Bluetooth connection between the mobile phone to the radio, the car key, etc. Also, more and more antennas are being used in industrial applications such as industrial automation, sen-

sor data transfer, heavy vehicles like mine trucks, fork lifts, wind turbines, trains and ships.

In car applications the focus is primarily on short-range communication and the need for antennas to be as small and as cheap as possible, whereas in the industrial sector the need is for high reliability, protection against vandalism, high electrical performance (gain, VSWR) and the need to resist the impact of vibration, water, salt, dust and chemicals.

Antennas are used for mobile communication, WiFi, ZigBee/Bluetooth, WiMAX or RFID applications. There is a large variety of existing products that focus on the car industry and these products have been used in the industrial environment as well. However, there are often issues with both electrical performance and mechanical stability.

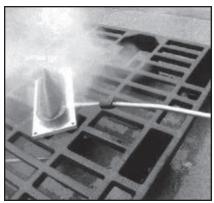
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▲ Fig. 1 Water testing of SENCITY antenna.

#### **ANTENNA SPECIFICATIONS**

The SENCITY® SWA-0825/360/5/30/DFRX30 antenna addresses these issues. It measures 145 by 100 by 40 mm and can operate in a temperature range of -40° to +85°C. In multiband its frequency ranges are 870 to 960 MHz, 1710 to 2170 MHz and 2400 to 2500 MHz. Impedance is 50  $\Omega$  and VSWR is 1.7. Polarization is linear, vertical and the maximum power is 100 W (CW) at 50°C.

In GPS/Galileo the frequency range is 1575.42 MHz  $\pm$  1.023 MHz, impedance is 50  $\Omega$  and VSWR is 1.6. The operating voltage is 3.0 to 5.0 VDC feed at the center conductor of the GPS antenna. Polarization is RHCP, gain LNA is 27 dB and the noise figure is 1 dB.

The antenna is 2002/95/EC (RoHS) compliant and also meets: IP68 (when correctly installed) EN50155, high current protection according to DB specifications (protection against short circuit of 40 kA) and electromagnetic compatibility (EN50121-3-2) standards.

These standards are particularly significant for industrial and transportation applications. It is important to put them into context for antennas operating outdoors and in harsh environments. A high level of salt in the air can cause corrosion of the product. It may be subject to shock and vibration and needs to be resistant to water and dust ingression, all of which are covered by EN 50155.

#### **IP RATINGS**

Most products meet an IP65 or even IP66 level, but vehicles



Fig. 2 Effect of galvanic corrosion.

are often hosed down with a highpressure cleaning device. This is the case when cleaning the roofs of trains. Thus, the higher IP rating of the SENCITY SWA-0825/360/5/30/ DFRX30 antenna is significant. *Figure 1* shows an antenna being water tested.

The antenna is also protected against high voltage impacts. This could be a lightning strike or, for trains, contact with the catenary line that can carries up to 28 kV. In fact, for the roof-top application of antennas on trains there has to be protection in case of a contact with the catenary line (UIC Code 533). If the catenary line breaks, it could damage the radome of the antenna and detach the metallic radiator and the high voltage could create a fire inside the vehicle.

Another serious consideration when designing the new antenna was galvanic corrosion, which often reduces the lifetime of an installed product in an outdoor environment. *Figure 2* shows the effect of galvanic corrosion. Choosing the right material mix helps to reduce the corrosion effect. Thus, the SENC-ITY SWA-0825/360/5/30/DFRX30 antenna has been developed following the MIL-F-14072A (EL) standard with regards to surface combinations.

Other design considerations were fire and rain (and hail). With regards to the antenna's behavior in a fire, the design goal was to limit any toxic materials and to reduce the flammability of the product (NF F101-16, DIN 5510 or BS 6853). Also, trains running at up to 400 km/h or antennas on industrial vehicles will not stop running in bad weather, so the SENCITY antenna has passed tests against hail and rain.

#### **ACCESSORIES**

Cables, connectors, filters and the radio unit also have to meet



Fig. 3 The selection of the cable assembly for the antenna is critical.

strict requirements. As a specialist for connector solutions, HUBER+SUHNER provides a particular solution for the contact between connector and radiator. It avoids completely the soldering process to guarantee optimal breakout.

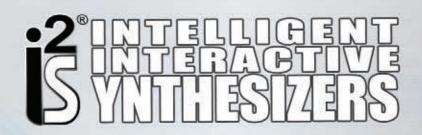
The selection of the cable assembly (shown in *Figure 3*) is also significant. Usually, the cable will be selected by the parameters related to loss and bending radius. Additionally, in the industrial and transportation environment, the shock and vibration requirements need to be considered. H+S offers EN 50155 railway approved diplexer products to split mobile applications from WiFi or WiMAX frequencies. Also, the integrated GPS antenna is protected by the mechanical design of the broadband radiator antenna.

#### **CONCLUSION**

Antennas in industrial and transportation applications are special products that have to meet tough requirements and the electrical performance and mechanical performance can be more important than price. For the SENCITY SWA-0825/360/5/30/DFRX30 tenna the design goal is to ensure high reliability and to cope with different installation scenarios. The product has been designed to withstand vandalism, corrosion, UV radiation, temperature drops, vibration, hail impact, rain, snow and cleaning over a long period without maintenance.

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Harmonic Suppression	15 dB (Typ.)				
	Offset	dBc/Hz.			
Wanted Marco Males	1 kHz	-93			
Typical Phase Noise	10 kHz	-95			
	100 kHz -110				
2422122222	Within 1 kHz	<22 mSec			
Settling Time	Within 10 Hz	<36 mSec			
Operating Temperature Range	-20 to +70 °C				

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External Reference	10 MHz				
Step Size	Programmable to 1 Hz				
Bias Voltage	+5/+3.3 V				
Output Power	+5.5 dBm (Min.)				
Spurious Suppression	60 dB (Typ.)				
Harmonic Suppression	10 dB (Typ.)				
	Offset	dBc/Hz.			
	1 kHz	-88			
Typical Phase Noise	10 kHz	-87			
	100 kHz	-100			
20010-0-000	Within 1 kHz	<10 mSec			
Settling Time	Within 10 Hz <20 ms				
Operating Temperature Range	-20 to +70 °C				

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Bandwidth	3000 MHz			
External Reference	10 A	MHz		
Step Size	Programma	ible to 1 Hz		
Bias Voltage	+5/+	3.3 V		
Output Power	+2 dBm (Min.)			
Spurious Suppression	60 dB (Typ.)			
Harmonic Suppression	20 dB (Typ.)			
	Offset	dBc/Hz.		
Total Share Males	1 kHz	-87		
Typical Phase Noise	10 kHz	-83		
	100 kHz -108			
ECONOMICS :	Within 1 kHz	<6 mSec		
Settling Time	Within 10 Hz <12 mSe			
Operating Temperature Range	-20 to +70 °C			

Patented Technology

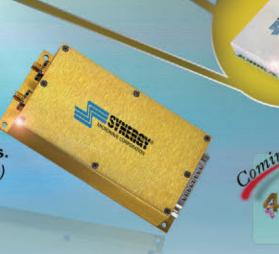
#### Programming Interface:

- -- 3.3V SPI (Standard)
- -- RS232

Also available in connectorized package with the following options.

- -- Internal reference (TCXO & OCXO)
- -- Divider output for lower bands
- -- Low phase noise option
- -- Low priase noise option

Available Frequencies Ranging Up To 8000 MHz





Visit http://mwj.hotims.com/23286-105 or use RS# 105 at www.mwjournal.com/info

For additional information, contact Synergy's sales and application team, 201 McLean Boulevard, Paterson, NJ 07504 | Phone: (973) 881-8800 Fax: (973) 881-8361 | E-mail: sales@synergymwave.com





#### FOR MORE NEW PRODUCTS, VISIT WWW.MWJOURNAL.COM/BUYERSGUIDE FEATURING VENDORVIEW STOREFRONTS



## RF/Microwave Products VENDORVIEW

Anatech Electronics announced it has launched three new websites that allow RF and microwave designers to more easily select from its families of RF and microwave filters and other components, and to order many products online. Anatech Microwave (AMC) (www. anatechmicrowave.com) covers the company's standard products. Anatech Electronics (AEI) (www.anatechelectronics.com) covers the company's custom products. AMCrf (www.anerch.com) is an e-commerce site that features specific standard products that can be ordered online. Anatech Electronics Inc.,

70 Outwater Lane, Garfield, NJ 07026

#### www.amcrf.com



# ICs, Modules, Subsystems & Instrumentation VENDORVIEW

Hittite's redesigned website includes crisp webpage designs and a dynamic homepage featuring full specifications for over 740 products across 20 product lines, press releases and featured articles. Comprehensive individual product "Splash Pages" containing in-depth product information and technical content are located on one easy to navigate page. Engineers will find improved Product Support and streamlined Quality & Reliability pages containing invaluable reference materials.

Hittite Microwave Corp., 20 Alpha Road, Chelmsford, MA 01824

www.hittite.com



### **AR's Bargain Corner**VENDOR**VIEW**

There is more than one way to get the quality equipment you need. If your budget is tight, the AR Bargain Corner is a good place to find some great values. Discontinued and demonstration equipment is available at a fraction of its original price. Visit AR's website to view the company's Bargain Corner.

AR RF/Microwave Instrumentation, 160 School House Road, Souderton, PA 18964

#### www.ar-worldwide.com



#### **Filtering Solutions**

K&L Microwave's redesigned website features improved product navigation and an integrated quote cart that enhances the customer's ability to review available products, simplify identification and specification of custom design solutions, and speed direct communication with the factory. Also, the new product catalog is available to download. The entire catalog or specific sections of interest can be downloaded by using provided

K&L Microwave, 2250 Northwood Drive, Salisbury, MD 21801

www.klmicrowave.com www.klfilterwizard.com

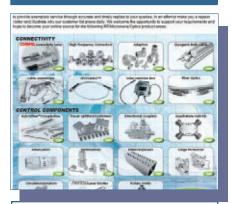


### RF Coaxial Cable Assemblies VENDORVIEW

The website features an easy-to-use product selector, broken down by cable type. Each cable type is available in a wide range of standard and custom lengths with a variety of connector choices. All connector/cable combinations can be reviewed using the company's Fast Quote tool, which also appears on each product page. The tool allows users to virtually design their own cable assemblies, with the ability to specify the cable type, length, connectors on both ends, and test requirements.

Electronic Assembly Manufacturing Inc., 126 Merrimack Street, Methuen, MA 01844

#### www.eamcableassemblies.com



# Component and Connectivity **Products**



Response Microwave Inc. announced the launch of its new website selection guide. The new site has migrated to a products focus and provides an overview of corporate capabilities and selection tables of the company's passive component and connectivity product offering that covers DC to 60 GHz. The site also offers application notes on the company's HYBRIDLINE series of drop-in quad hybrids and couplers.

Response Microwave Inc., 94 Jackson Road, Suite 110, Devens, MA 01434

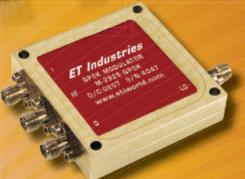
www.responsemicrowave.com

# Modulators Demodulators



#### **Vector Modulators**

- 360 Degree Phase Shift
- 0-20 dB Amplitude Adjustment
- Digitally Controlled



#### **QP5K Modulators**

- 0, 90, 180, 270 Degree Phase Shift
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- Built-in Low-Pass Filtering
- High Carrier Suppression



#### **BPSK Modulators**

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- Fast Switching Speed



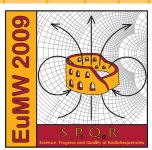
#### Demodulators

- I&Q Outputs With Linear Phase
- Wide Video Bandwidth
- Integrated Internal Low Noise Amplifier



Electromagnetic Technologies Industries, Inc.
50 Intervale Rd. Boonton, NJ 07005 U.S.A. Tel: 973-394-1719 Fax: 973-394-1710
email: sales@etiworld.com website: www.ETlworld.com

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  - European Microwave Conference (EuMC) 29 September 1 October 2009
  - European Wireless Technology Conference (EuWiT) 28 29 September 2009
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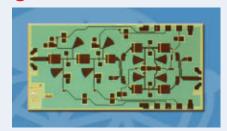
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#### **NEW WAVES:** SEMICONDUCTORS/MMICS/RFICS

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### GaAs HEMT LNA Die VENDORVIEW



The HMC-ALH508 is a three-stage GaAs HEMT MMIC low noise amplifier (LNA) chip that operates between 71 and 86 GHz, replacing the HMC-ALH459. The HMC-ALH508 features 13 dB of small-signal gain, 4.5 dB of noise figure and an output power of +7 dBm at 1 dB compression. The HMC-ALH508 operates from two supply voltages at 2.1 and 2.4 V respectively, while consuming only 30 mA of supply current. All bond pads and the die backside are Ti/Au metallized and the amplifier is fully passivated for reliable operation. This versatile LNA is compatible with conventional die attach methods, as well as thermocompression and thermosonic wire bonding, making it ideal for MCM and hybrid microcircuit applications.

Hittite Microwave Corp., Chelmsford, MA (978) 250-3343, www.hittite.com.

RS No. 217

### MMIC High Power Amplifier VENDORVIEW



This GaAs MMIC high power amplifier (HPA) features +37 dBm saturated output power and 27 dB small-signal

gain. This HPA, identified as XP1058-BD, uses a dual-sided bias architecture, covers 14.5 to 16 GHz, and achieves +44 dBm OIP3. The device is well suited for millimeter-wave military, radar, satellite and weather applications.

Mimix Broadband Inc., Houston, TX (281) 988-4600, www.mimixbroadband.com.

RS No. 257

#### Ultra-thin MOSFETs



Targeting battery-powered appliances and driver MOSFETs in DC/DC converters, the new N0100P, N0301P, N0302P and N0301N

MOSFETs, in a SOT-23F package, employ a flat lead structure instead of the conventional gull wing structure. This has made it possible to decrease the package height by 0.1 mm, thus enabling designers to realize a smaller design footprint. This flat lead structure also means that the packages of the new MOSFETs are capable of carrying larger chips, yet can still provide the high current capabilities of up to 4.5 A (N0301N). A 20 percent reduction on-resistance compared to existing MOSFETs is achieved. The new devices include three P-channels and one N-channel MOSFET enabling designers to choose the best option depending on the specific system.

NEC Electronics (Europe) GmbH, Düsseldorf, Germany +49 (0) 211 65 03 0, www.eu.necel.com.

RS No. 218

#### Two-way Power Dividers VENDORVIEW



These ten new low cost SMD type two-waydivider/splitter/combiners are designed for LTE and WiMAX frequencies. It is now proposed to have 2.6 GHz for Europe, 1800 to 2000 MHz for China, and 700 MHz for US LTE bands. PD09C2 (700 to 960 MHz), PD18C2 (1.7 to 1.9 GHz), PD20C2 (1.9 to 2.2 GHz), PD23C2 (2.2 to 2.4 GHz), and PD26C2 (2.5 to 2.7 GHz) has been released in an industry standard SOIC-8 type plastic package and is leadfree/RoHS compliant. All these devices will be available with SOT-23-6L package, which has the same footprint with SOT-6 and SOT-26. Cost advantage is increasingly becoming an important strategic advantage and this low cost divider can be the correct solution for many infrastructure telecommunication equipment manufacturers.

RFHIC Corp., Suwon, GyeongGi-do Korea 82-31-250-5011, www.rfhic.com.

RS No. 231

# Integrated Configurable Components

**VENDORVIEW** 

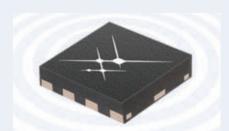
RFMD has extended its portfolio of integrated configurable components to include products for the cellular repeater and Wireless Local Area Network (WLAN) markets. The new integrated configurable components include the RF2057 RF synthesizer with integrated mixers and the RF2059 RF transverter. RFMD's integrated configurable components deliver unmatched levels of flexibility and functional integration to designers of radio systems. By integrating multiple common RF functions into highly integrated, size-reduced packages, the integrated configurable components enable designers to develop radio systems that operate

over a wide dynamic range and across a broad range of frequencies and channel bandwidths. The RF2057 and RF2059 join the RF2051, RF2052 and RF2053, which were introduced in April 2008 and have been adopted in markets as diverse as cellular, defense and broadband cable systems.

RFMD, Greensboro, NC (336) 664-1233, www.rfmd.com.

RS No. 256

#### PHEMT GaAs IC SP3T Switch



This pseudomorphic high electron mobility transistor (PHEMT) gallium arsenide (GaAs) integrated circuit (IC) SP3T switch is designed for 0.1 to 6 GHz. The SKY13317-373LF symmetric switch offers low insertion loss and high isolation with a 44 percent reduction in size than SKY13309-370LF. Featuring higher overall transmit efficiency and linearity, less board space is used with greater design/layout flexibility, equating to a small and thin end product. Appropriate for high volume, consumer products — end users will also discover better linearity and a clearer signal. The SKY13317-373LF is currently being used with wireless local area network (WLAN) and Bluetooth® combo chipsets.

Skyworks Solutions Inc., Woburn, MA, (781) 376-3000, www.skyworksinc.com.

RS No. 219

#### **RF Power Transistors**



HVVi Semiconductor introduces the HVV1011-500, the latest in its family of extremely rugged L-band (1030 to 1090 MHz) RF power transistors aimed at IFF, TCAS and transponder/interrogator markets. This robust 50 V device achieves output power over 500 W P1dB providing 19 dB gain and 50 percent drain efficiency under the following pulse condition (50  $\mu s$  P.W., 5 percent D.C.), while withstanding industry leading output load mismatch tolerance of 20:1 VSWR. The HVV1011-500 is a single-ended pulsed power transistor assembled in an HV800, two-lead, bolt-down, metal flanged package with LCP lid. HVVi Semiconductors Inc.

Phoenix, AZ (480) 776-3800, www.hvvi.com.

RS No. 255

# MICROVAVE SWITCHES NOW! 100 MILLION CYCLES

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#### **Components**

### Four-way Power Divider VENDORVIEW



Model AM-900PD1196 is a four-way power divider designed for applications such as wireless and industrial scientific and medical (ISM)

that operate between 800 to 1000 MHz. The module splits an input signal into four separate outputs, and features low insertion loss and excellent amplitude and phase balance. The model AM900PD1196 operates over a frequency range of 800 to 1000 MHz, with insertion loss of 1.5 dB or less, isolation of at least 25 dB, amplitude balance of 0.3 dB or less, and phase balance of 5 deg, or less. Size:  $4^{\rm w} \times 2.15^{\rm w} \times 1^{\rm m}$ .

Anatech Microwave, Garfield, NJ (201) 772-4242, www.anatechmicrowave.com.

RS No. 220

#### **E-band Components**



The newly developed E-band (WR-12 waveguide band) component family enables the rapid development of short-haul communication links operating license-free from 71 to 86 GHz. The component family includes oscillators, multipliers, low noise and power amplifiers, sub-harmonically pumped mixers and up-converters, filters and diplexers. All products are available as separate components or combined as integrated assemblies.

Ducommun Technologies Inc., Carson, CA (310) 847-2859, www.ducommun.com.

RS No. 221

#### Temperature Variable Chip Attenuator





The AN7 is a new solution for temperature compensation with an SMT planar style chip design. This

new AN7 offers a small 0805 package size for TVA line and has excellent frequency response from DC to 6 GHz. The AN7 is suitable for high volume, pick & place and targeted for telecom and WiMAX applications. The AN7 variable attenuator is available in designs of 1

through 6 dB in one dB increments with temperature attenuation coefficients (TCA) of -.003 through -.009, dB/dB/deg C and an operating temperature range of -55° to +125°C. Size:  $0.080"\times0.050".$ 

EMC Technology, Stuart, FL (772) 286-9300, www.emct.com.

RS No. 222

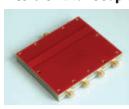
#### **Voltage-controlled Oscillator**

The RP-148258-01 model is designed to meet the stringent performance requirements of the aerospace industry. This model is compliant with MIL-PRF-38534 specification essential to high reliability, military and space applications. The operating frequency range is 1420 to 2500 MHz with an operating temperature range of -40° to +85°C. Tuning voltage is 1.85 to 12.65 V DC with 3.4 to 4.0 dBm power output. Modulation bandwidth is 5.5 MHz and typical phase noise is -96 dBc/Hz at 10 kHz.

Emhiser Research Inc., Verdi, NV (775) 345-0461, www.emhiser.com.

RS No. 223

#### 4 to 6 GHz RF Coupler



The low cost C P S 4 0 6 0 - 4 four-way reactive power divider/combiner has a frequency range of 4 to 6 GHz, which has been developed

for splitting or combining four RF-signals in phase while providing isolation between the four signals. It has a maximum insertion loss of 0.9 dB (over 6 dB), isolation > 20 dB, comes in a small package measuring 85 by 70 by 10 mm and operates within the commercial ambient temperature range of 0° to +70°C. The configuration is a four-way in phase splitter/combiner with a maximum matched input power of 2 W and an impedance of 50  $\Omega$ .

eubus GmbH, Munich, Germany +49(0) 89 4522 57811, www.eubus.net.

RS No. 224

## Solid-state Switches VENDORVIEW



The 50S-1820 and 50S-1821 are the latest innovations in JFW's high power solid-state RF switches. The 50S-1820 is capable of switching 100 W of RF power from 800 to 2700 MHz (cold switch), while the 50S-1821 will switch 75 W from 800 to 3000 MHz. Both switches boast 10 microsecond switching speeds and a minimum isolation of 55 dB. Available with SMA, N, BNC or TNC connectors.

JFW Industries, Indianapolis, IN (317) 887-1340, www.jfwindustries.com.

RS No. 225

#### 808 MHz Bandpass Filter



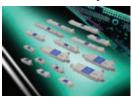
KR Electronics introduces part number 2907, a small surfacemount 808 MHz bandpass

filter. The filter has a typical insertion loss of 3 dB and minimum 3 dB bandwidth of 25 MHz (35 MHz typical). The filter is supplied in a surface-mount package measuring  $0.52" \times 0.84" \times 0.44"$ . The filter can be customized for other center frequencies and bandwidths.

KR Electronics Inc., Avenel, NJ (732) 636-1900, www.krfilters.com.

RS No. 226

#### **Directional Coupler Range**



The new LYNX directional couplers cover the frequency range from 500 MHz to 18 GHz and are suitable for use in a wide va-

riety of commercial and military applications. They can be specified with a choice of SMA-type or N-type female connectors and are available with coupling values of 5, 6, 7, 10, 15, 20 or 30 dB. Featuring insertion losses as low as 0.4 dB, the couplers offer VSWR values from 1.2:1 to 1.6:1, a frequency sensitivity of  $\pm 0.7$  dB or  $\pm 1.0$  dB, and a directivity of 10, 12, 18 or 20 dB. The couplers have an operating temperature range of -55° to 85°C and are suitable for integration into mobile-phone infrastructure or satellite communications equipment.

Link Microtek Ltd., Basingstoke, UK +44 (0)1256 355771, www.linkmicrotek.com.

RS No. 227

#### Band Reject Filter



Lorch model 6BRX-2257/X65-SR is a band reject filter with a center frequency of 2257 MHz. Insertion loss is 1 dB from 1400 to 2100 MHz and 3 dB from 2375 to 5500 MHz. Rejection is 40 dB from 2225 to 2290 MHz. Operating temperature is -40° to +85°C.

Lorch Microwave, Salisbury, MD (410) 860-5100, www.lorch.com.

RS No. 228

#### **Reactive Power Splitters**



Model Dx-19FN series is a collection of low cost two-, three- and four-way wideband reactive power splitters. The new series has been designed to a bandwidth of 700 to 2700 MHz, to

# Phase Locked And Crystal Oscillators

#### Features:

- Band Coverage from VHF through Ka-Band
- Proven Performance in Various Applications
- Single and Dual Loop Models available with Internal and External Reference
- Small Modular Assemblies from 2.25" x 2.25" x 0.6"
- · High Power and Low Harmonic Options available







	E		Typical Phase Noise				Output	Output		
Model	Frequency Range	Туре	10	100	1K	10K	100K	1M	Output Frequency	Power (dBm, Min.)
XTO-05	5-130 MHz	Ovenized Crystal	-95	-120	-140	-155	-160	100	100 MHz	n
PLD	30-130 MHz	P.L. Crystal	-95	-115	-140	-155	-155	1-57	100 MHz	13
PLD-1C	130-1000 MHz	P.L. Mult. Crystal	-80	-100	-120	-130	-135	-	560 MHz	13
BCO	.100-16.5 GHz	P.L. Single Loop	-65	-75	-80	-90	-115		16.35 GHz	13
VFS	1-14 GHz	Multiple Freq. Dual Loop	-60	-75	-110	-115	-115	- 33	12.5 GHz	13
DLCRO	.8-26 GHz	P.L. CRO Dual Loop	-60	-85	-110	-115	-115	-138	10 GHz	13
PLDRO	2-40 GHz	P.L. DRO Single/Dual	-60	-80	-110	-115	-120	-145	10 GHz	13
CP	.8-3.2 GHz	P.L. CRO Single Loop	-80	-110	-120	-130	-130	-140	2 GHz	13
CPM	4-15 GHz	P.L. Mult. Single Loop	-60	-90	-105	-110	-115	-130	12 GHz	13
ETCO	.1-24 GHz	Voltage Tuned CRO	A. S	SE IN	-70	-100	-120	-130	2-4 GHz*	13
* Octave b	oand.	题 对	Z. E	35 3		THE	100	-58	- 150	

For additional information of technical support, please contact our Sales Department at (631) 439-9220 or e-mail components@miteq.com



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#### New Products

include the common cellular, Wi-Fi and WiMAX frequencies, now being incorporated in indoor distributed antenna systems. An added benefit of this series is the guaranteed PIM performance of <-150 dBc when tested with two 20 W test signals. The extremely high reliability required of DAS systems is most easily met with a passive network approach.

Microlab, Wireless Telecom Group, Parsippany, NJ (973) 386-9696, www.wtcom.com.

RS No. 252

## Precision Phase Shifters VENDORVIEW



These precision coaxial phase shifters are designed for 1 to 5 GHz and 1 to 12.4 GHz that provide a high level of accuracy with maximum phase shift of 180 deg. The model 3752 cov-

ers 1 to 5 GHz and provides 180 deg. of phase shift at 1 GHz. It has insertion loss of 0.5 dB or less and maximum VSWR of 1.25. The model 3753B covers 3.5 to 12.4 GHz and provides 180 deg. of phase shift at 3.5 GHz. It offers insertion loss of 0.7 dB and maximum VSWR of 1.4. Both models can handle 200 W average and 1 kW peak power, have accuracy of  $\pm 0.5$  dB/GHz, use Type N connectors, and have a digital dial display of phase shift.

Narda Microwave-East, Hauppauge, NY (631) 231-1700, www.nardamicrowave.com/east.

. RS No. 229

# Wi-Fi Bandpass Filter VENDORVIEW

Reactel part number 8CX9-2436.5-X60N11 is a bandpass filter suitable for IEEE 802.1



applications. This unit is centered at 2436.5 MHz and has a minimum passband of 60 MHz and insertion loss of less than 0.75 dB. With high selectivity and a weather proof exterior, this unit is a great fit for your application. **Reactel Inc.**,

Gaithersburg, MD (301) 519-3660, www.reactel.com.

RS No. 230

#### **Programmable Step Attenuators**



RLC Electronics' PA Series Attenuators are binary programmable step attenuators designed to operate from DC to 20 GHz. Two basic models offer attenuation ranges of 15 and 70 dB. Control is in standard format: 1-2-4-8. The attenuators are available with failsafe or latching operation, 12 or 28 V coils and optional TTL drivers, with a choice of frequency ranges. RLC Electronics Inc., Mount Kisco, NY (914) 241-1334, www.rlcelectronics.com.

Right Angle Adapters
VENDORVIEW

The UG-27 C/U is a right angle adapter that features solderless construction. The solder-



free construction offers dependability equal to a straight plug while achieving 90° bends. The solder-free adapters also address RoHS compliancy issues by reducing lead content. The 50 ohm UG-27 C/Us perform efficiently up to 11 GHz and are rated for operating voltages of 1000 V RMS. The right angle adapters have a maximum dielectric withstanding voltage of 2000 V RMS at 60 Hz at sea level. They are designed for a temperature range of -65° to +165°C and meet interface standards in accordance with MIL-STD-348. VSWR is 1.15 from DC to 6 GHz, and 1.35 from 6 to 11 GHz.

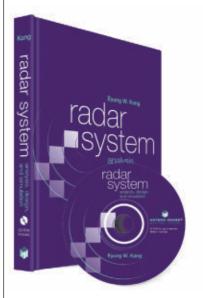
San-tron Inc., Ipswich, MA (978) 356-1585, www.santron.com.

RS No. 233

#### 60 GHz Converter



The FC1001V/00 broadband converter is a versatile building block for 60 GHz applications. It combines an up-converter and a down-converter in a single unit. Both operate independently and can thus be used for both frequency



# Radar System Analysis, Design and Simulation Eyung W. Kang

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RS No. 232



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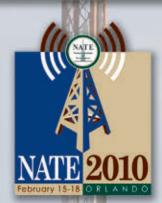
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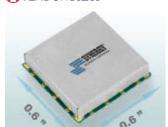


multiplexed and time multiplexed applications. The converter has the advantage of using external LO sources, with the user having full control of phase noise and frequency selection. Frequency multipliers (x8) are integrated in both the up-converter and the down-converter. The LO injection is done at 7 GHz with +0 dBm power. Other features include: 57 to 63 GHz RF bandwidth, > 1 GHz IF bandwidth and +10 dBm typical output power. Applications include point to point or multipoint radio, EW, secure communication and measurement.

Sivers IMA AB, Kista, Sweden +46-8-7036800, www.siversima.se.

RS No. 234

## Surface-mount Intelligent Synthesizers VENDORVIEW



The MFSH series of tiny surface-mount intelligent synthesizers with on-board microcontroller allows for self-programmable fixed frequency or wideband signal generation from a 0.6" package. Several models are available starting with frequencies from 1350 to 6500 MHz. Models are available with step size starting at 500 kHz.

Synergy Microwave Corp.,

Paterson, NJ (973) 881-8800, www.synergymwave.com.

RS No. 251

#### **Surface-mount Feedthrus**



This mini surface-mount 50 ohm feedthru is based on Thunderline's successful initial SMT Bell Pin offering. This new product has been designed to emulate the existing design, but will be one third less in size and will be built with a smaller pin. The use of a smaller pin its new mini surface-mount package will enable Thunderline customers to use this part in both J-band and K-band frequency ranges. Based on initial expectations Thunderline an-

ticipates this part will perform to limits somewhere between 22 and 25  $\,$  GHz.

Thunderline-Z, Hampstead, NH (603) 329-4050, www.thunderlinez.com.

RS No. 235

#### **Voltage-controlled Oscillator**



This RoHS compliant voltage-controlled oscillator (VCO) model ZRO1560A1LF is designed for L-band. The ZRO1560A1LF operates at 1560 MHz with a tuning voltage range of 0 to 5 VDC. This VCO features a typical phase noise of -121 dBc/Hz at 10 kHz offset and a typical tuning sensitivity of 0.7 MHz/V. The ZRO1560A1LF is designed to deliver a typical output power of 0 dBm at 5 VDC supply while drawing 18 mA (typical) over

the temperature range of -40° to 85°C. This VCO features typical 2nd harmonic suppression of -30 dBc and comes in Z-Comm's industry standard MINI-16 package measuring  $0.5" \times 0.5" \times 0.22$ ".

Z-Communications Inc., San Diego, CA (858) 621-2700, www.zcomm.com.

RS No. 236

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DC-2 GHz \$395 ea.



2 W SMA 5 W SMA 5 W Type-N			Attenua	tion (dB)
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\$1W2	S1W5	N1W5	1	±0.40
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S4W2	S4W5	N4W5	4	±0.40
S5W2	S5W5	N5W5	5	±0.40
S6W2	S6W5	N6W5	6	±0.40
S7W2	S7W5	N7W5	7	-0.4, +0.9
S8W2	S8W5	N8W5	8	±0.60
S9W2	S9W5	N9W5	9	-0.4, +0.8
S10W2	S10W5	N10W5	10	±0.60
S12W2	S12W5	N12W5	12	±0.60
S15W2	S15W5	N15W5	15	±0.60
S20W2	S20W5	N20W5	20	-0.5, +0.8
S30W2	S30W5	N30W5	30	±0.85
S40W2	S40W5	N40W5	40	-0.5, +1.5

\*At 25°C includes frequency and power variations.



To order Attenuators as RoHS, add + to base model No. Example: BW-S1W2+ Adapters available as RoHS, see web site.





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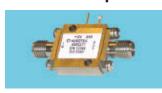
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#### **Amplifier**

#### Miniature RF Amplifier



Herotek's model A402277 operates in a frequency range from 26 to 40 GHz and provides the user with an amplifier in its small package "1C" (size:  $0.62^{\circ} \times 0.66^{\circ} \times 0.22^{\circ}$ ). It offers gain of 30 dB and gain variation of  $\pm 2.0$  dB. Noise figure of 6.0 dB and P Out at 1 dB

and compression is +16 dBm. Nominal DC current at 12 V is 400 mA. Application includes telecom infrastructure MW Radio and VSAT.

Herotek Inc., San Jose, CA (408) 941-8399, www.herotek.com.

RS No. 237

#### **Antennas**

#### Flat Panel Antenna



Model FPA13-2.2R/1533 is a small (195 by 163 by 12.6 mm) flat panel antenna with directional beam pattern, 40° azimuth by 40° elevation. Its frequency range is 2.2 to 2.35 GHz and it has 13 dBi gain with right hand circular polarization. It is designed for use within an information system for telemetry applications in the defence and surveillance industries. It can be incorporated into an existing multisector framework, and conforms to

existing technical and environmental specifications. The antenna can be used in a range of applications, providing operators with flexibility when designing network systems, and may also be used in industries where data is commercially valuable.

Cobham Antenna Systems, Microwave Antennas, Cheveley, Newmarket, UK +44 (0) 1638 732177, www.cobham.com/antennasystems.

RS No. 238

#### **Broadband Horn Antennas**



Cobham Sensor Systems' H-1498 series broadband linear horn antennas provide superior performance for use in a wide variety of laboratory, commercial and military applications. With excellent input VSWR over the 2 to 18 GHz band, these antennas provide high gain across the frequency range and consistent pattern performance. They have become a laboratory

standard as a reference horn in anechoic chambers and outdoor ranges. The H-1498 is available with SMA female connector (standard) and TNC female connector (H-1498T). A further option is a radome/aperture cover (H-1498R) for outdoor use.

Cobham Sensor Systems, Lansdale, PA (215) 996-2416, www.cobhamdes.com.

RS No. 239

#### **GPS Antenna Module**

The A1035-H antenna module, with a footprint of 16.5 by 30.5 mm², is based on the company's A1084 GPS receiver. It is designed around the SiRFstar III GPS chip and is optimized for use with passive antennas. With the onmodule antenna tuned to the receiver, a high level of sensitivity is



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	(dBm)	(MHz)	(dB)	(dB)	(Qty. 10)
MCA1-85L	4	2800-8500	6.0	35	9.45
MCA1-12GL	4	3800-12000	6.5	38	11.95
MCA1-24	7	300-2400	6.1	40	5.95
MCA1-42	7	1000-4200	6.1	35	6.95
MCA1-60	7	1600-6000	6.2	30	7.95
MCA1-85	7	2800-8500	5.6	38	8.95
MCA1-12G	7	3800-12000	6.2	38	10.95
MCA1-24LH	10	300-2400	6.5	40	6.45
MCA1-42LH	10	1000-4200	6.0	38	7.45
MCA1-60LH	10	1700-6000	6.3	30	8.45
MCA1-80LH	10	2800-8000	5.9	35	9.95
MCA1-24MH		300-2400	6.1	40	6.95
MCA1-42MH		1000-4200	6.2	35	7.95
MCA1-60MH		1600-6000	6.4	27	8.95
MCA1-80MH		2800-8000	5.7	27	10.95
MCA1-80H	17	2800-8000	6.3	34	11.95
		" x (W) 0.250"	x(H)0	.080"	
U.S. Patent	#7,027.	795			

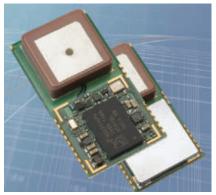




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#### New Products



achieved. Furthermore, the A1035-H has been especially designed for an extremely low current draw (an average of 85 mW in tracking mode), fulfilling the latest requirements for more integration and cost-saving solutions.

Vincotech GmbH, Unterhaching, Germany +49 (0) 89 8780 670, www.vincotech.com.

RS No. 240

#### Material

#### **RFID Tag**

MetalTagTM Impact is a Read-on-Metal EPC Gen 2 RFID tag. MetalTag Impact is constructed of a ruggedized outer coating, using a patent-

ed elastomer with a robust exoskeleton. The tag is ideal for challenging environmental conditions, such as severe weather, wide temperature variations, direct and prolonged UV exposure and significant physical impact. Its small form factor makes it amenable to a wide variety of surfaces often associated with asset tracking and supply chain applications. The tag is also available with an optional metallic ground plane for read on liquid applications, custom color coded labels and pre-encoded bar codes.

Emerson & Cuming Microwave Products Inc., Randolph, MA (781) 961-9600, www.eccosorb.com.

RS No. 241

#### antenna design quickly and reliably. Validated, parametric models of the initial design are exported seamlessly into CST MICROWAVE STUDIO or FEKO, where customization can be done in tried-and-trusted analysis tools. Antenna Magus will expand both the number of antennas it can design and export, as well as in the number of analysis tools it interfaces with. It will aid antenna design engineers, EMC engineers requiring antenna models and system integrators who require antenna models for antenna placement studies.

Computer Simulation Technology (CST) AG, Darmstadt, Germany

+49 6151 7303 0, www.cst.com.

RS No. 242

#### Software

#### **Antenna Design Tool** VENDORVIEW

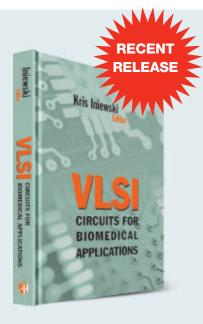


Antenna Magus is an expert system for antenna design with a large database of antennas that makes it suitable for a broad range of applications. Its feature set is targeted at aiding engineers to get to the customization phase of an

#### **Location Finding Software**



New location finding software for the IZT R3000 receiver series for both commercial and military applications has been introduced. It is a low-cost method that enables users to add location finding capabilities to their monitoring stations. Using cost efficient Time-Difference-Of-Arrival (TDOA) methods, the software resides on a central station and connects multiple IZT R3000 receivers in different remote locations. Comparing their receive signals results in accurate delay measurements that are then used to derive the location of the signal's source. Re-



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Kris Iniewski, Editor

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IZT, Erlangen, Germany
+49/9131/4800-181, www.izt-labs.de.

RS No. 243

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AR RF/Microwave Instrumentation, Souderton, PA (215) 723-8181, www.ar-worldwide.com.

RS No. 254

#### 2.45 GHz Radio Modem



The MiniTrans 2401 is an OEM 2.45 GHz radio modem for data rates up to 25 Mbit/s for point data transfer with

digital input and digital output. Spread spectrum transmission is possible with the integrated noise generator ( $\sim 10~\mathrm{MHz}$ ) or an external signal source, leading to a secure, rugged and tap-proof link. It is also suitable for UWB applications.

Heuermann HF-Technik GmbH, Aachen, Germany +49 (0) 241 6009-52108, www.hhft.de.

RS No. 216

## SSPA and Transmitter Systems VENDORVIEW

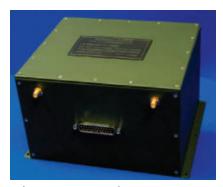


MITEQ introduces new medium power X-band rack-mount solid-state power amplifier (SSPA) and transmitter systems. The new PA-R Model series is an SSPA rack-mounted system designed using a modular approach to provide flexible solutions to meet a variety of applications. This approach allows for simple redundant configurations, as well as higher-power phase combined configurations. These SSPA systems provide for over-temperature, over-current and high output VSWR safety protection.

MITEQ Inc., Hauppauge, NY (631) 436-7400, www.miteq.com.

RS No. 245

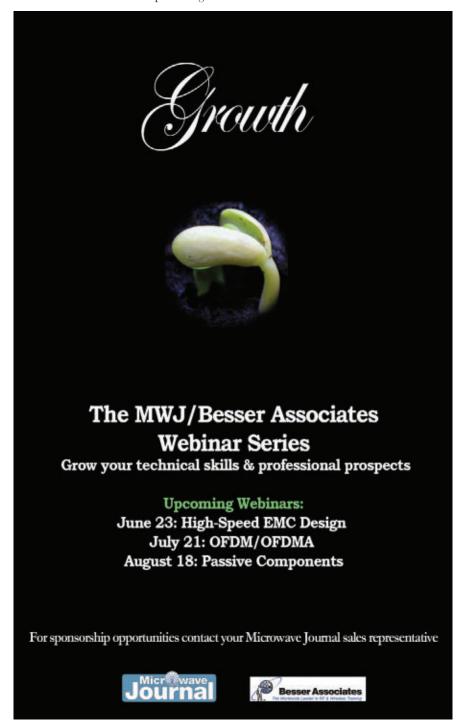
#### Tactical Transceivers



Achieving cosite interference protection in environments of multiple VHF/UHF tactical transceivers is now a reality through Pole/Zero's introduction of the Mega-Pole high power (50 W) electronically tunable filter product line. When placed between the antenna and transceiver, the Mega-Pole yields excellent selectivity with minimal insertion loss, even in frequency hopping modes of operation.

Pole/Zero Corp., West Chester, OH (513) 870-9060, www.polezero.com.

RS No. 246







DC to 18 GHz from \$6895 M STOCK ea. (qty.1-9)

Strength, ruggedness, and reliability...supercharged! That's what you get when you choose Mini-Circuits ultra-flexible precision test cables. Engineered to be a workhorse for your day-to-day test operations, these triple shielded cable assemblies are qualified to at least 20,000 bends, employ an advanced strain relief system, and are equipped with passivated stainless steel connectors, so you can rely on them to flex, connect and disconnect over and over and over again! They're so rugged, each test cable is backed by our 6 month guarantee\*! With low insertion loss and very good return loss, you can also rely on getting good performance over the wide DC-18 GHz band. Visit our website to choose and view comprehensive performance curves, data sheets, and environmental specifications.

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FLEX TEST CABLES			le to Male			
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CBL-2FT-SMNM+ CBL-3FT-SMNM+ CBL-4FT-SMNM+ CBL-6FT-SMNM+ CBL-15FT-SMNM+	SMA to N-Type SMA to N-Type SMA to N-Type SMA to N-Type SMA to N-Type	2 3 4 6 15	1.1 1.5 1.6 3.0 7.3	27 27 27 27 27	99.95 104.95 112.95 114.95 156.95	
CBL-2FT-NMNM+ CBL-3FT-NMNM+ CBL-6FT-NMNM+ CBL-10FT-NMNM+ CBL-15FT-NMNM+ CBL-20FT-NMNM+ CBL-25FT-NMNM+	N-Type N-Type N-Type N-Type N-Type N-Type	2 3 6 10 15 20 25	1.1 1.5 3.0 4.7 7.3 9.4 11.7	27 27 27 27 27 27 27 27	102.95 105.95 112.95 156.95 164.95 178.95 199.95	
Female to Male						
CBL-3FT-SFSM+ CBL-2FT-SFNM+ CBL-3FT-SFNM+ CBL-6FT-SFNM+	SMA-F to SMA-M SMA-F to N-M SMA-F to N-M SMA-F to N-M	2 3 6	1.5 1.1 1.5 3.0	27 27 27 27	93.95 119.95 124.95 146.95	
ARMORED CABLES		Ma	le to Male			

Frequency Range: DC-18 GHz, Impedance: 50 ohms Connector Type

Metric Sizes Available On Our Website

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#### Synthesizers

#### **SMT Frequency Synthesizer**

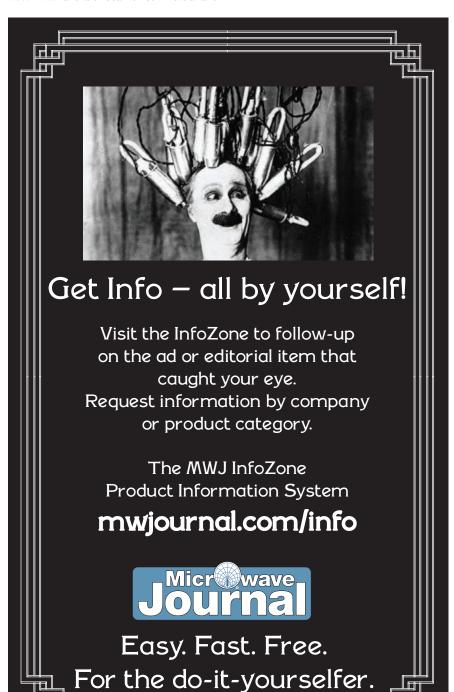
The CLX-500 phase-locked oscillator operates fixed at 500 MHz in surveillance radar applications. The CLX maximizes system performance with excellent phase noise (<-140 dBc/Hz at 1 kHz), +7 dBm output power and supply of +5 V DC at 120 mA, typical. The CLX Series is available in a surface-mount package,  $0.75^{\circ} \times 0.75^{\circ} \times 0.25^{\circ}$ . CLX units are available in custom frequencies from 200 to 4000 MHz and are ideal for commercial and



military systems requiring a fixed-frequency and exceptional performance.

EM Research Inc., Reno, NV (775) 345-2411, www.emresearch.com.

RS No. 247



#### Miniature Frequency Synthesizer



The SLSM5 is a new family of frequency synthesizers that operates to 12.5 GHz and covers up to octave bandwidths. This synthesizer features excellent phase noise (-95 dBc/Hz at 10 kHz at X-band) and excellent spurious performance (-60 dBc min). With 1 kHz steps and frequency controlled via convenient RS485 interface this synthesizer is a system friendly component. The SLSM5 operates on an external 10 MHz input or an internal TCXO. Only a single +5 V supply is needed to power this miniature  $(2.5"\times\hat{2}.\hat{5}"\times0.6")$  unit. This high performance source is suitable for applications in communications, radar and instrumentation. In its class, this is an exciting new product with many advanced features at a low cost.

Luff Research, Floral Park, NY (516) 358-2880, www.luffresearch.com.

RS No. 248

# Tunable Narrow Bandwidth Synthesizers VENDORVIEW



For applications requiring tunable bandwidths of center frequency ±10 percent (or less), Mini-Circuits'

custom narrowband frequency synthesizers can be specified to 6010 MHz with low phase noise, low harmonics, and spurious levels of -85 dBc or better. Available with customer-specified step sizes, these high performance synthesizers are housed in compact surface-mount or connectorized packages. Typical settling times of 30 ms or less and harmonics of -20 dBc or better.

Mini-Circuits, Brooklyn, NY (718) 934-4500, www.minicircuits.com.

RS No. 249

#### **Ultra-low Noise Synthesizer**



PTS introduces the fast-switching ultra-low noise LN310 synthesizer, an upgrade to the current PTS 310 product line. The synthesizer covers the 1-310 band with 0.1 Hz resolution and < 5  $\mu$ s frequency switching

#### Constant Impedance

#### 10 to 3000 MHz



 $^{\$}3^{95}$  from  $3^{95}$  ea.qty.10-49

Voltage Variable Attenuators (VVAs) deliver as high as 40 dB attenuation control over the 10 MHz through 3.0 GHz range. Offered in both 50 and 75  $\Omega$  models these surface-mount and coaxial low-cost VVAs require no external components and maintain a good impedance match over the entire frequency and attenuation range, typically 20 dB return loss at input and output ports. These high performance units offer insertion loss as low as 1.5 dB, typical IP3 performance as high as +56 dBm, and minimal phase variation low as 7°.

Mini-Circuits VVAs are enclosed in shielded surface-mount cases as small as 0.3" x 0.3" x 0.1". Coaxial models are available with unibody case with SMA connectors. Applications include automaticlevel-control (ALC) circuits, gain and power level control, and leveling in feedforward amplifiers. Visit the Mini-Circuits website at www.minicircuits.com for comprehensive performance data, circuit layouts, environmental specifications and real-time price and availability.

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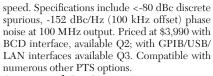
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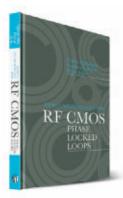






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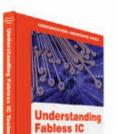
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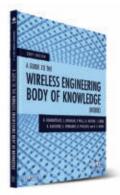
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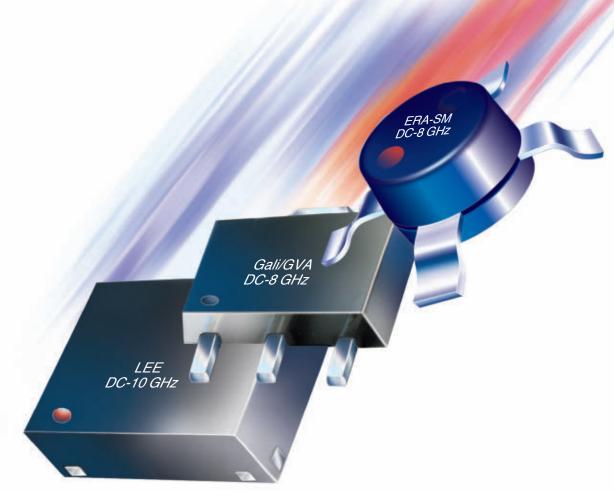
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#### Career Corner

# Now: Shaping the Future of Microwave Engineering Jobs, Shaping the Future Economy

The RF/microwave engineering community is relatively safe these days. Demand for skilled RF engineers far exceeds the supply and people's jobs are safe... for now.

Looking at the big picture, it is inevitable to realize that the short supply of microwave engineers endangers the existence of those vacant positions and also of those currently staffed. RF engineering and other science jobs can disappear in an offshoring process, as has occurred with production, service and software jobs. Those fields allow cheap labor, R&D and science centers to migrate to wherever technology talent is available. Every microwave engineer job not filled in this country will eventually be filled somewhere else. Every lost engineering job takes away from demand for other positions as well. Unlike the past millennium, the United States is not selfsufficient anymore. It pays hard cash for foreign labor through import of products and services, which it cannot produce domestically. When science and research centers migrate offshore as well, this country will have nothing to base its economy on.

Microwave engineering is core technology and is already essential infrastructure in many industry sectors (communications, defense, medical, automotive, transportation, retail, etc.). We are now in the midst of a race for next generation technologies laying microwave infrastructure in all those markets and more. Extensive R&D efforts occurring now across the globe are also drawing a new map of global technology powers.

Losing technology leadership in the international arena will result in a long-term impact on the country's economy and hence security and stability.

The goal is to ensure the availability of science and engineering resources needed to sustain leadership in technology and innovation. Microwave engineering is our agenda. The

same approach should be adopted in other science and technology sectors in order to protect all strategic technology and education assets while we still have them.

Isaac Mendelson ElectroMagneticCareers.com Isaac@ElectroMagneticCareers.com

#### **RF/Microwave Candidate Pool**

The shameful state of the RF/microwave candidate pool has again raised its ugly head. This reminds me of the recession from the early 1970s when we had very few universities, colleges and trade schools turning out graduates with skills in the electromagnetic field.

Our industry suffers when corporations are not supporting the educational systems to ensure a healthy crop of new technologists every year.

Now that we are in a recession, we still have thousands of career opportunities that we have no candidates to apply. The result is that contracts are late on delivery and our future through innovation is stalled.

It is up to industry and the educational system to keep the RF/microwave industry strong; they have to work together to support studies in this sector.

In the '70s, corporations like Raytheon, M/A-COM and many others supported several universities to develop microwave/RF studies. That solved the problem for a few years, but now we are back to square one.

If you are working with a company in this sector speak with your management and speak with your university, college, or trade school to promote education in the RF/microwave field.

I've seen similar times of shortage in engineering power and there is much to learn from what was done then.

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Model	Freq. (GHz)	Gain (dB) Typ.	NF (dB) Typ.	IP3 (dBm) Typ.	P <sub>out</sub> @ 1dB Comp. (dBm) Typ.	DC Volts (V)	Curren (mA) Max.	t Price \$ea. (1-9)
Lengtl	h: 0.74" x (W)				iyp.	( • )	wax.	(1 3)
ZX60-2510M	0.5-2.5	12.9	5.4	+28.8	17.1	5.0	95	59.95
ZX60-2514M	0.5-2.5	16.4	4.8	+30.3	16.5	5.0	90	59.95
ZX60-2522M	0.5-2.5	23.5	3.0	+30.6	18.0	5.0	95	59.95
ZX60-3011	0.4-3.0	12.5	1.7	+31.0	21.0	12.0	120	139.95
ZX60-3018G	0.02-3.0	20.0	2.7	+25.0	11.8	12.0	45	49.95
ZX60-4016E	0.02-4.0	18.0	3.9	+30.0	16.5	12.0	75	49.95
ZX60-5916M	1.5-5.9	17.0	6.4	+28.3	14.4	5.0	96	59.95
ZX60-6013E	0.02-6.0	14.0	3.3	+28.7	10.3	12.0	50	49.95
ZX60-8008E	0.02-8.0	9.0	4.1	+24.0	9.3	12.0	50	49.95
ZX60-14012L	0.0003-14.0	12.0	5.5	+20.0	11.0	12.0	68	172.95
ZX60-33LN	0.05-3.0	17.6	1.1	+30.0	17.5	5.0	80	79.95
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100	gth: 1.20" x (W							
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ZX60-2411BM	0.8-2.4	11.5	3.5	45.0	24.0	5.0	360	119.95
ZX60-2531M	0.5-2.5	35.0	3.5	+26.1	16.1	5.0	130	64.95
ZX60-2534M	0.5-2.5	38.0	3.1	+30.0	17.2	5.0	185	64.95
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*Typical Specifications:	ADE-1	ADE-2	ADE-11X
Frequency LO/RF (MHz)	0.5-500	5-1000	10-2000
Frequency LO/IF (MHz)	DC-500	DC-1000	5-1000
LO Level (dBm)	7	7	7
IP3 (dBm)	15	20	9
Conv. Loss (dB)	5.0	6.67	7.1
L-R Isolation (dB)	55	47	36
L-I Isolation (dB)	40	45	37
Dimensions: L.310"xW.220"xH	.162"	.112"	.112"
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Price \$ea. (Qty. 25)	2.49	2.49	2.49
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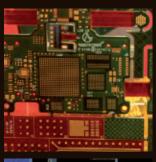




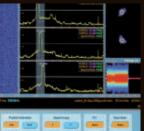






























#### **A**CROSS

- **4** The vector ratio of voltage to current, the reciprocal of admittance
- **9** Wideband gap III-V material used to produce broadband, high power amplifiers
- 11 Undesired changes in a waveform that result in spurious content of the signal
- **14** A device or impedance that terminates the output of a device
- **15** Loss of signal resulting from the insertion of a device in a transmission line (2 words)
- **16** Material typically used to produce high frequency, broadband PIN diodes
- 17 PA return loss under actual output drive levels (2 words)
- **18** Energy at integral multiples of the frequency of the fundamental signal
- 21 The ratio of the input signal to noise ratio to the output signal to noise ratio for a circuit or system (2 words)
  23 The process of varying the impedance seen by the

output of an active device to other than 50 ohms in

- order to measure performance parameters (2 words)
- **24** Measure of how much of the input power is usefully applied to the amplifier's output
- 25 The amount of power at which the amplitude of the output of a device or circuit is reduced by 1 dB from the expected small-signal gain

#### Down

- 1 Laterally diffused metal oxide semiconductor
- **2** Range of frequencies for which the amplifier gives "satisfactory performance"
- **3** The amount of electrical power converted to heat by a device (2 words)
- **5** The state of operation in which there is no interruption of the presence of a signal (2 words)
- **6** Undesired signals present at the output of a device under test that are neither harmonics nor intermodulation products
- **7** At a given point in a transmission system, the difference between the incident and reflected power (2 words)

- **8** The ratio between the amplitude of the output signal of a device or circuit compared to the amplitude of the input signal
- 10 Technique used to improve the linearity of amplifiers
- 12 The degree to which the impedance of a component differs from the transmission line or component to which it is connected
- **13** Amplifier class where the output filter blocks all harmonics to achieve very high efficiencies (2 words)
- 19 Amplifier configuration where the carrier amplifier is biased to operate in Class AB mode and the peaking amplifier is biased to operate in Class C mode to achieve higher efficiency
- 20 Metal Electrode Leadless Face package used for PIN diodes
- 22 Amplifier class widely used in SSB linear amplifier applications where low-distortion and high power-efficiency tend to both be very important (2 words)



#### CELEBRATING 2009: THE YEAR OF MMIX

2009 translates in Roman numerals to "MMIX." It only happens once, so Mimix Broadband is celebrating by declaring 2009... **the Year of MMIX**. During the year, we'll highlight key advances in our product portfolio, as well as pay tribute to other engineering feats – specifically the Seven Wonders of the Modern World as chosen by the American Society of Civil Engineers.

Toronto's CN Tower is a communications and tourist tower standing 553.33 meters (1,815.39 feet) tall. It is the tallest freestanding structure in the Americas and, amazingly, varies from true vertical accuracy by only 29 millimeters (1.1 inches) over the entire height of the tower. The CN Tower is a powerful communications tower for numerous radio and cellular media.

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#### MIMIX POWER AMPLIFIERS...TOWERING ABOVE INDUSTRY AVERAGES!

Description	Device	Frequency (GHz)	Gain (dB)	Gain Flatness (dB)	Output PIdB (dBm)	OIP3 (dBm)	Bias (mA @V)	Package (mm)
Power Amplifier	XP9003	1.6	38.0	+/-0.5	+43.0	-	2.9 A @ 9.0	40×36
Power Amplifier (QFN)	XPI035-QH	5.9-9.5	26.0	+/-1.0	+29.0	+39.0	500 @ 6.0	4×4
Power Amplifier (QFN)	XPI050-QJ	7.0-9.0	15.0	+/-0.5	+34.5 Psat	+48.0	I.2 A @ 8.0	6×6
Power Amplifier (QFN)	XPI042-QT	12.0-16.0	21.0	+/-1.0	+25.0	+38.0	500 @ 5.0	3×3
Power Amplifier (QFN)	XPI043-QH	12.0-16.0	21.5	+/-1.0	+30.0	+41.0	700 @ 7.0	4×4
Power Amplifier	XPI057-BD	13.5-16.0	17.0	+/-1.0	+39.0	+48.0	3.7 A @ 7.5	DIE
Power Amplifier	XPI058-BD	14.5-16.0	27.0	+/-1.0	+36.0	+44.0	2.2 A @ 8.0	DIE
Power Amplifier	XPI072-BD	34.0-37.0	22.0	+/-2.0	+35.0 Psat	-	2.4 A @ 5.5	DIE
Power Amplifier	XPI073-BD	34.0-37.0	22.0	+/-2.0	+37.0 Psat	-	4.8 A @ 5.5	DIE

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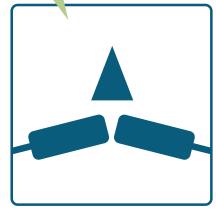


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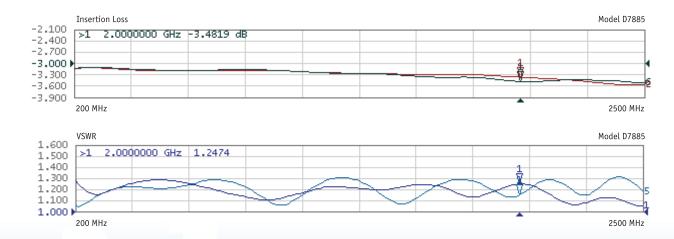
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COMBINERS

\*\*Multi-Section Power Dividers, first described by Seymour Cohn, employ a large number of floating, high value resistors, resulting in excessive high frequency roll-off and low unbalanced power capability.

\*\*Werlatone's, Patent Pending "Collapsed Cohn" design requires only one or two, low value, high power resistors to provide the same port-to-port isolation and higher unbalanced power protection, while eliminating high frequency roll-off.



#### www.werlatone.com

Model	Туре	Frequency	Power	Insertion Loss	VSWR	Isolation	Size
		(MHz)	(W CW)	(dB)		(dB)	(Inches)
D7885	2-Way	200-2500	200	0.65	1.40:1	15	7.7 x 1.6 x 1.1
D7823	2-Way	500-2500	200	0.4	1.35:1	15	4.7 x 2.0 x 0.8
D7630	2-Way	800-3000	200	0.4	1.35:1	15	3.7 x 1.9 x 0.87
D7539	4-Way	800-2800	200	0.6	1.35:1	17	5.5 x 4.1 x 1.1
D7695	4-Way	900-1300	100	0.4	1.30:1	20	4.0 x 3.3 x 0.8